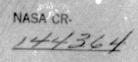
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DEVELOPMENTS IN CONVECTIVE HEAT TRANSFER MODELS FEATURING SEAMLESS AND SELECTED – DETAIL SURFACES, EMPLOYING ELECTROLESS PLATING

(NASA-CE-144364) DEVELOPMENTS IN CONVECTIVE	N75-29356
HEAT TRANSFER MCDELS FEATURING SEAMLESS AND	
SELECTED DETAIL SURFACES, EMPLOYING	
ELECTRCIESS FLATING (ITV Aerospace Corp.) 101 p HC \$5.25 CSCI 20E G3/34	Unclas
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BY C. J. STALMACH , Jr.	

30 June 1975

TECHNICAL REPORT 2-57110/5R-3227

Prepared under Contract No. NAS9-13692 by Vought Systems Division LTV Aerospace Corporation Dallas, Texas

For

National Aeronautics and Space Administration

FORWARD

This report covers the program conducted under contract No. NAS9-13692 with NASA, Lyndon B. Johnson Space Center. The contract time span was November 1973 to June 1975 during which time the contract was dormant for approximately six months (October 1974 to April 1975) awaiting availability of government furnished model under CCA No. 1.

The contract objective was to develop improved methods of fabricating heat transfer wind tunnel models. The program was divided into a Phase A, development of concepts, and Phase B, fabrication of an Orbiter model applying Phase A experience. Phase A experiments included evaluation of a plated slab model concept and feasibility study of plating controlled roughness on a model surface. Based on NASA technical priorities and cost estimates of Phase B options, a Change Order, CCA No. 1, was issued October 3, 1974 which directed the remaining funds to the selective plating of scaled heatshield tiles on an existing Orbiter model.

Dr. Winston D. Goodrich, NASA-JSC program technical monitor, provided valuable suggestions and encouragement which are greatly appreciated. Many other individuals provided assistance; particular recognition and thanks are given to:

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Mr. Thomas C. Pope, for computer studies of instrumentation concepts

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LIST OF SYMBOLS

A	Area
b	Thickness of metallic skin
erfc	Complementary error function, $\sqrt{\pi} \int_{\beta}^{\infty} e^{-\lambda^2} d\lambda$
C, Cp	Specific heat at constant pressure
h, H	Aerodynamic heat transfer coefficient
k, K	Thermal conductivity
M	Free-stream Mach number
P	Pressure
q, Q	Heat transfer rate
R	Radius, or free-stream Reynolds number
S	Surface Distance
T	Temperature
t	Time
β =	$\frac{h\sqrt{t}}{\sqrt{\rho CK}}$
ρ	Density
λ	Dummy variable of integration
u u	Micro-

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DEVELOPMENTS IN CONVECTIVE HEAT TRANSFER MODELS FEATURING SEAMLESS AND SELECTED - DETAIL SURFACES, EMPLOYING ELECTROLESS METALLIC PLATING

By C. J. Stalmach, Jr. Vought Systems Division LTV Aerospace Corporation Dallas, Texas

SUMMARY

Several model/instrument concepts employing electroless metallic skin were considered for improvement of surface condition, accuracy and cost of contoured-geometry convective heat transfer models. A plated semi-infinite slab approach was chosen for development and evaluation in a hypersonic wind tunnel. The plated slab model consists of an epoxy casting containing fine constantan wires accurately placed at specified surface locations. An electroless alloy is deposited on the plastic surface that provides a hard. uniformly thick, seamless skin. The chosen alloy forms a high-output thermocouple junction with each exposed constantan wire, providing means of determining heat transfer during tunnel testing of the model. A set of stringent model objectives were met except that maximum surface smoothness and maximum operating temperatures were demonstrated independently but not simultaneously. Plated epoxies with nominal 15 microinch RMS surface withstood approximately 350°F temperature and with nominal 60 microinch RMS surface withstood 550°F (which is approximately the limit for the epoxy material). The plated slab model demonstrated good data accuracy in the tunnel test. Further development effort is justified for electroless plated semi-infinite material and thin-skin calorimeter approaches.

A selective electroless plating procedure was used to deposit scaled heatshield tiles on the lower surface of a 0.0175-scale Orbiter model. Twenty-five percent of the tiles were randomly selected and plated to a height of 0.001-inch. The purpose is to assess heating effects of surface roughness simulating misalignment of tiles that may occur during manufacture of the spacecraft.

INTRODUCTION

During the aerothermodynamic development of the Space Shuttle Orbiter the need for improved methods of fabricating heat transfer models of contoured geometries was again apparent. Model/instrument demands were increased by the geometry, and high structural strength and resistance of the surface to particle damage were required by high Reynolds number hypersonic tests.

Problems with conventional machined thin-skin calorimeter models include the difficulty of instrumenting tight quarters such as leading edge radii and the inaccuracy of the measured heat transfer distribution in such areas caused by lateral heat conduction in the skin. Accessibility requirements for welding thermocouple wires to the skin inner surface implies high cost of machining and joints in the model surface. Local roughnesses from mechanical joints and attachment hardware influence the heating results, particularly at conditions near natural boundary layer transition.

Use of temperature-sensitive, phase-change paints applied to plastic models provides valuable data on heating distribution, however not without shortcomings. The optical recording of the melt-line progression causes this method to have inherent problems in providing quantitative data at all discrete model locations of interest over the surface of a contoured body. The paint layer also adds surface roughness that may influence the results. The surviability of the plastic models is often marginal to the temperature and particle environment of hypersonic wind tunnels.

This program evaluated promising new fabrication concepts of heat transfer models that employ an electroless deposition of a metallic alloy to the model surface. Electroless plating is a means of depositing metal through controlled autocatalytic chemical reduction. An electroless deposition of metal was discovered in 1844 by Wrentz, improvements (resulting in a patent) were accomplished by Roux in 1916, however the process was not practical until about 1946 when Brenner and Riddell developed a controllable autocatalytic reduction process (Refs. 1, 2, 3). Since electrical current is not involved in the deposition, the surface of non-conductors such as plastics may be plated by seeding the surface with a catalyst. The growth of the deposit originates from multitudinous point sources (catalytic centers) on the surface. On a properly prepared surface, the number of nuclei is so large that growth proceeds as a plane front parallel to the original surface. Thus electroless plating produces a plate of uniform thickness wherever the solution may reach, including blind holes and sharp corners that give problems in conventional electroplating. Most of the electroless nickel alloys contain phosphorous which results in a very hard plate comparable to chrome. Hardness and abrasion resistance can be increased further to about Rockwell C70 by heat treatment at 750°F. The nickel phosphorous alloy has very low thermal conductivity which can be used to great advantage in models that have high surface temperature gradients. Shipley Company, in its Niculoy 22, improved the ductility of the alloy while retaining hardness with the addition of one percent copper.

The inherent properties of electroless plating that are of particular importance to fabricating heat transfer models are: (1) uniform plate thickness regardless of the surface contour, (2) seamless coating over many materials including plastics or combinations of surface materials, (3) abrasion resistance, (4) low thermal conductivity and (5) automatic formation of thermocouple junctions when plated to surfaces equipped with thermocouple wires. An outstanding feature discovered during this study is that a high output, repeatable thermocouple junction results when the chosen electroless alloy (Niculoy 22) is plated to a single (constantan) wire. The one-wire junction greatly improves the accuracy and cost of instrumentation.

A Phase A effort studied several model/instrument fabrication ideas employing electroless plating. A plated, semi-infinite slab approach was chosen for laboratory and wind tunnel evaluations. In this method epoxy models are cast with constantan wires protruding at desired model locations. Two layers of electroless nickel totalling approximately 0.0015-inch thickness are applied. The ends of the wires are polished flush to the first layer surface so that the second layer provides a continuous skin over the surface. Such models provide accurate data in a hypersonic tunnel to maximum surface temperatures of approximately 550°F. Experimental evaluations of two other concepts and further refinement of the reported method are recommended.

Phase B effort began with application studies of Phase A results to current Orbiter test requirements. The chosen Phase B hardware product was to modify an existing Orbiter model to simulate the surface roughness resulting from heatshield tiles that may be misaligned in surface height during normal manufacturing and assembly practice. A selective electroless nickel plating procedure was used to precisely raise the randomly selected scaled tiles above the mean of the lower surface of a 0.0175-scale Orbiter model. This model is scheduled for test by NASA in the AF AEDC Tunnel F in the fall of 1975 where the same model was previously tested in a smooth surface configuration. The use of selective electroless plating to provide precise control of surface detail on wind tunnel models has significant application potential.

This report describes the model/instrument concepts studied, wind tunnel evaluations of one method and tables of the electroless plating procedures applied in this effort.

PROGRAM OBJECTIVES

New Model Methods

The objective for Phase A and part of Phase B was to develop techniques for fabricating aeroheating models that: (1) have a minimum of surface joints, (2) reproduce very closely the surface contours of the hardware, (3) have a smooth surface finish suitable for boundary layer transition studies, (4) are instrumented with thermocouple wires which can be predictably located, (5) possess hard surfaces that have good resistance to abrasion by particles normally encountered in hypersonic facilities, (6) have sufficient structural strength to withstand hypersonic flows at high dynamic pressures, (7) permit customizing the sensor sensitivity to the model location and the facility conditions, (8) allow instrument placement anywhere on the model surface, (9) are effective in measuring local heat transfer in areas of high temperature gradients, (10) can be fabricated in less time than conventional machining methods, and (11) can be fabricated at costs not to exceed conventional machining methods.

The technical characteristics (1-9) were demonstrated in varing degrees of success for the plated slab, model/instrument method evaluated. Detailed grading relative to the above list will be presented later. The item giving the most difficulty for the chosen approach was item (3). The surface smoothness objective was met, however with a reduction of temperature resistance of the plate bond to the substrate. Certain objectives are more sensitive to the choice of model/instrument concept. The troublesome objective may be better met by other methods to be discussed. Cost objectives (10-11) remain as expected benefits once the model techniques are fully developed. Test results indicate merits and potential of electroless plated model methods that justify further evaluation.

Selective Plating of Controlled Roughness

The objective of Change Order CCA No. 1 was to simulate the roughness of random misalignment of heatshield tiles that may exist on the lower surface of the Orbiter by selective electroless plating of tiles on an existing scaled model of the Orbiter.

This objective was met completely by plating the specified pattern and height on a 0.0175-scale stainless steel model. This successful application should encourage further uses of this method to control surface detail in aerothermodynamic models.

MODEL DEVELOPMENT PROGRAM

The development of improved methods of heat transfer modeling was begun with a review of past experiences in the literature. After the review a list was composed of promising concepts. A semi-infinite slab method employing an electroless nickel skin was chosen for laboratory development based on analytical, previous experience and cost considerations. After evaluating several fabrication procedures, sample models were made and evaluated in a hypersonic wind tunnel. Fabrication refinements after the tunnel test and cursory experiments with other concepts completed the development portion of the effort.

Trade Studies

Library Research. - Requests were issued to Defense Documentation Center and NASA Scientific and Technical Information Facility for computer literature search, including limited distribution references, from the period 1965 to the request date of September, 1973 for the following subjects:

> Electroless Plating of Plastics Casting of Wind Tunnel Models Heat Transfer Measurements

The results of the computer searches and private searches are presented in Appendix I, after screening for applicability. The bibliographies are not exhaustive but should be representative of the work published during this period that best applies to the subject effort.

No evidence was found in the literature of any previous attempts to use electroless plating in fabricating a heat transfer model (except for the author's preliminary work (Ref. 4)). Review of instrumentation developments was very helpful in both stimulating and culling design concepts for this program.

Model/Instrument Concepts. - Three instrumentation approaches that have the potential of meeting the program objectives are:

> Calorimeter Gardon Semi-Infinite Material

Example sketches of how these instrumentation approaches may be incorporated into a jointless heat transfer model are shown in Figure 1.

A method of measuring temperature with the electroless nickel skin at each point that it plates to a wire is shown for each of the concepts. The one-wire method contributes significantly to meeting the objectives, therefore one of the first laboratory experiments was to assess the thermocouple characteristics of the plate and various wire alloys. It was found that Shipley's electroless nickel Niculoy 22 plated to constantan wire provided an excellent thermocouple as shown in Figure 2. The Niculoy/constantan output is similar to the copper/constantan output which may be due to the one percent copper contained in the Niculoy 22 alloy. The thermcelectric characteristics of

Niculoy and its improved ductility and surface smoothness resulted in it being the primary plate material evaluated in the laboratory experiments.

The calorimeter approaches of Figure la include a free-standing, thinskin shell shown as Style A. The advantages of a shell plated by the electroless method compared to machining or electroforming include: (1) plating to one wire rather than welding of two wires, (2) jointless surface, (3) uniform plate thickness (inherent for electroless, difficult in electroplating and machining), (4) harder surface than heat treated stainless steel and (5) lower thermal conductivity. Several fabrication approaches appear feasible. For one example, a replica of the model could be cast with a low melting temperature alloy such as Cerrotru (a product of Cerro de Pasco Corporation). The casting would include the thermocouple wires and sting/model adapter. After plating, the replica would be melted and removed leaving a thin-skin, free-standing shell plated to the support and wires.

Style B provides sensitivity adjustment for long run facilities with a slug that is cast in an insulative substrate. A thin electroless nickel plate provides a jointless surface.

Style C would be more suitable for short run duration tunnels where a thin skin is desired for sensitivity and where high dynamic pressures require a solid backing except for local areas. The air gap reduces heat losses to the substrate at the sensor location for a short run time.

Style D is an attempt to thermally isolate a slug calorimeter from the substrate using an air gap.

Air spaces could be achieved by suitable placement of a low melting temperature material into the mold prior to puring the casting material. The disposable material would extend to the rear of the model to permit removal after the plating operation. Wax or Cerrotru wires are example materials and electroless plating was demonstrated for both. Hard "file-awax" was plated after first polishing the surface with boron nitride.

A Gardon gage (Ref. 5) is a steady state instrument that has been successfully used in heated blowdown tunnels (Ref. 6). The measurement required is the delta temperature from the center of a thin disc to its outer edge. The disc edge is cooled by a heat sink. Figure 1b shows possible ways to use this instrument with electroless nickel to form an instrumented, seamless model for use in long run duration tunnels.

Style A could make use of a machined steel model in which short constantan tubes are placed. The sleeve would contain a small constantan wire cast into its center, using a material such as Cerrotru. After plating, the Cerrotru would be melted and drained. The model could be cast with Gardon gages for Styles A, B, and C. Style C reduces the complexity of melting and removing materials, however the substrate under the disc needs to be addressed for effects on sensor accuracy.

Two classes of semi-infinite material gages incorporating electroless plating are shown in Figure 1c. The plated slab of Style A is similar to the cast models used for the phase-change paint method except that for the plated slab the surface temperature is measured with thermocouple wires that are joined to a thin metal skin during deposition of the skin.

Variations in material property have been experienced when fillers are used in epoxy castings (Ref. 7, for example) whereas the thermal properties are known and repeatable for thermocouple wire. The wire gage concepts shown as Styles B and C attempt to either isolate a wire from the substrate (Style B) or use a substrate that has thermal properties similar to the wire. The wire gages measure heat transfer using the surface thermocouple output and the wire material properties. The material in Style C may be cast or machined steel. For a steel model, the wire would have a thin electrically insulative coat. The electroless nickel would form the thermocouple junction and provide a seamless fourface. Style C employing a steel model should give results similar to the coaxial gage (Ref. 8) and has the advantages of requiring only one thermocouple wire per junction and exhibiting a continuous surface.

Analytical Heat Flow Study. - An analytical program was conducted to assess the effects of the geometric and thermal property variations on the design and accuracy of the various model/instrument concepts. A twodimensional computer routine was programmed (Appendix II) and representative results are given in Figures 3 through 8. The input heating condition shown in these figures represents a flow condition in the NASA Ames 3-1/2 Foot Hypersonic Wind Tunnel. The one inch diameter hemisphere represents the model size chosen for the Phase A test. Properties of the candidate materials are given in Table I. Some property values were assumed based on literature values for similar materials.

Effects of an air gap around a wire is indicated in Figure 3. The air gap locally increases the plate temperature which increases the temperature of the plate over the wire. The wire was not isolated by the gap because of the heat conduction in the plate. (Perfect isolation of the wire would approach the case shown for the infinite wire diameter). For these initial computer runs, the electroless plate properties were not known and therefore a pure nickel plate, 0.0015-inch thick, was assumed. As shown in Table I, the conductivity of nickel is over an order of magnitude preater than electroless nickel. Although electroless nickel would provide better isolation than indicated in Figure 3, a high degree of isolation with practical skin thickness does not appear likely. The results of Figure 3 and fabrication complexity eliminated all design concepts involving air gaps early in the study.

After the runs of Figure 3, the computer routine was refined to include calculation of the temperature at the interface between the plate and wire (or substrate if a wire was not present). Niculoy 22 had been chosen as the plate material and its properties were incorporated in the routine.

Figures 4 and 5 show effects of wire and plate dimensions for low and moderate conductivity substrate materials. The low conductivity of Isochem's Novimide results in a steep temperature rise, more than desired for application in a heated blowdown tunnel (Figure 4). The high thermal expansion of this material also often caused failures in the plate during laboratory evaluations and therefore Novimide 700/55 was not evaluated further. The Novimide material could prove advantageous in areas of low heat transfer and short run duration tunnels.

The results shown in Figure 5 for Emerson Cuming's Stycast 2762FT indicate that such a material coupled with practical electroless plate thickness and wire diameter will provide reasonable temperature histories for a plated slab gage in the designated NASA Ames facility. The effects of a 0.001-inch plate and a 0.003-inch diameter wire are noted as being small and essentially constant after the time interval required to insert the model into the test stream (~1/2 second). Larger wire diameters around 0.032-inch may be used as semi-infinite wire gage if the Niculoy plate is sufficiently thin as indicated for the 0.00025-inch case in Figure 5.

Figure 6 shows calculated temperature distributions in the materials after 2.5-seconds of heating. It is observed that the temperature along the axis of the 0.003-inch constantan wire that is cast within a Stycast substrate and topped with a 0.001-inch Niculoy plate is similar to the temperature distribution of the pure Stycast substrate.

Figures 7 and 8 were prepared to examine the possible use of Niculoy plate as a thin-skin calorimeter (Figure 1a). As discussed in Reference 8, a calorimeter gage will exhibit a straight line for the relation of Figure 8 up to the time that conduction errors become significant. The 0.003-inch diameter thermocouple wire had a negligible effect on the calorimeter gages. A 0.010-inch thick plate backed by Novimide (a very low conductivity substrate) indicates conduction errors after about a half second of heating. Figure 8 indicates that a thin skin calorimeter supported by a low conductivity substrate may be employed in a short run duration tunnel such as a hotshot type, however a "free-standing" shell (i.e. a thin shell held by minimum contact with support structure) would be more suitable for heated blowdown facilities. 2

Grading of Concepts. - Funding considerations necessitated an early judgement as to which one of the model/instrument concepts of Figure 1 would best demonstrate the program objectives in a hypersonic wind tunnel. The above discussed library and computer studies, predicted availability of required materials and fabrication complexities were used to help anticipate relative grades for the model/instrument concepts. Table II presents the grading results and indicates that the plated slab gage of Figure 1c had the highest anticipated relative grade (8.8 out of 10). Laboratory work from this point concentrated on developing and testing this model/ instrument method.

The anticipated grade for the plated slab concept was lowered as shown in Table II after completion of the experiments because the substratematerial/plating-procedure combination did not fully meet the projected results. Table II will be reviewed further when discussing recommendations.

Technique Development

Initial Material/Technique Evaluations. - After review of vendor information and initial laboratory evaluations, the following materials were chosen and proved to be adequate to meet the described needs of this study:

- (1) Molds Requires a castable material that faithfully reproduces the surface of the master or sub-master models. The mold must maintain diminsional accuracy while high temperature plastics are being cured in the mold and must permit release of the cured plastic replica. Silastic J by Dow Corning was chosen.
- (2) Sub-master model Requires a castable material that faithfully reproduces the surface of the master model and that can be readily drilled to locate each thermocouple station. (Sub-master is not required if surface drilling is permitted on master model or pattern). Epocast 11B, an iron-filled room temperature epoxy by Furane Plastics was chosen.
- (3) Model Skin Requires a smooth, hard, ductile and uniform plate that is suited for plating of plastics and that forms a reliable thermocouple junction with a standard wire. Niculoy 22 electroless alloy by Shipley was chosen. Desired improvements would be a plating solution that operates at a lower temperature and exhibits lower plating stress than the chosen alloy.
- (4) One-wire thermocouple Requires a sensitive, repeatable output from a standard thermocouple wire joined to an electroless plate. Niculoy 22/constantan junction proved to be quite adequate (Figure 2).

Sensitize Smooth Plastics Nickel Plate (SSPN). - Table III lists three representative plating procedures used in the initial laboratory evaluation of the candidate substrate materials of Table I. Because of the objective of a smooth surface, chemical etching of the plastic surface was only briefly evaluated in these initial experiments. A concentrated effort was made to obtain sufficient plate adherence to a smooth plastic surface through use of cleaners, ultrasonic agitation and wetting agents. Light sanding of the surface with wet 400 to 600 grit paper was added to the procedure to break the high gloss of the castings. The polishing improved adherence while retaining a sufficiently smooth surface. Several variations of the procedures were evaluated including ε , room temperature bath suggested by Feldstein (Ref. 9) and baking of the deposited palladium catalyst prior to nickel plating.

Evaluation of the casting and plating results for the SSPN procedure brought the disappointing results shown in Table IV. The three hydraulicsetting refractories evaluated exhibited surfaces considered too rough for this study. LO-XA125 by Duramics is the most promising of those evaluated and should be reconsidered if extreme temperature service is required. Large volume castings with hard surface molds produced an acceptable surface;

however small volume castings in RTV molds did not. The plating adherence to the refractories was good.

The Novimide 700/55 material plated the best of the plastics evaluated in the SSPN procedure, followed by Stycast 2762FT. None, however, had adequate adherence to survive the heating in a hypersonic facility.

The SSPN development was terminated and emphasis directed to an innovative aluminum transfer method discovered during this study.

Aluminum Transfer Zinc Aid Nickel Plate (ATZN). - Significantly improved plating bonds to epoxy substrates were achieved and with a very smooth plated surface by use of an aluminum transfer casting method followed by a Zinc Aid and nickel plating procedure summarized as follows:

- (1) Aluminize the RTV mold surface by lightly rubbing "leafy" aluminum powder into the surface with cotton and blowing away all excess not adhered to the mold
- (2) Insert the thermocouple wires into the holes cast in the mold
- (3) Pour the epoxy (or other castable plastic) into the mold
- (4) Aluminum layer is bonded to the epoxy casting while curing
- (5) Remove the casting from mold, aluminum film is transferred to the casting
- (6) Post cure casting
- (7) Clean and condition surface for plating
- (8) Plate surface and exposed wires to 2/3 of plate thickness
- (9) Clip and polish wires to plated surface
- (10) Reactivate plate (Shipley 1424)
- (11) Plate to final thickness

Smooth nickel and copper electroless platings were achieved with all of the epoxy materials evaluated. Oven tests demonstrated however that the temperature resistance of the plate-to-epoxy bond is sensitive to the material composition and plating procedure. The material should have a coefficient of thermal expansion near that of the plate material. The cast material should develop a high bonding strength to the inner surface of the aluminum powder without wetting the outer aluminum surface.

Table V shows the material samples that were cast, plated and evaluated in an oven. Stycast 3070 material proved best in the "as received" mixture and thus was used as the base material with which optimization with additional fillers was attempted. Optimization of the plating procedure was also conducted and resulted in the procedure for depositing the first layer of electroless nickel shown in Table VI. The best material/plating combination of those evaluated for the ATZN process is indicated in Tables V and VI. This optimum combination will normally survive an oven test of 350 F. Most other combinations would exhibit diamond-pattern wrinkles in the plate when cooled from 350°F because of inadequate bonding and high compressive stress in the plate. Additional improvements in the basic metallic film transfer concept is certainly possible.

Personnel within the local (Dallas) and home offices of Shipley Company were interested in assisting in this program and were supplied sample castings for their independent evaluation. Their study suggested an etch process that will be dicussed next.

Etch, Catalyst, Accelerator, Nickel Plate (ECAN). - The mechanical strength of the plate attachment to a plastic is greatly increased if the surface is slightly porous to permit the plate to mechanically latch into these pores. Certain materials, such as the ABS plastics used extensively for plated plastics in industry, have a constituent that is readily removed by etching. The contorted, tiny tunnels become plated in the electroless process and securely lock the plate to the surface. Unfortunately the ABS plastics do not have the temperature resistance required in this study. Most epoxies do not etch readily and generally develop a rough, pitted or grainy surface.

It was discovered at Shipley that an etched surface of Stycast 3070 castings was more suitable for plating than normally considered for epoxies, possibly explained by the calcium carbonate powder filler. Calcium carbonate reached by an acid will be dissolved leaving random, fine-grain voids in the epoxy surface. Oven evaluation demonstrated that the Phase A ECAN process of Table VI would permit plated Stycast 3070 to withstand temperatures up to 550°F. This exceeds the quoted limit temperature for the epoxy material. The surface was not nearly as smooth as the ATZN process, however.

Wind tunnel test models were fabricated and evaluated for both ATZN and ECAN processes as will be discussed. After the tunnel test an optimization study was conducted to improve the surface smoothness of the ECAN process. This resulted in the Phase B ECAN plating procedure of Table VI and an optimum material of those evaluated in Table VII. The surface condition is very sensitive to the temperature, dwell time, and degree of nitrogen agitation of the Shipley PM-930 solution. The etch process partially exposes the fine glass fibers in the optimum material which provides additional "roots" for the plating. The Phase B ECAN process produced improved surface smoothness compared to Phase A ECAN but the surface is not as smooth as the ATZN process.

Nickel Transfer to Epoxy Cast (NTEC). - Another approach to obtain a smooth plated surface on an epoxy substrate is to first plate the skin and then cast the epoxy into the shell. The bond strength of an epoxy cured to a plate may be greater than the adherence obtained by plating to a smooth surface. Futhermore, the bond would not be subjected to the plating stresses of the plate. The approach was not fully exploited, however some effort was given to the following ideas with promising results. The primary problem was casting a Cerrotru surface free of air bubbles.

- (1) Internal plating Cast a female mold with a disposable material that has a smooth surface and that plates well, such as Cerrotru. Insert the thermocouple wires into the cast holes. Plate internal surface with electroless nickel to about half to two-thirds the final plate thickness. Pour epoxy into model cavity and cure. Post cure the epoxy to a higher temperature which will also melt away the Cerrotru mold. Polish the thermocouple wires to the surface. Chemically clean and activate the surface. Plate skin to final thickness.
- (2) External plating Cast a male replica including the thermocouple wires with a disposable material that has a smooth surface and that plates well, such as Cerrotru. Plate the surface to about two-thirds the final plate thickness. Polish the wires to the surface, activate and plate the surface to the final plate thickness. Cast around the outer surface of the model with a disposable material such as plaster of Paris. Melt and drain the Cerrotru, chemically clean the inner surface and pour epoxy into the cavity. After final curing of the epoxy, the plaster becomes brittle from the oven temperatures and can be broken away from the plate.

<u>Free-Standing Thin-Skin Nickel Plate (FTSN).</u> - A brief laboratory evaluation was given to the free-standing, thin-skin calorimeter model as depicted by Style A of Figure 1a. This concept is given a high anticipated rating in Table II. The generation of the uniform thickness shell would be similar to that discussed for the NTEC process except that a thicker shell is required (0.005 to 0.020-inch depending on facility conditions) and the shell would be supported at minimum number of contact points. The support could be joined to the skin during the plating process or later bonded to the skin for maximum isolation.

A feasibility experiment was conducted by plating Niculoy 22 to a thickness of 0.012-inch on a contoured piece of Cerrotru material. The Cerrotru was melted and drained and the inner plate surface was cleaned with caustic soda. The resultant free-standing contoured shell is strong, hard, uniform thickness, smooth and continuous.

The primary difficulty experienced with this process was casting the Cerrotru free of surface air bubbles. Cerrotru casting was attempted in the Silastic molds used for the epoxy castings and the hot metal appeared to cause an out-gassing in the RTV material.

EVALUATION OF PLATED SLAB MODEL

Results of the development program were evaluated continuously and had a daily effect on the course of the development. The major evaluation of the semi-infinite slab method, however, was accomplished by subjecting sample instrumented and non-instrumented models to M = 7.32 tunnel flow in the NASA Ames 3-1/2 Foot Hypersonic Wind Tunnel.

Wind Tunnel Test Program

<u>Models.</u> - The two model geometries of Figure 9 were tested in the wind tunnel. The hemisphere cylinder provides ease of comparison to existing data and theory. The flat face cylinder geometry provides a good assessment of the instrumentation accuracy in areas of high surface temperature gradients and assessment of the particle resistance of the plate. A master thinskin model was machined for each shape out of 17-PH stainless steel. The steel models served as mold masters from which the epoxy replicas were derived. The steel masters were instrumented and tested simultaneously with the plastic models to help gauge the data effectiveness of the plastic models.

Table VIII lists and briefly defines the Phase A test models. Figure 10 shows the models prior to shipment to the test facility.

<u>Test Procedure.</u> = Two master models and eight plastic models were tested simultaneously by using the mount shown in Figures 10 and 11. The shadowgraph of Figure 12 and oil flow patterns on the centerbody confirmed that the model assembly was in fully started flow. Eight runs were conducted at M = 7.32 at a nominal total temperature of 1500° R. The test began at low Reynolds number (0.8 x 10⁶ per foot) and progressed to 4.0 x 10⁶ per foot which exceeded the target value for the evaluation of 3.6 x 10⁶ per foot.

The models were inserted into the flow stream and then retracted after about two seconds. Digital temperature data from the models were recorded on magnetic tape. Notes and photographs were made of a visual inspection of the models after each run (Table IX). Models whose plating wrinkled or otherwise failed were replaced during the model inspection.

<u>Data Reduction</u>. - The data reduction procedure for the plated semiinfinite slab model is rather simple if sphere data are obtained and used to determine the thermal property of the substrate-plate-wire combination. The data reduction made use of the semi-infinite slab solution as expressed by Jones and Hunt (Ref. 10):

$$\overline{T} = 1 - e^{\beta^{2}} \operatorname{erfc}_{\beta}$$

$$\overline{T} = \frac{T_{w} - T_{i}}{T_{aw} - T_{i}}$$

$$\beta = \frac{h\sqrt{t}}{\sqrt{oCK}}$$

For simplicity, assume $T_{aw} = T_{m}$. The effects of this assumption and the effects of the plate and thermocouple wire on the in-depth heating of the substrate are lumped into the material property term $\sqrt{\rho_{CK}}$ which is determined from a plastic hemisphere model for which the heat film coefficient, h, is known from measurements with the master model. This effective $\sqrt{\rho_{CK}}$ term is then applied to determine h for the flat face cylinder test model. The flat face model was fabricated in the same manner and encountered a similar range of heating as the hemisphere model.

The step-by-step procedure followed:

- (1) Establish h for a sphere in the test conditions using the master sphere model (Table X, Average values shown in Figure 13)
- (2) Determine temperature-time data for the plastic models
- (3) Plot temperature-time data (See Figures 14 and 15 for examples)
- (4) Determine the effective time zero (t_i) and initial wall temperature (T_{ui}) (Figures 14 and 15)
- (5) Calculate T at selected times
- (6) Determine β from \overline{T} (Ref. 10)
- (7) For the plastic sphere models determine $\sqrt{\rho CK}$ at each station and time by using the measured values of h obtained with the master sphere model
- (8) Plot $\sqrt{\rho CK}$ as a function of \sqrt{t} for all model positions, all times and all runs for a given sphere model (Figure 16)
- (9) Calculate h for the flat face plastic models using the faired values of \sqrt{OCK} from a sphere model composed of the same materials

The relation of $\sqrt{\rho_{CK}}$ to \sqrt{t} was suggested by Reference 7. An attempt was made to more closely define the $\sqrt{\rho_{CK}}$ term by relating it to a second term. It appears that the term β can be related to $\sqrt{\rho_{CK}}$ for selected times as is indicated in Figure 17. The Figure 17 faired values are within ±10% of the Figure 16 fairings. The Figure 16 fairings were used in the data reduction.

Data reduction of the flow conditions and heat transfer rates for the thin-skin master models were provided by NASA-Ames. Millivolt-time digital data were also provided for the plastic model thermocouples.

<u>Tunnel Data.</u> - Evaluation data from the tunnel test began with notes on model survivability as shown in Table IX. Thermocouple data from selected ECAN and ATZN models were reduced and the results are given in Tables X and XI and Figure 18. The averaged stagnation values for the hemisphere and flat face master models were in excellent agreement with theory as noted in Table XI. The plastic model data compare well with the master flat face model data and expected distribution as shown in Figure 18. The surface of the ECAN Model CC was rougher than the ATZN Models G and I. The ATZN models generally failed after one or two runs, however. The sensitivity of the fairing of $\sqrt{\rho CK}$ on the comparison was examined. Calculations of h for Model CC were made for the lower fairing of Figure 16. The results are presented in Table XI and are 8% lower.

The increasing value for / OCK as time approaches zero in Figure 16 is attributed to the influence of the wire and plate (review also Figure 5). The indicated influence is independent of the local geometry. Checks were made to see if using the experimentally determined / OCK (that combined the wire, plate and substrate properties) resulted in any time dependency in the calculated values of the film coefficient, h. The coefficient was calculated at each model station for several selected times between the interval 0.1 to 1.75 seconds. The calculations were found to agree well with the average and did not indicate a time dependency. Further proof of the validity of the data procedure is given through the good agreement of the computer prediction of temperature to the measured temperature shown in Figure 14. The average experimental value of \sqrt{OCK} at time one second was input in the routine for the substrate property. The routine assumes the value to be constant. The average experimental value of h was also a constant computer input. The effects of the wire and plate on the thermocouple temperature are taken into account in the routine through thermal balance of the finite elements of the various materials.

The slope of the material property $\sqrt{\rho CK}$ with time after about one second (where the wire and plate effects become negligible) are comparable with results for a similar substrate material without a plate or wire (Ref. 7). The reduction of the substrate value of $\sqrt{\rho CK}$ can explain why the predicted temperature in Figure 14 falls below the measured for times greater than one second.

Figures 14 and 15 indicate the agreement in temperature measurements between the new Niculoy/constantan and standard copper/constantan thermocouples. Stations 002 and 012 are both located thirty degrees from stagnation but along different rays. The agreement was particularly good for the smoother models such as Model BB of Figure 15 and the ATZN models.

Evaluation Results

The combined laboratory and tunnel results for the plated slab method are compared to the technical program objectives. The plastic modeling research did not extend through a phase B model and therefore the cost objectives (10 and 11) remain as expected benefits.

<u>Compliance with Objectives</u>. - Combined laboratory and tunnel results demonstrate that the plated slab concept fully meets the following program objectives:

- (1) No surface joints
- (2) Good surface detail reproduction
- (4) Accurate instrument location
- (6) Sufficient strength
- (8) Instrument placement anywhere
- (9) Effective in areas of high thermal gradients

The plated slab possesses a very hard surface that is resistant to particle damage and therefore meets in principal the model objective number (5). However, particle damage did occur in the pebble-bed heater facility used in this evaluation. Figure 19 shows post-test magnified views of the flat face of ECAN Model CC compared to the heat treated (190,000 psi) flat face of the master Model A. Both models were subjected to all eight runs in the hypersonic tunnel and both were still providing data without any loss of instrumentation. Figure 19 and Table IX indicate particle damage resistance of the ECAN models is comparable to a heat treated stainless steel model. The softer copper coating of the ATZC process had more severe particle damage as noted in Table IX.

The customization of sensor sensitivity, objective (7), was restricted to materials that provided good plate-to-substrate bond strength. The best materials for bond strength fortunately also provided good data sensitivity. Areas of low heating impose less demand on the plate bond and therefore less restriction on the choice of materials for increased sensitivity (if required).

Data accuracy (not listed as a specific objective) obviously must be adequate if the plated slab concept is to be practiced. The tunnel results of this preliminary test proved that this model method will provide accurate data. Further improvements in accuracy can be expected as material, process and data reduction improvements are made. Discovery of the Niculoy/ constantan thermocouple greatly enhances the data accuracy and overall attractiveness of this modeling approach.

Problem Areas. - A smooth surface finish (objective (3)) could be provided, however, for marginal operating temperatures. The principal problem area was finding an acceptable compromise between surface smoothness, plate hardness and maximum operating temperature of the model.

Figure 20 is a photograph comparing the surface smoothness of master, ATZN and ECAN models. The smoothness of ATZN models are considered addquate for applications involving natural hypersonic boundary layer transition. Figure 21 shows magnified views of the ATZN surfaces compared to the master and the aluminum transfer film. Note that polishing marks of the master are reproduced in the plated plastic models which attests to the faithful reproduction of surface detail of this process. The thicker plate of Model M shows some pores caused by hydrogen bubbles forming on the surface during plating. This problem can be reduced by better control of the nitrogen agitation in the plating scluttion. The ATZN process in the current state of development is restricted to maximum temperatures of about 300 to 350°F. This maximum is based on both oven and tunnel evaluations. One ATZN model, Model F, failed after run four and experiencing a stagnation temperature exceeding 500°F (Table IX). The ATZN models generally fail in the cool-down process when the compressive stress in the plate overcomes the bond strength of the plate. The compressive stress results from the deposition process and from the difference in coefficient of thermal expansion of the plate and substrate.

An aluminum transfer method that meets both the temperature and surface smoothness requirements is ATZC. The difference of ATZC with ATZN is that an electroless copper (Shipley CP-74) is deposited rather than nickel. The CP-74 copper alloy is harder than pure copper and plates smoothly, although not as glossy as Niculoy 22. Table IX shows that Model V with the ATZC process survived all eight runs at stagnation temperatures exceeding 650° F without a temperature induced failure. The bond strength of the electroless copper is not considered to be higher than electroless nickel, therefore the lack of wrinkling is assumed to mean lower plating and thermal expansion stresses exist at the interface. Nickel coatings over the copper, ATZCN, failed whereas ATZC did not. The ATZC models were not instrumented; however no problems in obtaining data with the ATZC process are expected. Valid one-wire/plate thermocouple of copper/constantan should be possible. The ATZC method lacks particle resistance.

The surface finish of ECAN models are shown in Figures 20 and 22. Model CC represents the roughness of the Phase A ECAN models, and Model FFF represents the improved surface finish obtained in a Phase B optimization study conducted after the tunnel test. Table IX shows the ECAN models generally survived all eight runs at stagnation temperatures exceeding 650°F. Oven tests (where the models were heat soaked and cooled to progressively higher temperatures) generally caused local plate blistering in ECAN models when cooling from 550°F. The manufacturer's rating of Stycast 3070 is 500°F. Therefore, the ECAN demonstrated operating temperatures exceeding the plastic substrate rated temperature.

Models AA and CC provided valid heating data for the model geometries of this study in spite of the undesirable roughness. The improved surface finish of Phase B ECAN may prove adequate for many model applications, however further improvements should be sought.

APPLICATIONS STUDIES

The Phase A development results indicate applications and modeling concepts that justify further effort. Some of the recommended effort may have progressed within a Phase B of this contract except that a reassessment of priorities directed the remaining funds to the selective plating effort to be described.

Orbiter Model Requirements in Tunnel B

Phase B was begun with the intent of fabricating a 0.0175-scale model of the Orbiter with the improved ECAN process and test in the AF-AEDC Tunnel B. The Phase A tests in the NASA-Ames facility were conducted at heating conditions exceeding Tunnel B at its maximum Reynolds number. The model insertion mechanism is not as rapid in Tunnel B as is possible in the NASA-Ames 3-1/2 Foot Hypersonic Tunnel. Figure 23 shows the computer prediction of maximum temperatures that are expected for Orbiter and hemisphere models during the nominal five to seven second insertion time of Tunnel B. The shown extrapolations were made to conserve computer time. Considering the temperature predictions, Phase A results, and the lower particle contamination of Tunnel B, it appears Phase B ECAN models could be tested successfully in Tunnel B. The "durability" factor of safety for the models would be essentially one, however, unless: (1) the operating temperature of the plated slab model is increased through improvements. (2) the insertion time of the facility is decreased, or (3) the test is conducted in the Mach 6 capability of the facility. If the model insertion time in Tunnel B could be reduced to the nominal two seconds of the Ames facility then the ECAN models could be used with confidence of survival in Tunnel B and the smooth-surface ATZN models would have a fair probability of survival.

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Recommended Efforts

Based on the difficulty in finding a substrate-plating combination for the plated slab method that meets both the smoothness and temperature criteria, the "grade" in Table II was reduced for the plated slab approach. Further material and process studies could raise this grade and should be conducted because of the attractiveness of this method if the material problem is solved.

Review of Table II and Figure 1 indicates that the semi-infinite wire concept Style C and calorimeter concept Style A currently have the highest predicted ratings. Laboratory and tunnel evaluations of both are recommended.

The wire gage would be easily evaluated with an existing model machined from 17-4PH stainless steel or similar material. Instrumentation holes would be filled with a length of constantan wire that has a coating of electrical insulator. The surface would be plated with Niculoy 22 to provide a smooth, jointless surface and establish Niculoy/constantan thermocouples at each sensor location. The material property term $\sqrt{\rho CK}$ of constantan differs from 17-4 stainless steel by only one percent (Table I) which should result in good accuracies. This approach is not suitable for areas of high thermal gradients where the material conduction would quickly distort the surface heating distribution.

The free-standing thin-skin calorimeter (FTSN) concept requires more laboratory development. The electroless plated thin-skin heat transfer model has several advantages over machined or electroformed models that make it worthy of development. The concept also has application to dynamic stability testing where low model inertia and freedom from energy absorbing structural joints are important. A successful material-technique optimization for the FTSN process would also permit fabrication and evaluation of the NTEC process that could conceivably help the plated slab method pass all of the objectives.

SELECTIVE PLATING HEATSHIELD TILE ROUGHNESS

The feasibility of electroless nickel providing a controlled surface roughness on wind tunnel models was demonstrated during Phase A. This process promised an accurate assessment of heatshield heating on the Orbiter as affected by misalignment of tiles resulting from manufacturing. This assessment is important to current NASA project and therefore, the remaining contract effort was devoted to this task.

Specifications

The specifications for simulating misaligned heatshield tiles on the lower surface of the Orbiter were:

- Tile Pattern The herringbone tile pattern planned for the centerline portion (as defined in Rockwell drawing VL70-399043) will be used over the total area of interest
- (2) Tile Area of interest Begin tile pattern 2% length aft of nose, covering the lower orbiter area up to the tangent line of the chines and wing leading edge, extending rearward to 80% length of the model
- (3) Selection of Tiles to be Raised Random selection of tiles to provide 25% of raised tiles in the tile area of interest. The plated tile pattern will be symmetrical about the longitudinal centerline (instrumentation is located only on one side of centerline)
- (4) Tile Size All selected tiles will be plated to within 0.0009 to 0.001 inch height. The tiles are 0.105 inch square for the 0.0175-scale model

Technique Development

A positive-resist method of selective electroless nickel plating was chosen. Development tasks included a negative of the plating pattern and customization of the selective plating method for the material, geometry and specifications of this effort.

A negative was generated by first accurately drawing all of the lower Orbiter tiles existing on one side of centerline to 0.04167-scale with a Gerber computer driven drafting machine. A table of random numbers (Ref. 13) was used to designate which 25% of the tiles would be raised. The tiles and the selection are shown in Figure 24. The selected tiles were covered with 0.250-inch flat black tape on the drawing and then photographic processes were employed to provide a 0.0175-scale negative of the plating pattern with symmetry about the longitudinal centerline. The basic steps of the selective plating process are:

- (1) Clean surface
- (2) Apply resist
- (3) Expose and develop resist
- (4) Activate exposed surface
- (5) Electroless plate exposed surface
- (6) Remove resist

The process used for the subject model is given in Table XII. The nickel strike improved adhesion to the polished stainless surface. Two coats of resist were necessary for it to endure the activation and relatively long plating time. A vacuum bagging technique was used to tightly hold the negative over the model surface during resist exposure. The model is shown in Figure 25 with the exposed and baked resist prior to the activation and plating steps.

Model Results

The plating of simulated heatshield tile roughness on a scaled model was successfully accomplished. Figure 26 is a photograph of the completed model. This existing model had a welded nose section and weld fills. Weld heat-lines became vivid during the mild etching of the activation process as shown; however, they did not cause any surface roughness. The plated pattern duplicates the negative with good fidelity. The plated height is within the requested tolerance; the plate surface is bright and the tiles are well adhered.

NASA has scheduled a test in the AF AEDC Tunnel F where this same model was previously tested in a smooth-surface condition.

This demonstration of controlled roughness suggests application of the technique to provide special model surface details in other aerothermodynamic requirements.

CONCLUSIONS AND RECOMMENDATIONS

- 1. A plated slab concept demonstrated the technical model objectives in varying degrees of success. Objectives such as a jointless surface and accurate placement of instruments were readily achieved. Good surface smoothness and model operating temperatures to the limits of the substrate material were demonstrated individually but not simultaneously.
- 2. The plated slab concept may be applied to hypersonic wind tunnel models if the maximum, momentary surface temperature is restricted to approximately 500°F for the ECAN and 300°F for the ATZN processes.
- 3. Experimental results indicate that further development work is required and justified for two modeling methods employing electroless nickel: (1) semi-infinite material and (2) free-standing thin-skin calorimeter
- 4. Controlled surface roughness was successfully accomplished on a scaled wind tunnel model using a selective electroless plating method. Selective electroless plating is an effective method for providing special surface details on wind tunnel models.
- 5. This research resulted in four innovations considered as new technology items: (1) a plated slab model method of measuring convective heat transfer. This method is a new approach for obtaining highly instrumented, seamless-surface models regardless of external geometry, (2) a one-wire Niculoy/constantan thermocouple that is formed during electroless plating of the model surface. This instrumentation improves accuracy and cost and makes practical the plated slab model concept, (3) an aluminum transfer procedure whereby a thin layer of aluminum powder is bonded to the plastic surface during the casting process. The film is readily plated with electroless nickel or copper to excellent surface brightness and with temperature resistance up to 350°F for nickel and 550°F for copper coating and (4) selective electroless plating of scaled surface detail on aerothermodynamic models. The use of photo resist and selective electroless plating (or etching) to control surface roughness on wind tunnel models is considered a new application of an existing technology.

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Material (Trademark & No.)	Thermal Conductivity X 10 ^l (Cal)(cm)/(sec)(cm ²)(°C)	Specific Gravity	Specific Heat Cal/gm °C	Maximum Surface Temperature ^o C	Thermal Expansion Coef.x10 6/°C	Tensile Strength PSI	Flexural Strength PSI	Compressive Strength PSI	Shrinkage Linear, 5
2762 FT	32.0	2.1	.2	300	38	a dina series Provinsi series	18,500		
Stycast 3070				260	20	9,000	16,000	12,000	
1095	4.48	. 80		260	40		4,200		NIL
2850 KT	103.3	2.8		200	29		16,000		
Eccobond Paste 99	40.3			230	32				
Solder 58C	241.			260	32		9,700		and the
Novimide 700755	5.0	1.94		540	64	10,300		18,000	.05
LO-XA 125	40.0	1.80		1260	1.20			4,000	.00
Thermo-Sil 120	14.8	1.88		1650	.81			5,000	.10
Kaolite 2200	5.68	.90		1200				700	.3
Air (Standard Atmosphere at Rest)	•57	.00123	.24						
Quartz	34.0	2.2	.18	1100	.56				
Wax (Nominal)	6.0	•9	.69	120					
Electroless Nickel (Literature)	105 to 135	7.85		890	13.				
(RCA)				1240					
(Niculoy 22)	135*	8.20	.13*	1000	13.5				
Nickel (200)	1819 to 1600	8.89	.13	1450	15.3 to 13.5	48,000		la parte de la composición de la compos La composición de la c	
Stainless S. (17-4PH) 430	7.78	.13	1400	10.8	145,000			$f_{i,j} = e_{i,j} f_{i,j} e_{i,j}$
Chromel	460	8.73	.107	1430	13.1	95,000			
Constantan	506	8.92	.094	1220	14.9	80,000			

TABLE I PROPERTIES OF MATERIALS CONSIDERED FOR MODEL AND INSTRUMENTATION

* Measurement not available; value shown assumed for computer program

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TABLE II GRADING OF MODEL/INSTRUMENT CONCEPTS

EMPLOYING JOINTLESS ELECTROLESS NICKEL SURFACE

	PGRM			ORIME			GARI			SEM	I-INFI CO	NITE NCEPT		IAL
	OBJ. NO.	A	В	С	D	A CAST	A MACH	В	Ċ	A* ATZN	A* ECAN	В	C CAST	C MACH
MODEL/INSTRUMENT FABRICATION Model Fabrication Instrument Fabrication Availability of Suitable Materials Reproduction of Surface Detail Ease of Instrument Placement	2 8	7.8	6.6	6.4	5.6	5.6	7.6	5.0	6,0	8.4	8.4	6.2	6.8	8.4
ELECTROLESS PLATING (To Required Thickness) Lack of Joints Lack of Mold Lines, Localized Roughness Overall Surface Smoothness Process Complexity	1 1 3	8.8	6.8	7.3	6.8	6.8	9.5	6.8	6.8	7.5	7.3	6.8	7.3	8.5
ACCURACY OF DATA Suitable Theory to Process Data Calibration or Property Determination Heat Loss/Gain Errors with Time Influence of Model Raiii (Thermal Gradients) Instrument Effect on Surface Temp. Dist. Instrument Effect on Surface Roughness Customize Sensor Sensitivity Accuracy of Inst. Location	9 7 4	8.3	5.6	6.8	5.5	7.3	7.3	7.3	5.9	8.6	9.1	6.3	7.9	7.8
MODEL/INSTRUMENT DURABILITY High Pressures and Vibrations Particle Impingement Surface Temperature Rise	6 5	9.0	6.7	8.7	6.7	4.3	5.0	4.3	8.0	5.0	6.7	4.3	6.7 	9.3
AVG. GRADE OF MAJOR HEADINGS		8.5	6.4	7.3	6 . 2	6.0	7.4	5.9	6.7	7.4*	7.9*	5.9	7.2	8.5

NOTES: (1) Refer to Figure 1 for concepts; Text for objectäves.

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(2) Grading criteria: 1 = poor or very difficult

5 = acceptable or difficult

10 = excellent or simple

(3) Each major heading grade is an average of subheading grading.

(4) Grading is conjectured, based on library and computer studies and general experience to date.
 The * columns include laboratory and wind tunnel experience on samples (anticipated ~ 8.8 prior to recent experience)

TABLE III

REPRESENTATI	E PLATING	PROCEDURES	FOR
SENSITIZED	SMOOTH PL	ASTICS (SSP	N)

P	Process		Solution	Temperature	Time	Agitation
1	2	3			(Min.)	-0-
0	0	0	Sand with wet 400 to 600 grit paper			
0	0	0	Xylene	RT	10	Ultrasonic
0	o	0	Shake off			
0	0		Alconox	RT	10	Ultrasonic
0	0		Rinse water + spray	RT	1	Ultrasonic
		0	Hydrolyzer (Shipley)	140	5	
		0	Rinse water + spray	RT	5	
		0	Neutralizer, PM-950 (Shipley)	110	3	
		ο	Rinse + spray rinse	RT	2	
0			Sensitizer (Stannum Chloride)	120	1	Ultrasonic
	0	0	Catalyst 9F (Shipley)	RT	5	
0	ο	0	Spray rinse	RT		
0			Activator (Palladium Chloride)	120	1	Ultrasonic
	0	0	Accelerator PM-960 (Shipley)	RT	2	
0	0	0	Spray rinse	RT		
0			Repeat Sensitizer and Activator steps			
0	0	0	PM-980 Nickel (Shipley)	RT	5	
0	0	0	Spray rinse	RT		
0	o	o	Niculoy 22 (Shipley)	195	As req'd ~ 10 μ	N ₂
					inch/min.	
0	0	0	Rinse water	195	2	
0	0	0	Spray rinse (optional)	RT	1	

TABLE IV

EVALUATION OF CANDIDATE SUBSTRATE MATERIALS WITH SSPN (TABLE III) PLATING PROCEDURES

Material (Trademarks)	General Casting Characteristics	Air Pores, Roughness	Hardness	Comp atability With Waxed Wires	Plating Results
Stycast 2762FT 3070 1095 2850KT Eccobond 99	X X	ø ø ø x	\$\$ \$ \$ \$		x x
58C Novimide 700/55-F18 700/55-F19 700/55-P19 700/55-F18/P19	x g g g	\$ 	Ø -	- x x x x	
10-XA 125 Thermo-Sil 120	- x	x x x			ø
Kaolite 2200	X	x	x		ø

grading (relative, based on the samples evaluated and not to be considered an absolute conclusion)

27

øø excellent good

X

fair marginal

unsatisfactory

(blank) not evaluated

TABLE V

MATERIAL SAMPLES EVALUATED WITH ATZN PLATING PROCESS

		\$	UBSTRATE MATERIAL		
Filler Material	Emerson Cuming Stycast 2762FT	Emerson Cuming Stycast 3070 +% Filler	Furane Epocast 21 +% Filler	Shell 828 +% Filler	Dow 438 +% Filler
None	0	Ο	0	0	0
Graphite		2, 3, 4*, 5, 8, 16	20,40		
1/16" Long Fiber Glass		2, 4, 6, 8, 12, 18	18, 35, 44		
PVA Fibers		.625, 1.25			
Quartz		4, 8, 11, 22	44, 51	79	24
Aluminum		8, 16	116		

SUBSTRATE MATERIAL

* Considered best with the ATZN process

TABLE VI

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PLATING PROCEDURES FOR ALUMINUM TRANSFER (ATZN) AND ETCHED SURFACE (ECAN) PLASTICS

ATZN *	Phase A ECAN	Phase B ECAN **	Solution	Temperature (°F)	Time (Min.)	Agitation
0			Xylene	RT	10	Ultrasonic
0			Shake off			
0			Alconox	RT	10	Ultrasonic
0			Rinse water + spray	RT	1	Ultrasonic
0			10% Nitric Acid	RT	1	Ultrasonic
0			Zinc Aid	RT	1/2	
	ο		Concentrated Sulfuric Acid	RT	25	
	Ο		Rinse water + spray	RT	2	
	ο		Etch PM-930 (Shipley)	140	5	N ₂
		ο	Etch FM-930 (Shipley)	150	7	N ₂
	ο	ο	Rinse water	RT	2	
	ο	ο	Rinse water + spray	RT	2	and An an
	ο	ο	Neutralizer PM-950 (Shipley)	110	5	
	0	0	Rinse water + spray	RT	2	

TABLE VI (CONTINUED)

ATZN *	Phase A ECAN	Phase B ECAN **	Solution	Temperature ([°] F)	Time (Min.)	Agitation
	O	o	25% Hydrochloric Acid	RT	1	
	0	o	5-2-1 mix catalyst 9F (Shipley)	RT	3	Ultrasonic
	o	ο	Rinse water + spray	RT	2	
	Ο	ο	Accelerator FM-960 (Shipley)	105	2	Stir
ο	0	o	Rinse water + spray	RT	1	
0	o	0	Niculoy 22 (Shipley)	195	As req'd ~ 10 μ	N2
O	0	O	Rinse water	195	inch/min. 2	
0	0	0	Spray rinse (optional)	RT		

* Optimized for Stycast 3070 + 4% graphite with bonded aluminum powder on surface

** Optimized for Stycast 3070 + 4% glass fibers

TABLE VII

MATERIAL SAMPLES EVALUATED WITH ECAN PLATING PROCESS

	Substrate	Material
Filler Material	Emerson Cuming Stycast 3070 + % Filler	Dow 431 + % Filler
None	Ο	
Graphite	4,6	6, 16, 32
Boron Nitride	4 1	
1/16" Long Fiber Glass	4*, 8, 12	
Quartz	8	
Calcium Carbonate	2, 4	
Aluminum	4, 16, 32	
Copper	4, 16	
Carbolized Iron	4, 16, 32	
Pure Iron	8, 16	

* Considered best with the ECAN process

TABLE VIII

ONE INCH DEVELOPMENT MODELS

A. PHASE A

FLAT FACE	DOME FACE	SUBSTRATE MATERIAL	INSTRU- MENTED	SKIN MATERIAL	SKIN THICKNESS	PLATE PROCESS	TUNNEL TESTED	FABRICATION REMARKS
A	B		Yes	17-4 PH	.03 (Nom)	Machine	Yes	Master Models, 4.8 to 9.8 rms
	С	Stycast 3070	Yes	Ni 22-9-M	.001	ATZN	No	Isolated wrinkle on cylinder, void
	D	3070 + 2% Gr.	Yes	Ni 22-9-0	.0015	ATZN	No	Blistered, void
	E	3070 + 3% Gr.	Yes	Ni 22-9-M	.001	ATZN	Yes	ОК
	F	3070 + 4% Gr.	Yes	Ni 22-9-M	.0015	ATZN	Yes	.001 + .0005, OK
G		3070 + 4% Gr.	Yes	Ni 22-9 - M	.0015	ATZN	Yes	.001 + .005, surface 11 to 20 rms
H		3070 + 4% Gr.	Yes	Ni 22-9-M	.003	ATZN	Yes	.002 + .001, 2 piece mold
Ι		3070 + 4% Gr.	Yes	Ni 22-10-N	.0015	ATZN	Yes	.0005 + .001, No Agita- tion Plate Rougher than G
J		3070 + 4% Gr.	No	Ni 22-9-0	.001	ATZN	No	Al. dull, plate spotty, One Blister, <u>void</u>
ĸ		3070 + 4% Gr.	No			-	No	Al. dull, did not plate, <u>void</u>

TABLE VIII (CONTINUED)

FLAT FACE	DOME FACE	SUBSTRATE MATERIAL	INSTRU- MENTED	SKIN MATERIAL	SKIN THICKNESS	PLATE PROCESS	TUNNEL TESTED	FABRICATION REMARKS
L		3070	No	NI 22-9-0	.001	ATZN	No	OK
M		3070	No	NI 22-9-0	.0035	ATZN	No	.003 + .005, face loo after plating, surface 12 to 33 rms
N		3070 + 2% Gr.	No	Ni 22-9-0	.001	ATZN	No	Al. dull, spotty pla Question
0		3070 + 3% Gr.	No		-		No	Al. dull, did not plate, void
P		3070	No	CF-74 + Ni 22-9-M	.001	ATZCN	Yes	.0008 + .0002, Al. dull, plate spotty, Question
	Q	3070 + 2% Gr. + 2% Gl.	No	Ni 22-9-M	.001	ATZN	No	Al. dull, plate spotty, Question
	R	3070	No	CP-74	.001	ATZC	Yes	OK
NOTE:	New RTV	Molds were used	l for subs	equent non-inst	rumented model	s to solve	dull Al.	problem
	s	3070 + 4% Gl.	No	Ni 22-9-M	.0015	ATZN	Yes	Plate spotty
	T	3070 + 2% Gr. + 2% Gl.	No	Ni 22-9-M	.0015	ATZN	Yes	Plate spotty
	U	3070 + 4% Gr.	No	CP-74 + Ni 22-9-M	.00125	ATZCN	Yes	.001 + .00025, OK

TABLE VIII (CONTINUED)

FLAT FACE	DOME FACE	SUBSTRATE MATERIAL	INSTRU- MENTED	SKIN MATERIAL	SKIN THICKNESS	PLATE PROCESS	TUNNEL TESTED	FABRICATION REMARKS
	V	3070 + 4% Gr.	No	CP-74	.001	ATZC	Yes	ОК
W		3070 + 4% Gr.	No				No	Did not plate, surface 13 to 25 rms
x		3070 + 4% Gr.	No	Ni 22-9-M	.0005	ATZN	Yes	ок
Y		3070 + 4% Gr.	No	Ni 22-9-M	.002	ATZN	Jes	OK
	AA	3070	Yes	Ni 22-9.5-N	.0015	ECAN	Yes	.001 + .0005, surface like CC
	BB	3070 + 4% Gr.	Yes	Ni 22-9.5-N	.0015	ECAN	Yes	.001 + .0005, not as rough as CC
CC		3070	Yes	Ni 22-9.5-N	.0015	ECAN	Yes	.001 + .0005, surface 70 to 140 rms
DD		3070	No	NI 22-9.5-N	.003	ECAN	Yes	.0015 + .0015, surface like CC
	EE	3070	No	NI 22-9.5-N	.003	ECAN	No	.0015 + .0015, surface like CC
	FF	3070	No		-	-	No	Did not plate, surface 10 to 17 rms

TABLE VIII (CONTINUED)

B. PHASE B

FI AT FACE	DOME FACE	DATE CAST	SUBSTRATE MATERIAL	INSTRU- MENTED	SKIN MATERIAL	SKIN THICKNESS	PLATE PROCESS	TUNNEL TESTED	FABRICATION REMARKS
	FFF	9/16	3070 + 4 Gl.	No	N1 22-9.5M	.001	ECAN	No	Surface improved, 40 to 78 rms
	GG	9/16	3070 + 4 G1.	No	Ni 22-9.5M	.001	ECAN	No	Surface like FFF
HH		9/16	3070 + 4 G1.	No	Ni 22-9.5M	.001	ECAN	No	Surface like FFF
II		9/16	3070 + 4 G1.	No	Ni 22-9.5M	.001	ECAN	No	Surface like FFF

Footnotes for Table VIII

N1 22- CP74 -	Niculoy 22, Nickel Alloy by Shipley Copper Alloy by Shipley
9-0	90% strength, old solution
9-M	90% strength, old and new solution mixed
10-N	100% strength, new solution
Gr	Graphite, powder
.G1	Glass, chopped fibers
ATZN	Aluminum Transfer cast process with Zinc Aid, Nickel plate procedure
ATZC	Aluminum Transfer cast process with Zinc Aid, Copper plate procedure
ATZCN	ATZC with Nickel plated over the copper
ECAN	Etch, Catalyst, Accelerator treatment of plastic with Nickel plate

С С TABLE IX Model Surviability Results M = 7.32 Tests

Run NO.	hS [*] BTU Ft ² -Sec- ⁰ R	MAX. Model Temp. at $\theta=30^{\circ}$, F	Tinser- tion Time Sec.	Mount Posi- tion	Model Letter	Model Condition After Run
1	.020		2	1	В	go::
				2	A	goc∂
				3	AA	goo
				4	CC	good
n dia 5 Martina Martina dia 4		355		5	BB	good
				6		good
				7	H	good
				8	F	good
				9	G	face wrinkled after run
				10	Е	face wrinkled after run
2	.028		1	1	В	<pre>{slight particle abrasion {at stagnation on all models</pre>
			an an an an traithe an athr a 1975 an ann an Stàitean an An	2	Α	
				3	AA	
				4	CC	
		395		5	BB	
				6	I I	face loose after run
				7	Н	
				8	F	
				9	DD	
				10	V	

TABLE IX Model Surviability Results M = 7.32 Tests

Run No.	hS [*] BTU Ft ² -Sec- ^O R	MAX. Model Temp. at 0=30°, F	*** Inser- tion Time Sec.	Mount Posi- tion	Model Letter	Model Condition After Run
3	.034		en en l a factoria de la composición de la comp	1	В	(particle abrasion
				2	Α	Zmore noticeable
				3	AA	(on all models
				4	CC	
		445		5	BB	
				6	U	particle pitting more appar- ent due to copper under nickel
				7	H	wrinkle and spalling on face
				8	F	two fine cracks in plate from particle pits
				9	DD	
				10	V	particle pitting more appar- ent on copper
4	.040		1	1	В	particle pitting continues
				2	A	fon all models
				3	AA	
				4	CC	
		490		5	BB	
				6	U	
				7	Y	most of plate on face lost
				8	F	some spalling of plate on face
				9	DD	
				10	v	

3 L TABLE IX Model Surviability Results M = 7.32 Tests

Run No.	hS [*] BTU Ft ² -Sec- ^o R	MAX. Model Temp. at $\theta=30^{\circ}$, F	Inser-*** tion Time Sec.	Mount Posi- tion	Model Letter	Model Condition After Run
5	.038		2	1	В	particle pitting very noticeable
				2	А	particle pitting very noticeable
n gana. Tinang				3	AA	some particles penetrating plate,
				4	CC	local damage only some particles penetrating plate,
				4	UU I	local damage only
		540		5	BB	practically no particle penetra-
				6	IJ	tion, very little abrasion face area very pitted and rough
				Ŭ		
				7	X	most of plate on face lost
				8	T	plate peeling at stagnation area
				9	DD	two small blisters and a crack in plate on face, very little
				10	v	particle penetration most particles penetrating
						through plate and deep into
6	.043		2	1	$\mathbf{B}^{(n)}$	substrate pitted, rough face
	•0+3			2	A	pitted, rough face
	an a the second s			3	AA	hit by a large particle leaving
				,		a crater and local plate damage, fine cracks in plate at stagnation
				1	CC	particle pitting of plate notice- ably increased

TABLE IX Model Surviability Results M = 7.32 Jests

Run No.	hs [*] BTU Ft ² -Sec- ⁰ R	MAX. Model Temp. at θ=30°,°F	*** Inser- tion Time Sec.	Mount Posi- tion	Model Letter	Model Condition After Run
6 (Cont'd)	.043	615	2	5	BB	two small blisters in plate near stagnation
				6	U I	fine cracks in plate in addi- tion to heavy pitting
				7 8	P R	wrinkles in plate on face stagnation area blue and pur- ple from heat
				9	DD	more cracks in plate, particle penetration low
				10	v	stagnation area blue and pur- ple from heat
7	.039		2	1	В	no apparent change (except more particle hits)
				2	A	no apparent change
				3	AA	no apparent change
				4	CC	no apparent change
		560		5	BB	no apparent change
				6	U	most of plate on face lost, peeled back
				7	S	local spalling and blistering of plate on face
				8	R	no apparent change
				9	DD	cracks in plate increased, lost a spot of top coat of plate
				10	v	no apparent change

			M	= 7.32 Tests		
Run No.	hs [*] BTU Ft ² -Sec- ⁰ R	MAX. Model Temp. at θ = 30°, F	*** Inser- tion Time Sec.	Mount Posi- tion	Model Letter	Model Condition After Run
8	.040	470	2	1 2 3 4 5	B A Ar CC BB	{no apparent change in any of models
				6 7 8 9 10	- - - V	models in mounts 6-9 removed and mount rotated 90° so that position 5 is top, an objec- tive of run was to get best shadowgraph view of shock system on each type of model

TABLE IX Model Surviability Results M - 7 22 Monto

.*:

Measured value on Model B, 1.0 inch diameter hemisphere Measured on Model BB, 30° off stagnation, 1.0 inch diameter hemisphere; this model mounted such ** that it was first into and last out of flow, maximum temperature reached during retraction cycle. *** Delta time between beginning of insertion to beginning of retraction

£

	Run No.	P _T Psia	T oR R	Re ^{/ft} 6 x 10 ⁻⁶	Model Face & Type	Model T/C	S/R	Twi oR t = 0	$\begin{array}{c} Q\\ \underline{Btu}\\ \widetilde{ft}^2-sec\\ t=0 \end{array}$	h Btu ft ² -sec- ^o R	h h _s Flat	h h _s Sphere
	1	202.8	1548.7	.813	Dome Master	B001 B002 B003 B004	0 .524 1.047 1.571	562.0 560.4 559.0 557.2	19.494 17.185 8.907 2.083	.01976 .01738 .00906 .00210		1.0 .8796 .4585 .1063
					Flat Master	A001 A002 A003 A004	0 .50 1.146 3.092	563.0 563.2 562.8 561.9	11.491 12.854 12.888 1.137	.01166 .01304 .01307 .00115	1.0 1.1184 1.1209 .0986	.5901 .6599 .6614 .0582
					Flat ECAN	CC012 CC002 CC003 CC004	.50 .50 1.146 3.092	552 552 552 552 552		.01189 .01628 .01446 .00136	1.0200 1.3962 1.2401 .1166	
					Flat ATZN	1012 1002 1003 1004	.50 .50 1.146 3.092	545 545 545 545 545		.01399 .01283 .01256 .00139	1.1998 1.1003 1.0772 .1192	
41					Flat ATZN	G012 G002 G003 G004	.50 .50 1.146 3.092	540 540 540 540		.01374 .01328 .01256 .00151	1.1784 1.1389 1.0772 .1295	

Run No.	P _T P sia	°R R	Re/ft_6 x 10	Model Face & Type	Model T/C	S/R	Twi oR t = 0	$\frac{g}{Btu}$ ft ² -sec t = 0	h <u>Btu</u> ft ² -sec- ⁰ R	<u>þ</u> ^h s Flat	h ^h s Sphere
2	399•3	1561.1	1.5 7 9	Dome Master	B001 B002 B003 B004	0 .524 1.047 1.571	572.4 570.6 569.1 567.1	27.800 24.713 13.217 2.901	.02812 .02495 .01332 .00291		1.0 .8873 .4737 .1035
				Flat Master	A001 A002 A003 A004	0 .50 1.146 3.092	573.5 573.9 573.4 570.9	15.977 18.283 18.129 1.672	.01619 .01852 .01836 .00169	1.0 1.1448 1.1346 .1044	.5754 .6587 .6528 .0601
				Flat ECAN	CC012 CC002 CC003 CC004	.50 .50 1.146 3.092	555 555 555 555 555		.01797 .02347 .01916 .00171	1.1099 1.4500 1.1834 .1056	
				Flat ATZN	. 1012 1002 1003 1004	.50 .50 1.146 3.092	550 550 550 550		.01957 .01777 .01658 .00172	1.2088 1.0976 1.0241 .1062	

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				M = 7.32,	AMES 3-1/2	2 FOOT HI	PERSONIC	TUNNEL			
Run No.	P _T Psia	5 _R	Re/ft_6 x 10 ⁻⁶	Model Face & Type	Model T/C	S/R	Twi °R t = 0	$\begin{array}{c} Q\\ \underline{Btu}\\ \mathbf{ft}^2 - \mathbf{sec}\\ \mathbf{t} = 0 \end{array}$	h <u>Btu</u> ft ² -sec- ⁰ R	h ^h sFlat	h h Sphere
3 1011 1011 1011 1011 1011 1011	599. 2	1597.8	2.277	Dome Master	B001 B002 B003 B004	0 .524 1.047 1.571	566.7 564.2 562.0 559.7	34.666 31.005 16.614 3.663	.03362 .02999 .01603 .00352		1.0 .8920 .4848 .1047
				Flat Master	A001 A002 A003 A004	0 .50 1.146 3.092	568.2 568.4 568.0 567.8	20.205 22.769 22.471 2.007	.01962 .02212 .02182 .00195	1.0 1.1274 1.1121 0.0994	.5836 .6579 .6490 .0580
				Flat ECAN	CC012 CC002 CC003 CC004	.50 .50 1.146 3.092	555 555 555 555 555		.02250 .02916 .02375 .00257	1.1468 1.4862 1.2105 .1310	
4	850.2	1616.3	2.638	Dome Master	B001 B002 B003 B004	0 .524 1.047 1.571	580.1 577.2 574.6 572.2	41.390 36.959 19.783 4.462	.03994 .03556 .01899 .00427		1.0 .8902 .4754 .1069
				Plat Mäster	A001 A002 A003 A004	0 .50 1.146 3.092	581.7 581.6 581.1 582.9	24.153 26.840 27.025 2.446	.02335 .02594 .02611 .00237	1.0 1.1112 1.1183 .1014	. 5844 . 6494 . 6536 . 0593
				Flat ECAN	CC012 CC002 CC003 CC004	.50 .50 1.146 3.092	570 570 570 570 570		.02616 .03452 .02802 .00294	1.1203 1.4784 1.2000 .1259	

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Run No.	P _T Psia	T OR	R/ft x ^e 10 ⁻⁶	Model Face & Type	Mođel T/C	S/R	Twi R t = 0	$\frac{g}{\text{Btu}}$ $\frac{ft^2-\sec}{t=0}$	h <u>Btu</u> ft ² -sec- ⁰ R	h ^h s Fla t	h ^h s _{Sphere}
5	848.0	1562.4	3.349	Dome Master	B001. B002 B003 B004	0 .524 1.047 1.571	569.3 566.7 564.3 561.9	37.940 33.929 18.471 4.356	.03821 .03407 .01850 .00435		1.0 .8917 .4844 .1138
				Flat Master	A001 A002 A003 A004	0 .50 1.146 3.092	571.6 571.7 571.4 571.4	23.230 25.222 24.720 2.318	.02344 .02546 .02494 .00234	1.0 1.086 1.064 .0998	.6135 .6663 .6527 .0612
				Flat ECAN	CC012 CC002 CC003 CC004	.50 .50 1.146 3.092	560 560 560 560		.02268 .03025 .02680 .00286	.9676 1.2906 1.1433 .1220	
6	997.1	1617.7	3.709	Dome Master	5001 9002 9003 9004	0 .524 1.047 1.571	571.7 568.8 564.8 561.5	45.142 40.320 22.032 5.293	.04316 .03844 .02092 .00501		1.0 .8906 .4847 .1161
				Flat Master	A001 A002 A003 A004	0 .50 1.146 3.092	573.0 574.6 573.7 573.1	26.626 29.240 28.759 2.725	.02540 .02803 .02755 .00261	1.0 1.0999 1.0808 .1024	.5905 .6495 .6383 .0604
				flat Ecan	CC012 CC002 CC003 CC004	.50 .50 1.146 3.092	550 550 550 550		.02462 .03347 .03039 .00340	.9693 1.3177 1.1965 .1339	

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Run No.	P _T Psia	Г Т С	R _e /ft x 10-6	Model Face & Type	Model T/C	S/R	^Î Wi ^O R t = 0	$\frac{Btu}{ft^2-sec}$ t = 0	h Btu ft ² -sec- ^c R	h h _s Flat	h ^h sSpher
7	848.0	1549.3	3.397	Dome Master	B001 B002 B003 B004	0 .524 1.047 1.571	575.8 573.5 570.3 567.6	37.658 33.625 18.381 4.421	.03871 .03445 .01877 .00450		1.0 .8900 .4849 .1162
				Flat Master	A001 A002 A003 A004	0 .50 1.146 3.092	577.4 578.9 577.9 576.9	22.666 24.805 24.338 2.297	.02332 .02556 .02506 .00236	1.0 1.0961 1.0744 .1013	.6023 .6602 .6471 .0610
				flat ECAN	CC012 CC002 CC003 CC004	.50 .50 1.146 3.092	558 558 558 558 558		.02287 .02995 .02753 .00296	.9807 1.2843 1.1805 .1269	
8	846.7	1415.9	3.952	Dome Master	B001 B002 B003 B004	0 .524 1.047 1.571	563.9 564.1 562.2 560.3	34.131 30.320 16.431 3.870	.04006 .03559 .01924 .00452		1.0 .8647 .4674 .1098
				Flat Master	A001 A002 A003 A004	0 .50 1.146 3.092	561.2 559.9 557.1 553.9	20.044 22.155 21.896 2.045	.02342 .02588 .02550 .00237	1.0 1.1053 1.0888 .1012	.5845 .6461 .6364 .0592
				Flat ECAN	CC012 CC002 CC003 CC004	.50 .50 1.146 3.092	547 547 547 547		.02271 .02965 .02778 .00306	.9697 1.2660 1.1862 .1307	

Model Face and Type	-Model T/C	S/R	h ^h s Sphere	h s Theory	h h ^S Flat	Runs Averaged
Dome	B001	0	1.0000	1.020***		1-8
Master	B002	•524	.8864			
	B003	1.047	.4767		(1,1) = (1,1) + (1,1	-
	B004	1.571	.1097			
Flat	A001	0	•5906	1.011****	1,0000	1-8
Master	A002	.50	• > > > 0 0	I. VII	1.1111	1=0
	A003	1.146			1.0990	
	A004	3.092			0.1011	
Flat	CC002 & CC012					
ECAN	CC012	•50			1.2034	1-8
	CC003	1.146			1.1937*	
	CC004	3.092			0,1240*	
_						
Flat	CC002 & CC012	.50			1.1057**	1-8
ECAN	CC003	1.146				1-0
	CC004	3.092			1.093** 0.1141**	
	0004	3.092			0.1141	
Flat	1002 4					
ATZN	1012	•50			1.1516*	1-2
	I003	1.146			1.0874#	
	1004	3.092			.1127*	
					•	
Flat	G002 &					
ATZN	G012	.50			1.1587#	1
	G003	1.146			1.0772*	
	G004	3.092			.1295 *	

■ Using mid fairing of VPCK

****** Using lower fairing of $\sqrt{\rho CK}$ (See Figure 16)

*** Fay-Riddell theory (Calculated each run by NASA Ames)

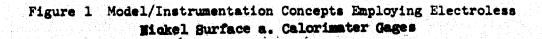
Zoby-Sullivan theory, Ref. 11

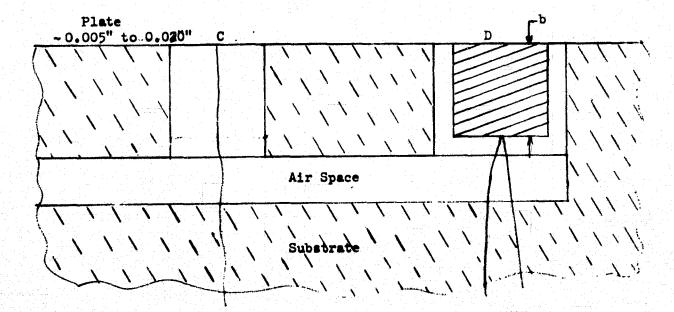
TABLE XII SELECTIVE PLATING PROCESS ON STAINLESS STEEL MODEL

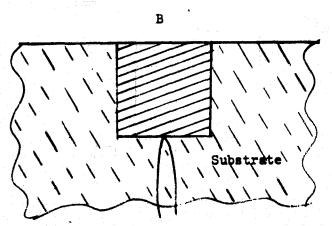
Solution or Treatment	Temperature (°F)	Time** (Min.)
* Nickel Chloride Plate	140	Strike Coat
Preheat in Oven	175	60
Clean 1424 (Shipley)	165	12
Water Rinse and Spray	RT	
Dry in Oven	175	30
Resist AZ111 (Shipley)	RT	Dip
o Air Dry	RT	30
• Resist AZ111 (Shipley)	RT	Dip (Opposite End First)
Air Dry H Resist AZ111 (Shipley) Airdry	RT	30
S Cure in Oven	175	60
Expose Pattern Through Negative	RT	15
With Ultraviolet Lamps Develop AZ-303A (Shipley)	RT	10
Water Rinse and Spray	RT	
Bake in Oven	400	60
Preheat Model	200	60
Activate 1424 (Shipley)	165	13
Water Rinse and Spray	165	2
Plate Niculoy 22 (Shipley)	195	As Required ∼10 µ in./min. ***
Remove Resist 1112A (Shipley)	170	60
Water Rinse and Spray	RT	

* Optional, Depending on Plate Thickness Required

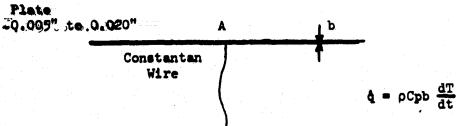
- ** Approximate Times; Actual Times Dependent on Specific Condition, i.e. Model Size, Light Intensity, Resist Thickness, etc.
- *** Two Coats of Resist Will Withstand Activation and Plating to Approximately 0.001 Inch Thickness











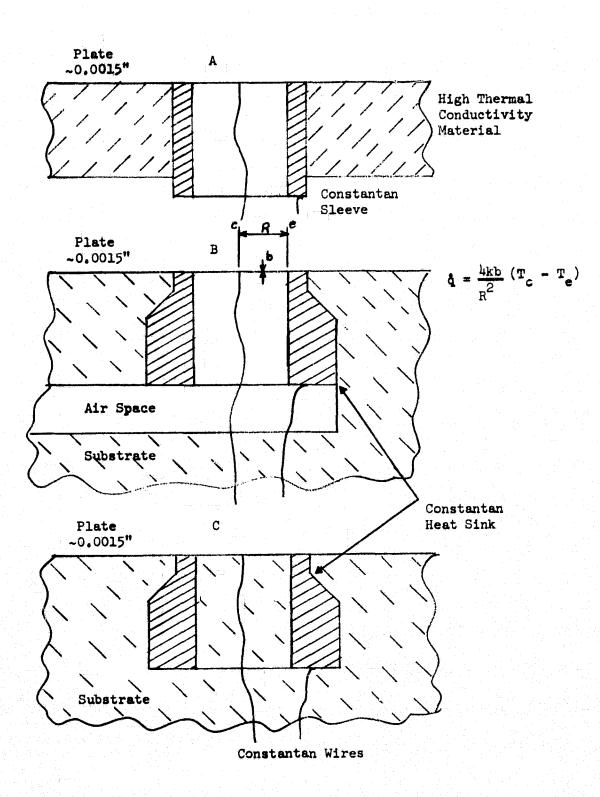
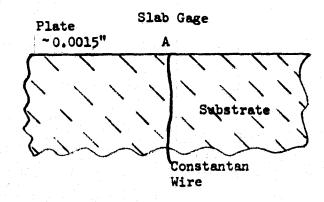
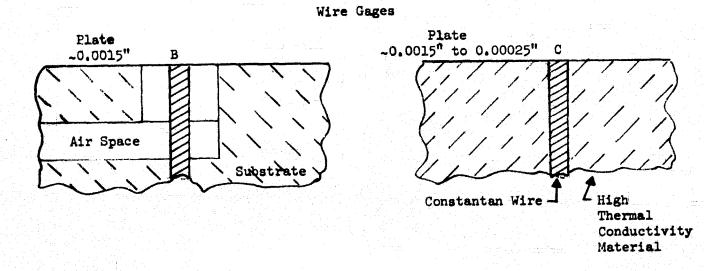


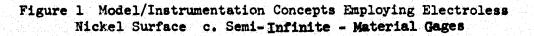
Figure 1 Model/Instrumentation Concepts Employing Electroless Nickel Surface b. Gardon Gages



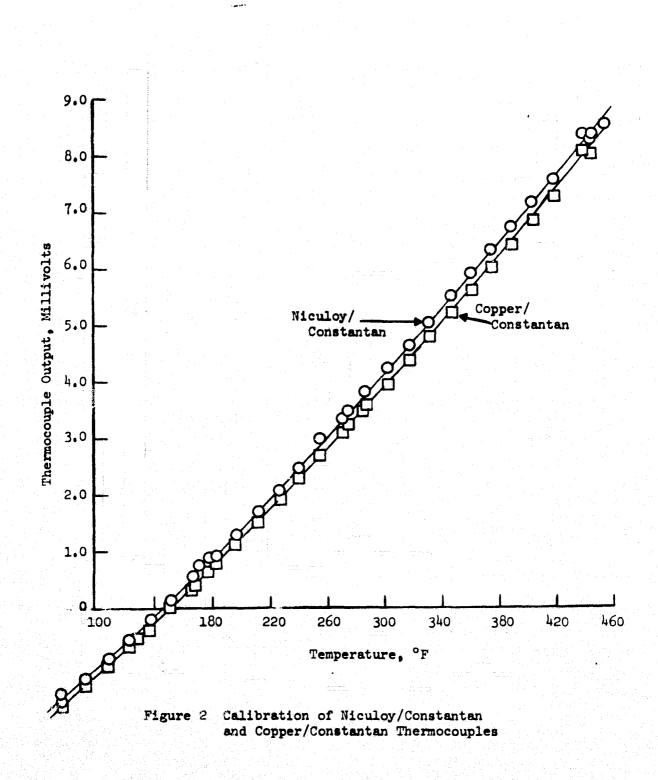
h =
$$\frac{\beta \sqrt{\rho ck}}{\sqrt{t}}$$

 $\frac{T_{w} - T_{i}}{T_{aw} - T_{i}}$ = 1 - $e^{\beta^{2}} erfc \beta = \overline{T}$

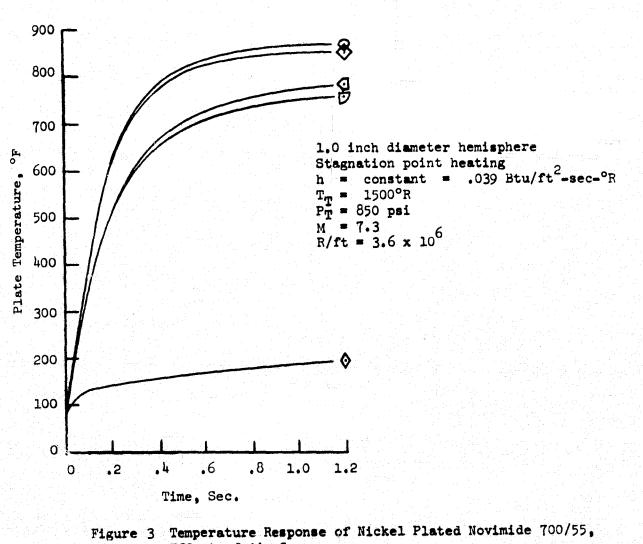


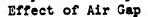


الديني الموتي ويرتبعوا



	ckness (in) kel Plate	Diameter (in) Constantan Wire	Air Gap (in) Around Wire	Substrate Material
\diamond	.0015	.010	0	Novimide 700/55
$\mathbf{\nabla}$.0015	.010	.010	Novimide 700/55
	.0015	.03125	0	Novimide 700/55
D	.0015	.0325	.01625	Novimide 700/55
\diamond	.0015	Ø	••••••••••••••••••••••••••••••••••••••	





	Thickness (in) Niculoy Plate	Diameter (in) Constantan Wire	Substrate Material
	.001	он салаан байлаан байла Салаан байлаан б	Novimide 700/55
Δ	.001	.003	Novimide 700/55
\diamond	.001	.010	Novimide 700/55
Q	.001	.032	Novimide 700/55
\mathbf{Q}	.001	2	***

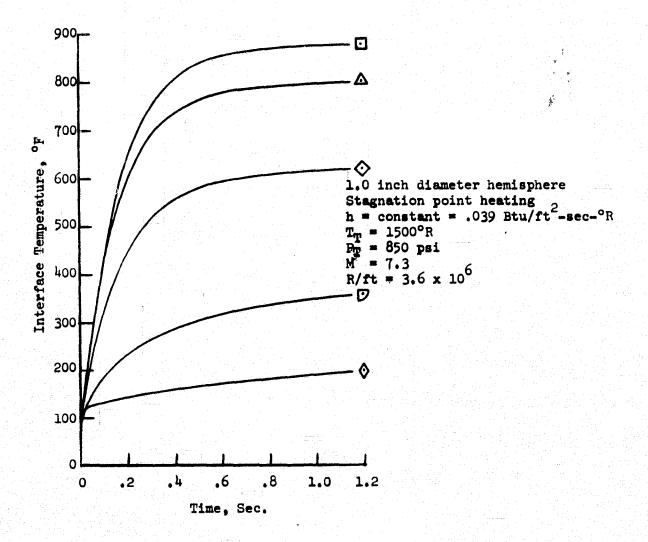
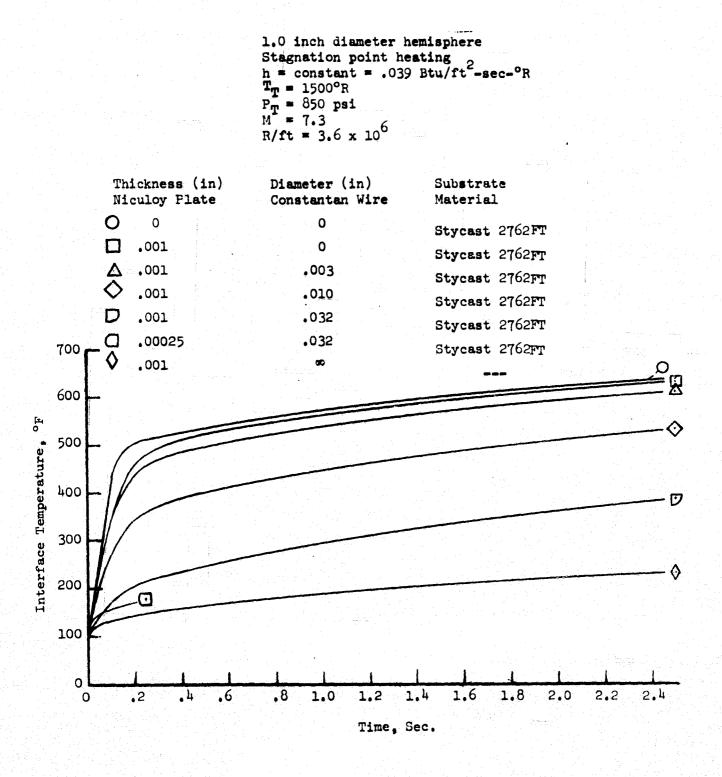
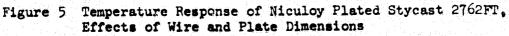
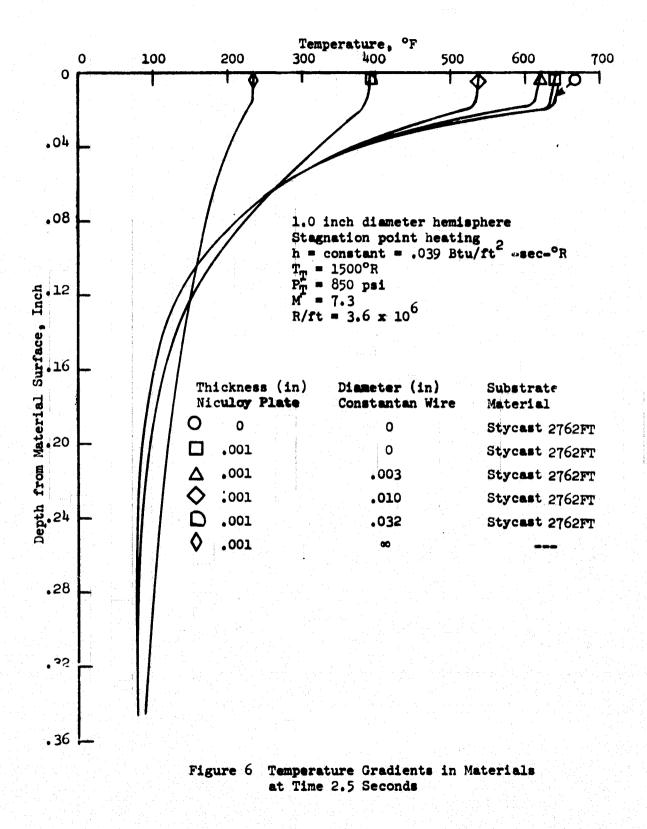


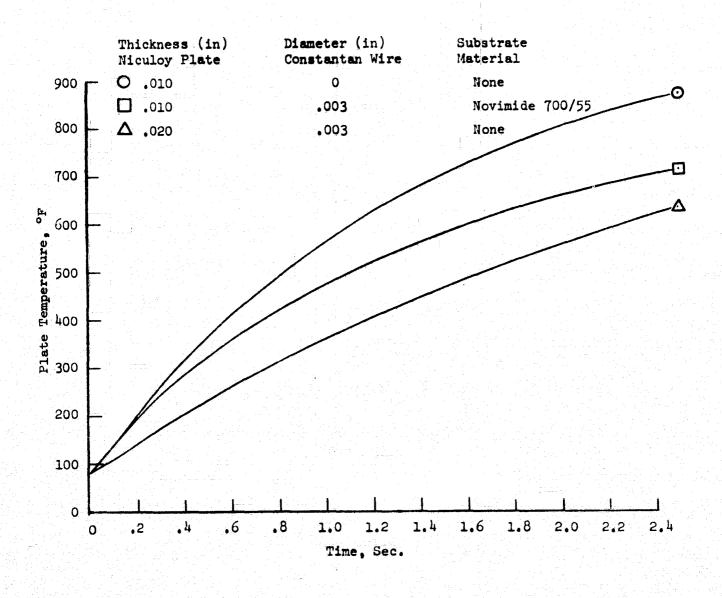
Figure 4 Temperature Response of Niculoy Plated Novimide 700/55, Effect of Wire Diameter

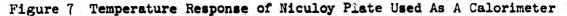






1.0 inch diameter hemisphere Stagnation point heating $h = \text{constant} = .039 \text{ Btu/ft}^2 \text{-sec-}^{\circ} \text{R}$ $T_T = 1500^{\circ} \text{R}$ $P_T = 850 \text{ psi}$ M = 7.3 $\text{R/ft} = 3.6 \times 10^6$





1.0 inch diameter hemisphere Stagnation point heating h = constant = .039 Btu/ft²-sec-°R T_{m} = 1500°R B_{m} = 850 psi M⁴ = 7.3 R/ft = 3.6 x 10⁶

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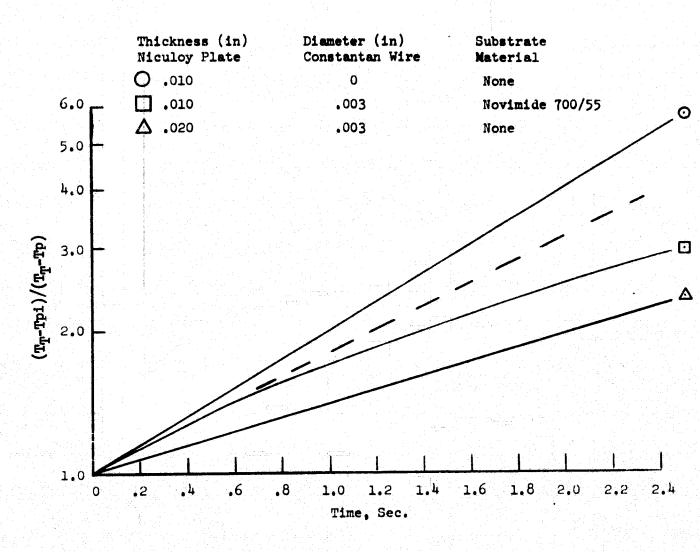


Figure 8 Effect of Substrate and Wire on Calorimeter Temperature History

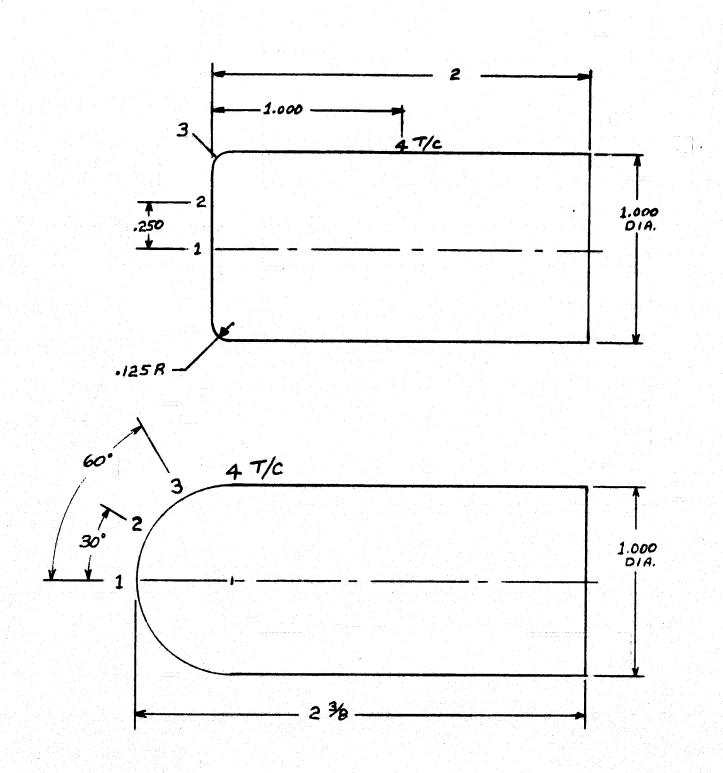


Figure 9 Geometry and Thermocouple Locations of Development Models

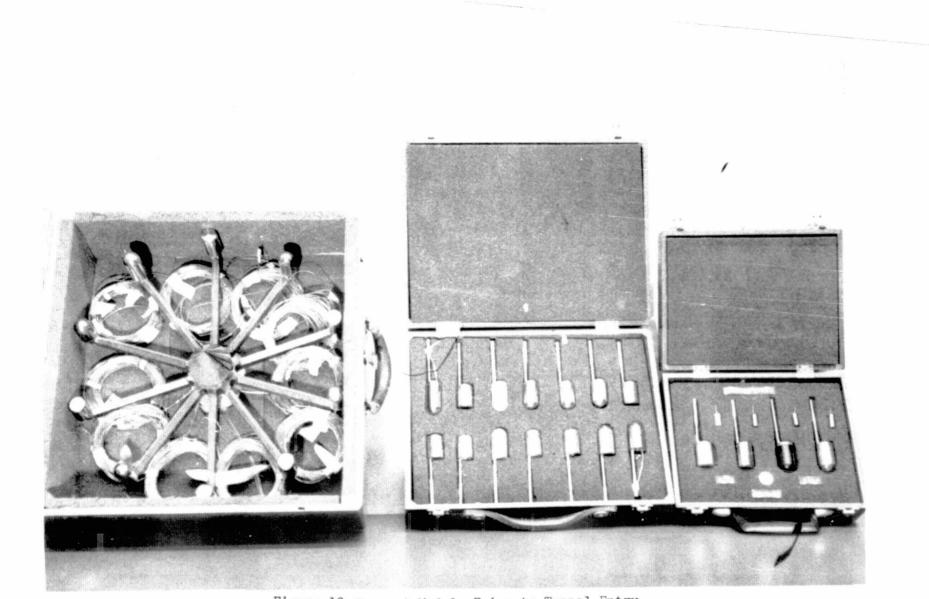


Figure 10 Phase A Models Prior to Tunnel Entry

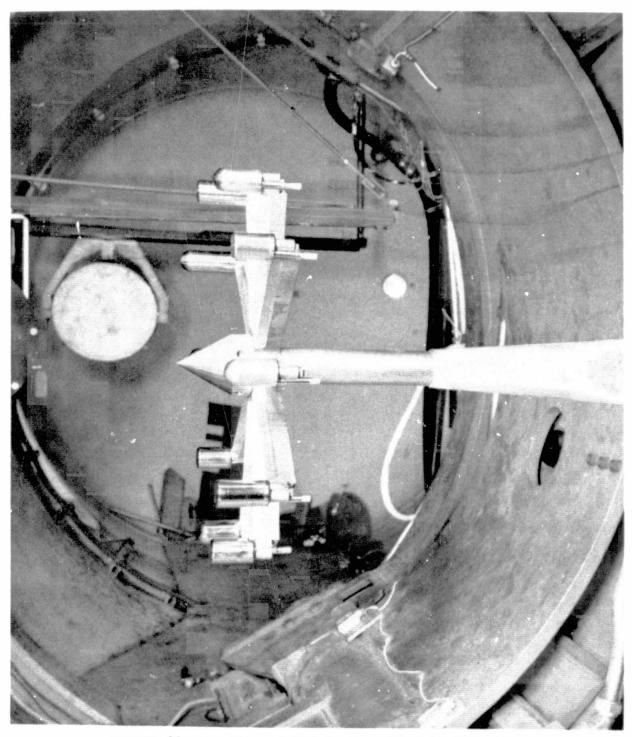


FIGURE 11 Ten Phase A Models Installed in NASA Ames 3-1/2 Foot Hypersonic Wind Tunnel

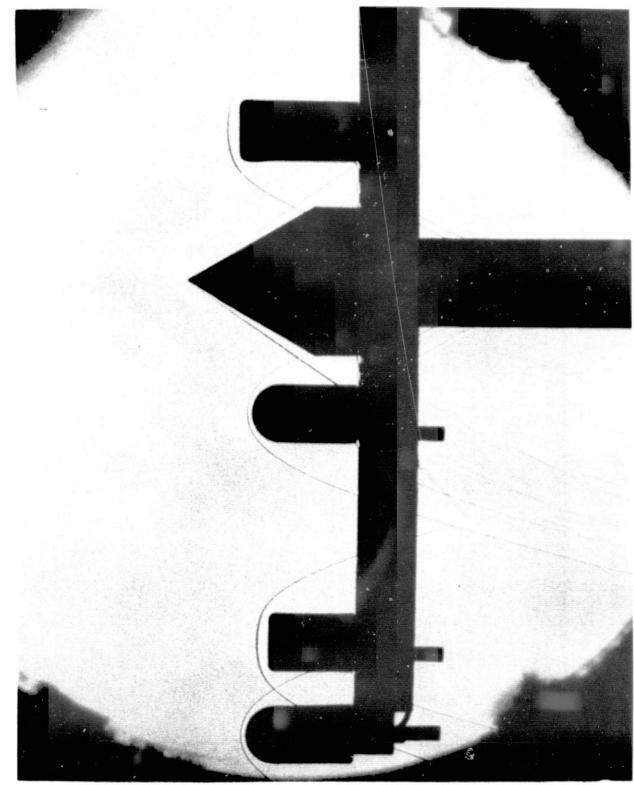
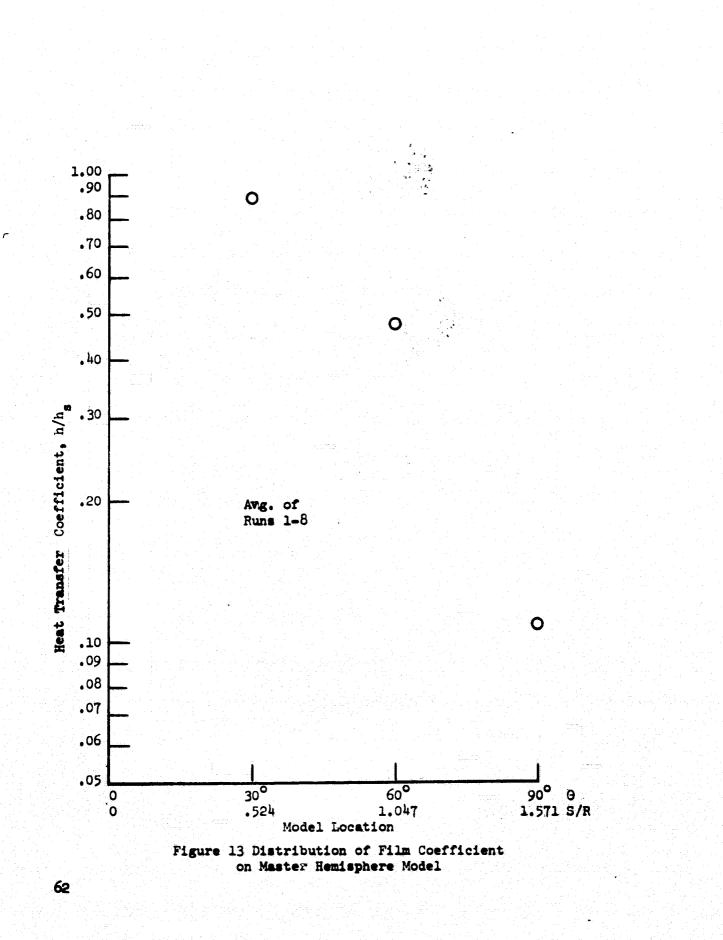


Figure 12 Phase A Models Being Tested at M = 7.32





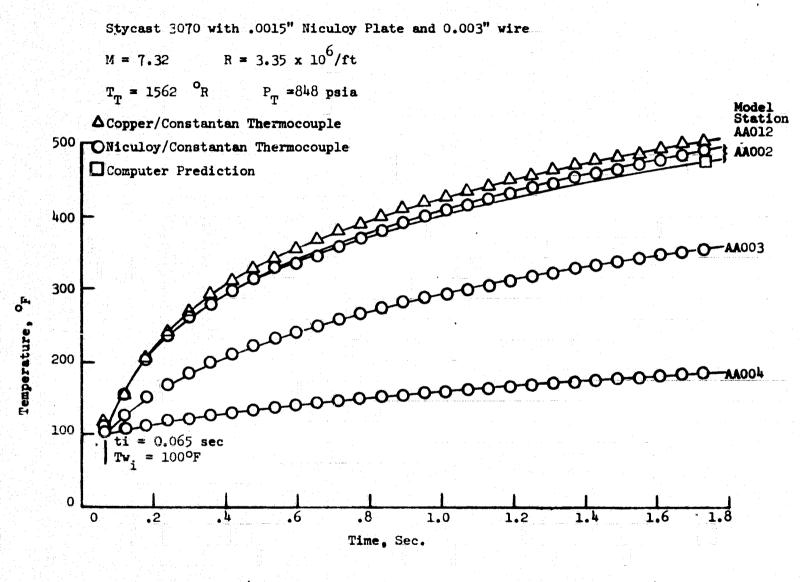


Figure 14 Temperature History of Model AA Hemisphere, Run 5

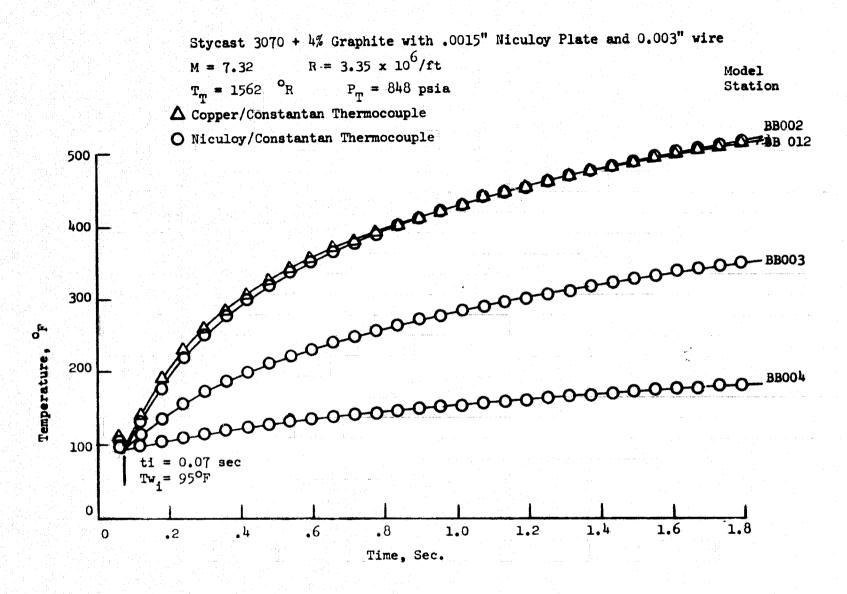


Figure 15 Temperature History of Model BB Hemisphere, Run 5

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Stycast 3070 with .0015" Niculoy Plate and 0.003" wire for all Runs 1-8, M = 7.32 Ranges: .8 x 10⁶ < R/ft < 4.0 x 10⁶ 202 < P_T, Psia < 1000 1415 < T_T, ⁶R < 1618

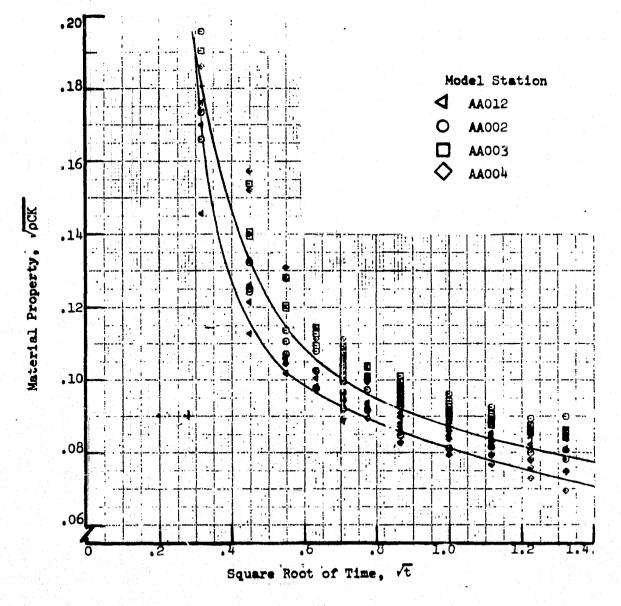
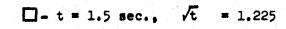


Figure 16 Material Property of Model AA Hemisphere

Stycast 3070 with .0015" Niculoy Plate and 0.003" wire for all Runs 1-8, M = 7.32 Ranges: .8 x 10⁶ < R/ft < 4.0 x 10⁶ 202 < P_T , Psia < 1000 1415 < T_T , ^oR < 1618 O-t = .5 sec., \sqrt{t} = .707



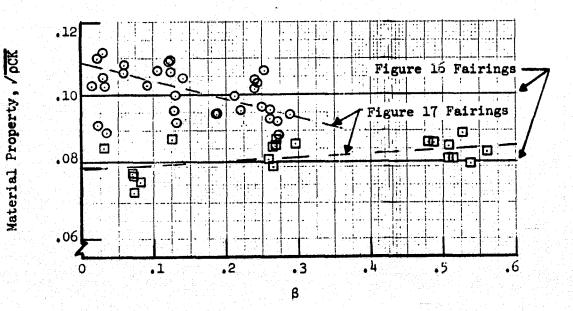
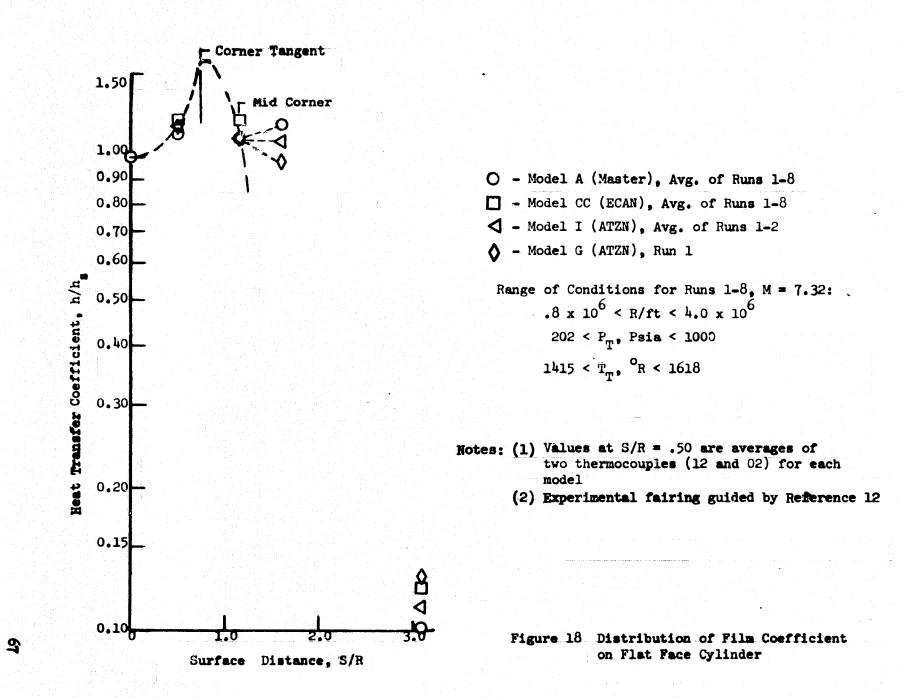
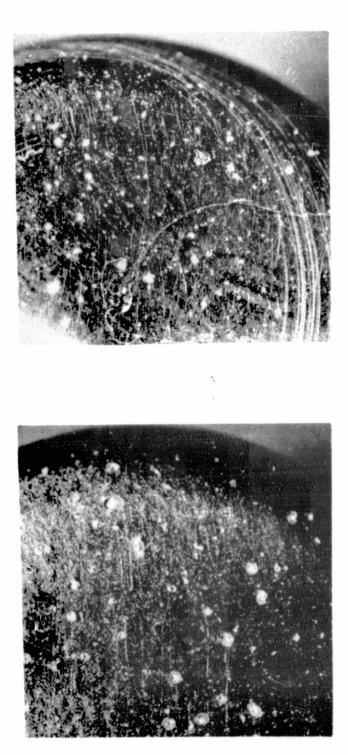


Figure 17 Material Property of Model AA as Function of β at Selected Times





Model A Steel Master Flat Face 8 x Magnification

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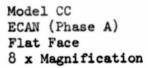


FIGURE 19 Comparison of Particle Damage Between Steel and Plated Epoxy Models After Eight Tunnel Runs

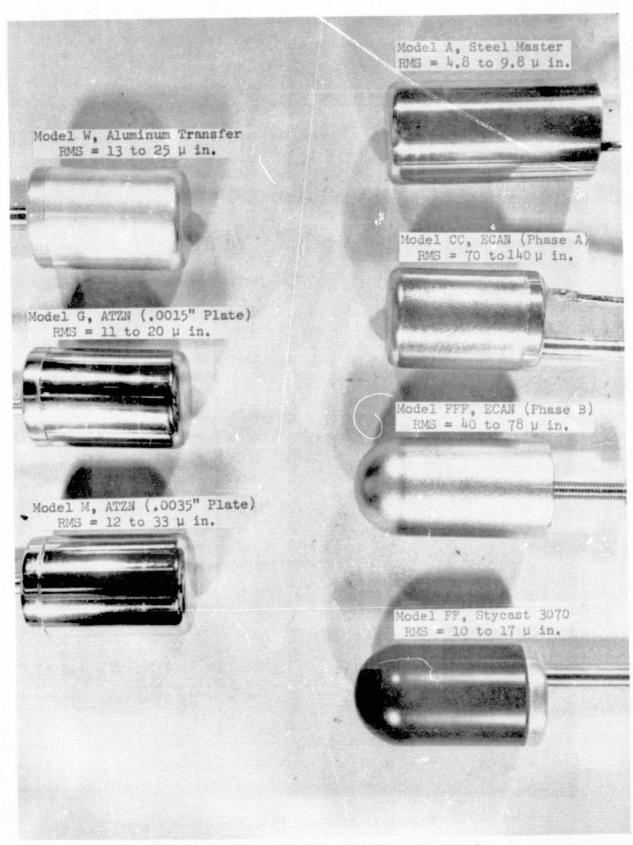
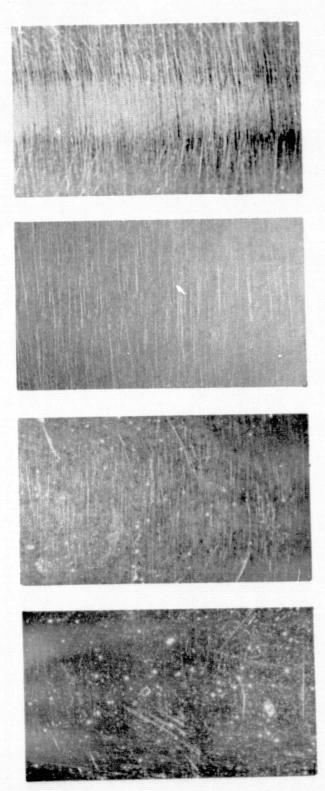


Figure 20 Representative Development Models



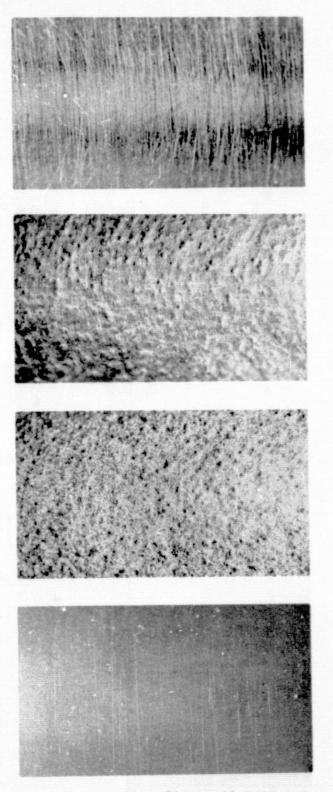
Model A, Steel Master 8 x Magnification RMS = 4.8 to 9.8 µ in.

Model W, Aluminum Transfer 8 x Magnification RMS = 13 to 25 μ in.

Model G, ATZN (0.0015" Plate) 8 x Magnification RMS = 11 to 2ύ μ in.

Model M, ATZN (0.0035" Plate) 8 x Magnification RMS = 12 to 33 μ in.

Figure 21 ATZN and Master Model Surfaces



Model A, Steel Master 8 x Magnification RMS = 4.8 to 9.8 µ in.

Model CC, ECAN (Phase A) 8 x Magnification RMS = 70 to 140 µ in.

Model FFF, ECAN (Phase B) $8 \times Magnification$ RMS = 40 to 78 μ in.

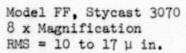


Figure 22 ECAN and Master Model Surfaces

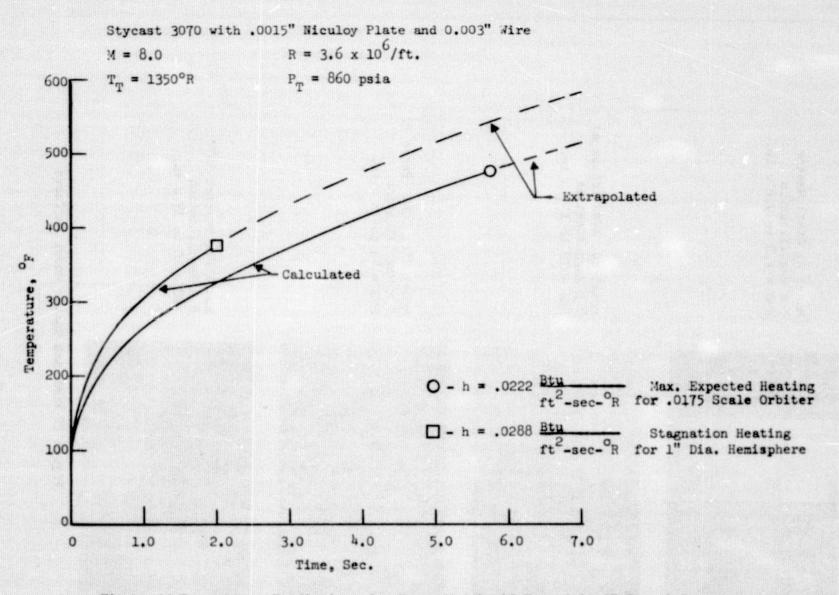


Figure 23 Temperature Predictions for Epoxy Models if Tested in AF Tunnel B at Maximum Reynolds Number

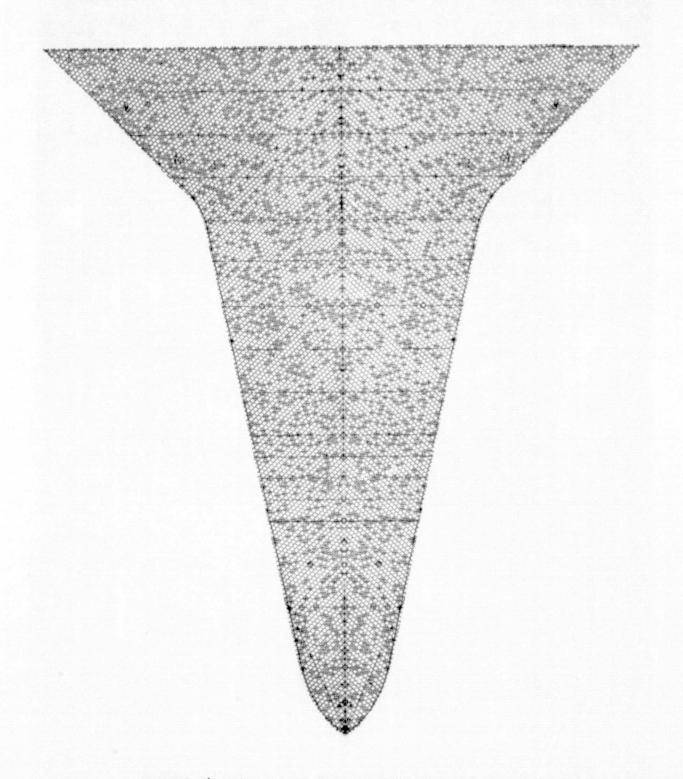
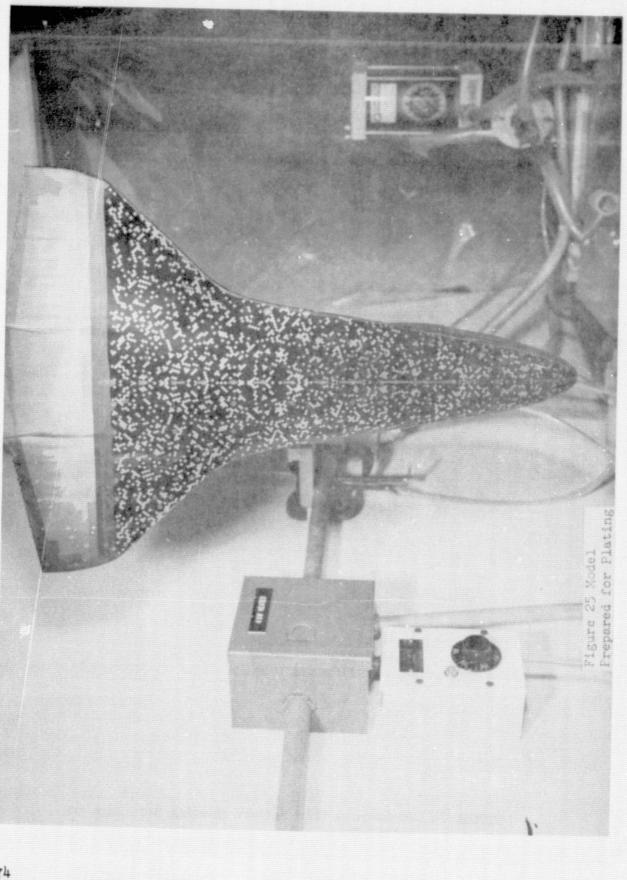


FIGURE 24 Heatshield Tile Pattern Showing Selection of Raised Tiles



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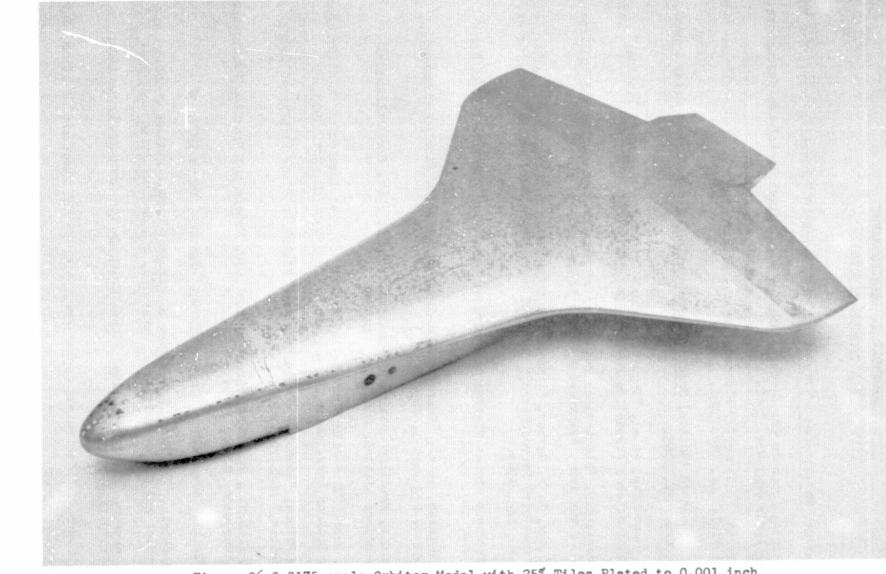


Figure 26 0.0175 scale Orbiter Model with 25% Tiles Plated to 0.001 inch

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Appendix II

Description of a Computer Routine for the Analysis of a Two-Dimensional Conductive Heat Transfer

By: T. C. Pope

A simplified heat transfer routine has been developed for the analysis of two-dimensional conductive heating in a body comprised of as many as four materials. The heat source for the system was conductive heating, represented by $\hat{Q} = HA \left(T_{\substack{\text{adiabatic}\\ \text{wall}}} - T_{\substack{\text{wall}}} \right)$, to which one side of the body was

exposed. Although the routine was coded for a specific problem, it is adaptable and can be used for other applications involving conductive heating.

The program was developed under NASA contract NAS9-13692 for the purpose of determining the effects of the geometric and thermal-property variations which could be affected in the design of heat transfer instrumentation. The basic configuration is illustrated in Figure 1 and consists of a thin, metallic film to which a wire is butted to the backside; the remainder of the backside volume consists of a low-conductivity substrate and, if desired, an air gap around the wire.

Since the problem was two-dimensional, the model configuration was sliced in half and divided into finite elements as shown in Figure 2. (The arrangement and number of elements in this figure, 4 by 10, is for illustrative purposes only; the routine is capable of handling 11 by 44 elements if computation time is not a consideration.) A single element is shown in Figure 3 and the various conductive areas are defined. The two-dimensional elements which were modeled in the computer routine are illustrated in Figure 4 with the areas designated and the heat flow sign convention defined.

By modifying the three-dimensional elements of Figures 2 and 3 to the twodimensional form of Figure 4, the model matrix becomes that of Figure 5. The dimensions of the elements may be varied; however, with the present arrangement the first two layers have a width of half the wire diameter and a depth or thickness equal to the film thickness; the remaining layers have the same width and a thickness of 0.05 inches. The program is a finiteinterval computation of the heat balance equation given in Figure 4 for each of the elements. The incremental heat conduction is calculated from

(thermal conductivity)(conduction area)(temperature difference between elements)(time increment) (conduction length)

for each of the four heat flux components. The temperature increment for each element is caluclated from

(heat stored)

(specific heat)(density)(element volume)

The boundary conditions slightly alter the heat balance equation in Figure 4. For instance, for elements on the surface (the first layer) Q₁ would be replaced by HA (T_{adiabatic} -T_{wall}). Similarly, the sides and bottom are wall

adiabatic boundaries so that the appropriate Q in each case would be set to zero. The selection of the time increment is most important from two aspects not related to accuracy. If the increment is too small, the computer time can become prohibitive. If the time increment is too large, the computed temperatures will begin to oscillate, rather than continuously rise, and subsequently diverge. An estimate of the magnitude of the largest increment that can be used. and divergence avoided, is given by

(specific heat)(density)(element thickness)² thermal conductivity

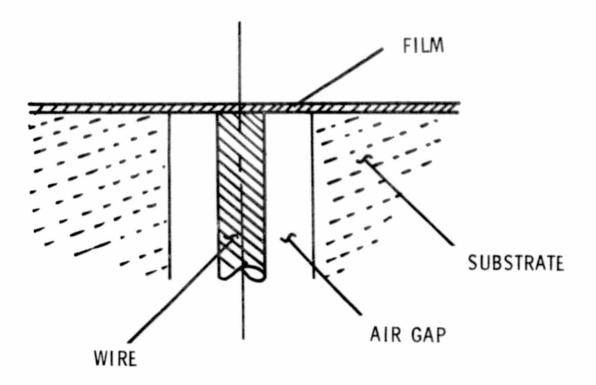
The above expression must be evaluated for each material and the minimum value obtained selected for use.

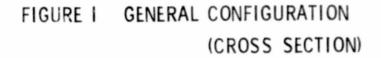
With regard to the simplification of the routine it should be noted that radiation has been neglected in the heat balance equation. Similarly, corrections for joints (interfaces between materials) have been omitted. This was done because of the ill defined joints which would probably exist and the complexity which would be required in establishing the model matrix for the routine. Finally, in the runs that were made with an air gap separating the wire from the substrate, convection was ignored.

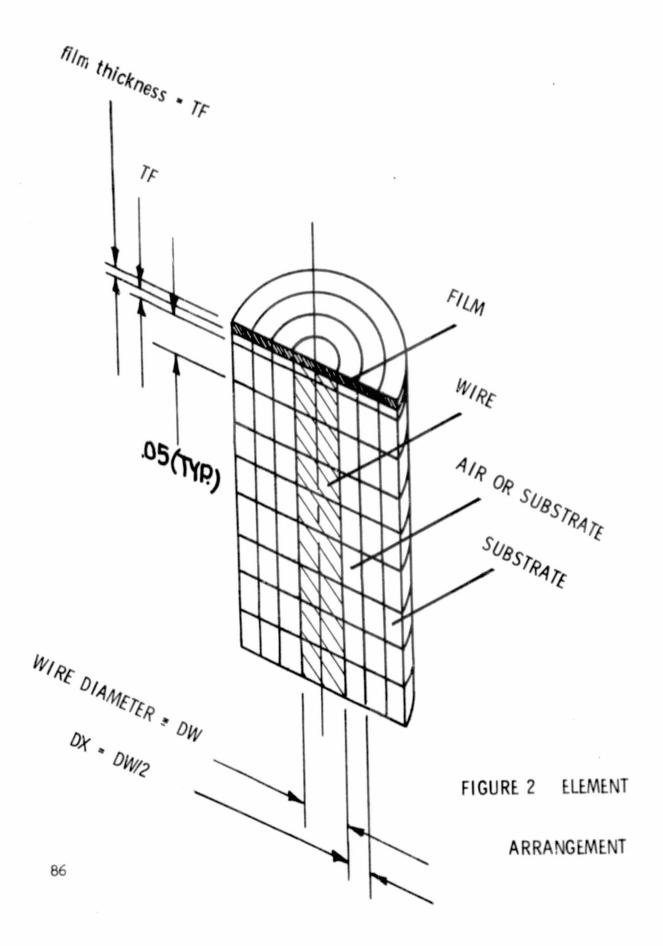
The results which were generated for the aforementioned contract are difficult to check. Thus, to provide some verification of the routine and procedures upon which it was based, a classical, constant-property, semiinfinite-slab problem was run, and a series of hand calculations were made using the information presented in <u>Temperature Response</u> <u>Charts</u> by P. J. Schneider @ 1963, John Wiley & Sons, Inc. A comparison of these results is shown in Figure 6. The agreement between the two methods at 3 seconds (the problem termination time) was within 0.1°F. This extremely small difference is particularly impressive or perhaps fortuitous since in the course of this solution the computer performed 30,000 finiteinterval approximations without the benefit of extended precision. This feature was not available due to the limitation of the storage capacity.

Other applications of the routine may be effected by varying the material properties and element dimensions as desired. Cases ranging from the basic semi-infinite homogenous slab to the more complex four-material problem can be handled.

Enclosure 1 defines some of the more prominent terms used in Enclosure 2, a listing of the FORTRAN program. A sample of the output format is given in Enclosure 3.







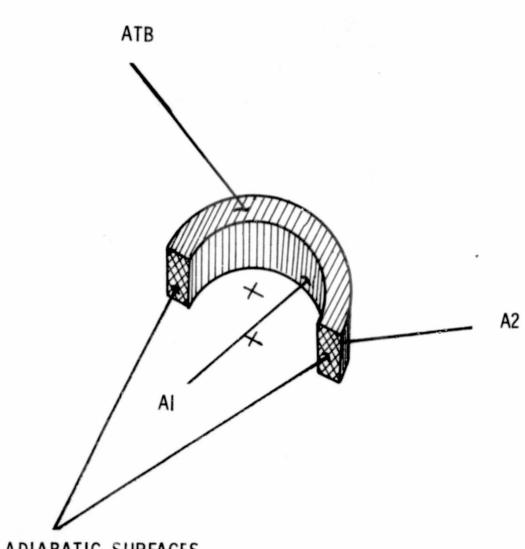
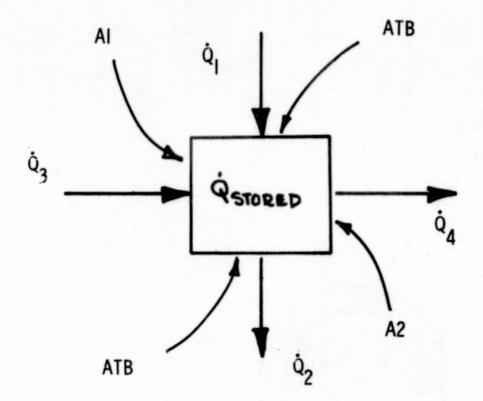


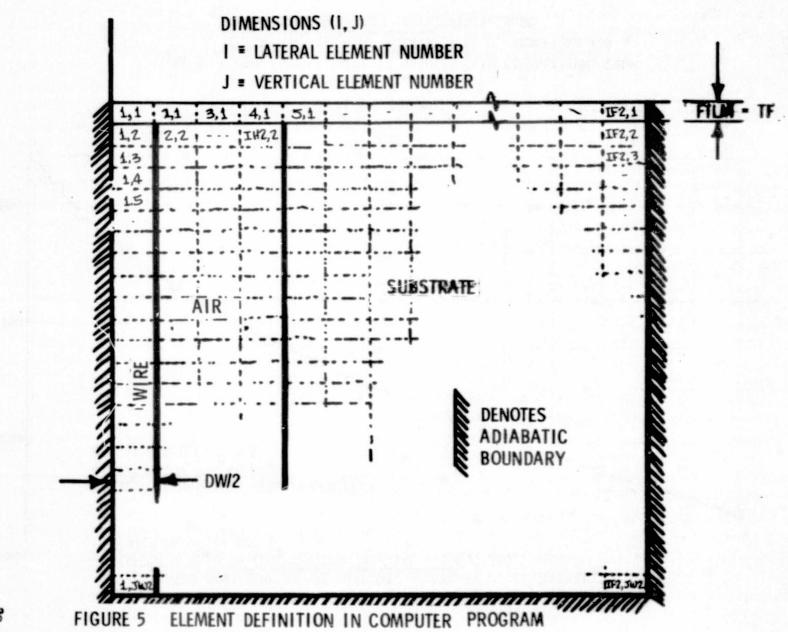


FIGURE 3 DEFINITION OF AREAS ON TYPICAL ELEMENT



$$\dot{q}_{\text{STORED}} = \dot{q}_1 - \dot{q}_2 + \dot{q}_3 - \dot{q}_4$$

FIGURE 4 TWO-DIMENSIONAL VERSION OF TYPICAL ELEMENT AND HEAT FLUX SIGN CONVENTION



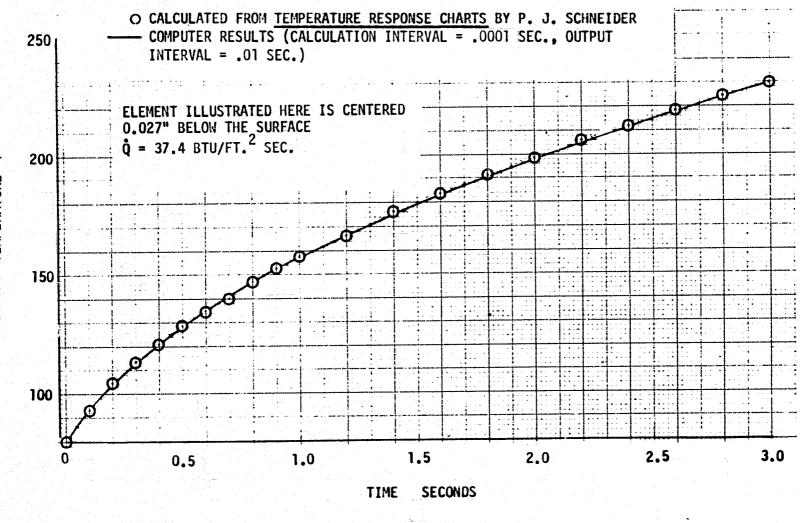


FIGURE 6 COMPARISON OF COMPUTER RESULTS WITH CALCULATIONS FROM <u>TEMPERATURE RESPONSE CHARTS</u> BY P. J. SCHNEIDER FOR A HOMOGENOUS, CONSTANTAN SEMI-INFINITE SLAB

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ELEMENT TEMPERATURE "F

CPA, CPF, CPS and CPW	specific heat of air, film, substrate and wire, respectively, BTU/lb. F
DENA, DENF, DENS and DENW	density of air, film, substrate and wire, respectively, 1b./ft.3
DIR	wire diameter, in.
DX	DW/2, the width of an element, in.
DYF	the height of elements in the first two layers, in.
DYW	the height of elements in layers below the first two layers, in.
H	heat transfer coefficient, BTU/ft. ² sec. ^O F
I	lateral element number (see Figure 5)
IF2	the number of elements in the horizontal plane (see Figure 5)
J	vertical element number (see Figure 5)
JW2	the number of elements in the vertical plane (see Figure 5)
KA, KF, KS and KW	thermal conductivity of air, film, substrate and wire, respectively, BTU/ft. F sec.
TAW	adiabatic wall temperature, ^o F
TF	film thickness, in.
T(I,J)	temperature of element(I,J) ^o F.

Enclosure 1 - Definition of Some Terms Used in Program

	Enclosure 2
· REAL KF, KA, KH, KS, K(11,44)	Page 1 of 3
DIFENSION $T(11, 44), TeVG(11), DEN(11, 44), ($	CP(11,44), pTE(11),
101(11,44), C2(11,44), C3(11,44), C4(11,44),	
$2 \qquad A1(11,44), A2(11,44), ANET(11,44)$	44)
11 = .039 1 = .040.	
$T_1 = .001$	
1) L = 0 L	
$\frac{1}{10} = \frac{1}{10} \frac{1}{2}$	
DYF=TF	
$\overline{1}$ I $i_1 \in = ()$	
$I \subset I = 0$	
(1)(1)(1)(1)(1)=1,44	
1)11 100 I=1, 11	
1(0) T(1, J) = 80.	
$\frac{CP}{A=.24}$	
$\frac{0.164}{0.000} = 0.000038$	
KA = .0000038 $KF = .0009$	
DENF=515.	
CPF=.13	
0Em9=556.6	
CPH = . ()94	
Ku= . 00337	
UPS=.2	
$015 \times S = 1.31.$	
KS=.0002132	
IFZ=7 JFZ=1.	
J = 2 = 3	
$\frac{1}{1}$	
1S = 112 + 1	
1 / = Z	
(1) = .0001	
(1, 11) J=1, J+2	
$1 \in 1 I = 1, I \in Z$	
$(1^{2}(1, j) = (1^{2})^{-1}$	
$\frac{(1+1)(1+1)(1+1)}{(1+1)(1+1)}$	
$\frac{110 \text{ K}(I,J)=\text{KF}}{100 \text{ I}11 \text{ J}=2,20}$	
$\frac{1}{111} \frac{1}{1} $	
(P(1+J)=CP)	
$\frac{O(I+J)}{O(I+J)} = O(E^{N}A)$	
111 K(1, J) = KA	
Du 112 J=2.20	
DU 112 I=1,1	
$CP(I_{j}J) = CPI_{j}$	
$\frac{11-16}{1}\left(1,J\right)=11E^{11/4}$	
$\frac{112}{112} \times (I, J) = KH$	
$\frac{1113 J=2, 20}{1011 113 I=IS, IF2}$	an a
111 JUD 1 - J 07 J - C	
/* 35 / T 11 m /* 12 C	
CP(I+J)=CPS $DEM(I+J)=DEMS$	
$\frac{1}{113} K(I,J) = 0 E^{NS}$	
$\frac{1}{13} \times (I, J) = 0 E^{MS}$ $\frac{1}{13} \times (I, J) = KS$ $\frac{1}{15} = 1 \cdot 1 + 2$	ACR B
)EN(I,J)=DENS 113 K(I,J)=KS	PAGE IB

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$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		
$ \frac{1}{122} \times 10[1] = 3.14 [k = 0.2 \text{ MeV} (2.8 + [-1])/2.7 (142,$		Enclosure 2 (Con't.)
$\begin{array}{llllllllllllllllllllllllllllllllllll$		
$\begin{array}{c} (11, 1) = 1, 1 \leq $		Mage 2 01.3
$\begin{array}{c} r_{2}(1, j) \geq s_{1}(1, j) \in \mathbb{N}^{2}(1, j) \in \mathbb{N}^$		
$ \begin{array}{c} 0.1(1, i) = 1/2, \cdots, (1, i) . (11, i) / i/VV \\ 0.2(1, i) = 1/2, \cdots, (1, i) . (11, i) / i/VV \\ 0.2(1, i) = 1/2, \cdots, (1, i) . (11, i) / i/VV / 1/2. \\ 0.0 10 1 = 1/7, i/7 \\ 1.0 1 = 1/7 \\ 1.0 1 = 1/7 \\ 1.0 1 = 1/7 \\ 1.0 1$		
$ \begin{array}{c} c_{2}(1, j) = 12, \cdots, (1, i) - 1(1, i) / 0x \\ c_{3}(1, j) = 12, \cdots, (1, i) + 2(1, j) / 0x \\ let (1, j) = 12, \cdots, (1, i) + 2(1, j) / 0x \\ let (1, j) = 12, l + 12, l + 12 \\ let (1, j) = 12, l + 12, l + 12 \\ let (1, j) = 12, l + 12, l + 12 \\ let (1, j) = 1, l + 12, l + 12 \\ let (1, j) = 1, l + 12, l$		
$ \begin{array}{l} C_{3}(1, d) = 12 \cdot r_{1}(1, d) + r_{2}(1, d) PX \\ (F) & U(1, d) = 1 + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} + r_{2} + r_{1}(1, d) + r_{2} \\ (U(1, d) = 1 + r_{2} + r_{1}(1, d) + r_{2} + r_{2} + r_{2} + r_{2} + r_{2} + r_{2} \\ (U(1, d) = 1 + r_{2} \\ (U(1, d) = 1 + r_{2} \\ (U(1, d) = 1 + r_{2} + $		
$ \begin{array}{llllllllllllllllllllllllllllllllllll$		
$ \begin{array}{c} 0.0 \ 151 \ 1=7,7^{\circ} \\ 0.0 \ 151 \ 1=7,172 \\ 1F(3-2)157,155,156 \\ 155 \ 0.0 \ 157 \ 0.0$		
D) 151 1=1,172 1F(3-2)157,155,156 155 DYM=.05 GU 10 157 OPROR QUALTY 157 A1(1,J)=3.141630X80/PW(1-1)/144. A2(1,J)=3.141630X80/PW(1-1)/144. C1(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1/J)WM C2(1,J)=12.*K(1,J)*ATE(1,J)*ATE(1)AM C2(1,J)=12.*K(1,J)*ATE(1,J)*ATE(1)AM C2(1,J)=12.*K(1,J)*ATE(1,J)*ATE(1,J)*ATE(1,J)*ATE(2,J) C335 FURMAT(5=20.6) 00 932 J=1.20 932 WHTE(6,9331K(1,J), DEN(2,J),DEN(3,J),DFM(4,J),DFM(4,J),DFM(4,J), ATE(6,9331K(1,J),T(2,J),AT(3,J),AT(4,J),AT(5,J),AT(4,J), ATE(6,9331A(1,J),AT(2,J),AT(3,J),AT(4,J),AT(5,J),AT(4,J), ATE(6,9331A(1,J),AT(2,J),AT(3,J),AT(4,J),AT(5,J),AT(4,J), ATE(6,9331A(1,J),AT(2,J),AT(3,J),AT(4,J),AT(5,J),AT(4,J), ATE(6,9331A(1,J),AT(2,J),AT(3,J),AT(4,J),AT(5,J),AT(4,J), ATE(6,9331C(1,J),AT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C2(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C2(1,J),CT(2,J),CT(3,J),CT(4,J),CT(5,J),CT(4,J), ATE(6,9331C2(1,J),CT(2,J),CT(3,J),CT(4,J),CT(4,J), ATE(6,9331C2(1,J),CT(2,J),CT(3,J),CT(4,J),CT(4,J), ATE(6,9331C2(1,J),CT(2,J),CT(3,J),CT(4,J),CT(4,J),CT(4,J), ATE(6,9331C2(1,J),CT(2,J),CT(3,J),CT(4,J),CT(4,J), ATE(6,9331C2(1,J),CT(2,J),CT(3,J),CT(4,J),CT(4,J), ATE(6,9331C2(1,J),CT(2,J),CT(3,J),CT(4,J),CT(4,J), ATE(6,9331C2(1,J),CT(1,J),CT(2,J),CT(1,J),CT(1,J),CT(1,		12.
$ \frac{1F(J-2)157, 155, 196}{156} \\ \frac{156}{60} \frac{10}{10} \frac{157}{156} \frac{10}{157} \frac{10}{157}$		
$ \begin{array}{c} 157 \ \text{DYWe, 05} & \text{ORIGINAL PAGE IS} \\ \text{GU 10 157} & \text{ORIGINAL PAGE IS} & \text{OF POOR QUALIX} \\ 157 \ \text{Al } (I, J) = 3.141 \text{Gen} \text{Sen} (1 + 3)/144. & \text{OF POOR QUALIX} \\ \text{A} (2I, J) = 12.4 \text{K} (I, J) \approx 1/1/44. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4/1/144. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4/1/144. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4/1/144. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4/1/144. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4/1/144. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4/1/144. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4/1/144. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4/4. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 12.4 \text{K} (I, J) \approx 1/1/4. & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 1/2.0 & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 1/2.0 & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 1/2.0 & \text{OF POOR QUALIX} \\ \text{C} (I, J) = 1/2.0 & \text{OF POOR QUALIX} \\ \text{C} (I) = 0.4 \text{C} (I, J) & \text{OF POOR QUALIX} \\ \text{C} (I) = 0.4 \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I) = 0.4 \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I) = 0.4 \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I) = 0.4 \text{C} (I, J) & \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OPOR QUALIX} \\ \text{C} (I, J) & \text{OF OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OPOR QUALIX} \\ \text{C} (I, J) & \text{OF OF ORIGH (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I) & \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I, J) & \text{OF OR QUALIX} \\ \text{C} (I) & \text{OF OR QUALIX} \\ \text{C} (I) & OF OF OR $		
$ \begin{array}{llllllllllllllllllllllllllllllllllll$		
156 DYM=.05 157 Al(1, J)=3.1416*NIX#0(P*X(1-1)/144. Al(1, J)=2.*K(1, J)*A(1, J)/DY C3(1, J)=12.*K(1, J)*A(1, J), CP(2, J), CP(3, J), CP(4, J), CP(5, J) D0 932 J=1, 20 934 MRITE(6,933)A(1, J), DEN(2, J), DEN(3, J), DEN(4, J), DEN(5, J), ME*(4, J). D1 PSN(7, J) D1 935 J=1, 20 935 WRITE(6,933)A(1, J) +A(2, J), A1(3, J), A1(4, J), A1(5, J), A1(4, J), D1 936 J=1, 20 937 WRITE(6,933)A(1, J) +A1(2, J), A1(3, J), A1(4, J), A1(5, J), A1(4, J), D1 936 J=1, 20 937 WRITE(6,933)A(1, J) +A1(2, J), A1(3, J), A2(4, J), A2(5, J), A2(4, J), D1 937 J=1, 20 937 WRITE(6,933)C2(1, J) +C2(2, J), C2(3, J), C2(4, J), C2(5, J), C2(6, A), D1 937 J=1, 20 937 WRITE(6,933)C2(1, J) +C2(2, J), C2(3, J), C2(4, J), C2(5, J), C2(6, A), D1 941 J=1, 20 A(1 94 0		ORIGINAT PAGE IS
157 A1(1, J)= 3. 1416×11×11/1×11/144. A2(1, J)=3. 1416×11×11/1×11/144. C1(1, J)=12. *K(1, J)*Y1(1, J)/DY C2(1, J)=12. *K(1, J)*Y1(1, J)/DY C3(1, J)=12. *K(1, J)*Y1(1, J)/DY 151 C4(1, J)=CP(1, J)*DF*(1, J)/DY 151 C4(1, J)=CP(1, J)*DF*(1, J)/DY 934 FURMAT($5E20.6$) 932 WHITE(6,933)DEV(1, J). CP(2, J). CP(3, J), CP(4, J), CP(5, J) 101 934 J=1.20 934 WHITE(6,933)DEV(1, J). DEV(2, J). DEV(3, J), DEV(4, J), DEV(5, J), DEV(6, J). 102 935 J=1, 20 935 WHITE(6,933)DEV(1, J). DEV(2, J). DEV(3, J), K(5, J). K(6, J)., V(7, J) 103 935 J=1, 20 935 WHITE(6,933)A1(1, J). T(2, J). K(3, J), K(4, J). K(5, J). K(6, J)., V(7, J) 101 934 J=1, 20 937 WHITE(6,933)A1(1, J). A1(2, J). A1(3, J), A1(4, J). A1(5, J). A1(4, J). 1A2(7, J) 1D1 937 J=1, 20 937 WHITE(6,933)A2(1, J). 2(2, J). A2(3, J). A2(4, J). A2(5, J). F2(6, H). 1A2(7, J) 1D1 937 J=1, 20 937 WHITE(6,933)C1(1, J). C1(2, J). C1(3, J). C1(4, J). C1(5, J). C1(6, H). 1A2(7, J) 1D1 939 J=1, 20 937 WHITE(6,933)C2(1, J). C2(2, J). C2(4, J). C2(5, J). C2(6, H). 1C(7, J) 1D1 939 J=1, 20 937 WHITE(6,933)C2(1, J). C3(2, J). C3(3, J). C3(4, J). C3(5, J). C3(6, h). 1C2(7, J) 1D1 941 J=1, 20 20 0HITE(6,933)C3(1, J). C3(2, J). C3(3, J). C3(4, J). C3(5, J). C3(6, h). 1C2(7, J) 1D1 941 J=1, 20 20 0HITE(6,933)C3(1, J). C3(2, J). C3(3, J). C3(4, J). C3(5, J). C3(6, h). 1C3(7, J) 1C3(7, J) 20 0HITE(6,933)C3(1, J). C4(2, J). C3(3, J). C3(4, J). C3(5, J). C3(6, h). 1C3(7, J) 20 0HITE(6,933)C3(1, J). C4(2, J). C3(3, J). C3(4, J). C3(5, J). C3(6, h). 1C3(7, J) 20 0HITE(6,933)C3(1, J). C3(2, J). C3(3, J). C4(4, J). C4(5, J). C4(6, h). 1C3(7, J) 20 0HITE(6,933)C3(1, J). C3(2, J). C3(3, J). C3(4, J). C3(5, J). C3(6, h). 1C3(7, J) 20 0HITE(7, J) 20 0HITE(7, J)=DT*(HAATF(1)*(TAN-T(1, 1))- 20 (1, 2)*(T(1, 1)-T(1, 2)). 20 0HITE(7, J)=DT*(HAATF(1))*(TAN-T(1, 1))+ 20 (1, 2)*(T(1, 1)-T(1, 2)). 20 0HITE(7, J)=DT*(HAATF(1))*(TAN-T(1, 1))+ 20 0HITE(7, J)=DT*(HAATF(1))*(TAN-T(1, 1))+ 20 0HITE(7, J)=DT*(HAATF(1))*(TAN-T(1, 1))+ 20 0HITE(7, J)=DT*(HAATF(1))*(TAN-		
$ \begin{array}{l} & A2(1, J) = 3.141 \ A \approx 19 \ \% (I + 0 + 17 \ I + 4 +$		UF FOUR QUALLER,
$ \begin{array}{l} Cl(1, J) = 12, *K(1, J) * F((1)/DYW \\ C2(1, J) = 12, *K(1, J) * A(1, J) / DY \\ C3(1, J) = 12, *K(1, J) * A(1, J) / DY \\ 151 C4(1, J) = CP(1, J) * DF (1, J) * AF_D(1) * DYW/12. \\ 933 FORMAT(5E20.6) \\ 00 932 J = 1, 20 \\ 932 WRITE(6, 933) CP(1, J) + CP(2, J) + CP(3, J) + CP(4, J) + CP(5, J) \\ 00 934 J = 1, 20 \\ 934 WRITE(6, 933) DEN(1, J) + DEN(2, J) + DEN(3, J) + DEN(4, J) + DEW(5, J) + DEW(6, J) \\ 101 935 J = 1, 20 \\ 935 WRITE(6, 933) DEN(1, J) + U(2, J) + DEN(3, J) + DEN(4, J) + DEW(5, J) + DEW(6, J) \\ 101 935 J = 1, 20 \\ 936 WRITE(6, 933) A1(1, J) + U(2, J) + A(3, J) + A(4, J) + A(5, J) + A(6, J) + (7, J) \\ 101 937 J = 1, 20 \\ 936 WRITE(6, 933) A2(1, D) + A(2, J) + A(3, J) + A(4, J) + A(5, J) + A(6, J) + (7, J) \\ 101 937 J = 1, 20 \\ 937 Vs(TTE(6, 933) A2(1, D) + A(2, J) + A(3, J) + A(4, J) + A(5, J) + A(6, J) + (7, J) \\ 101 937 J = 1, 20 \\ 937 Vs(TTE(6, 933) C2(1, J) + C2(2, J) + C2(4, J) + C2(5, J) + C2(6, a) + (107, J) \\ 101 938 J = 1, 20 \\ 939 VRITE(6, 933) C2(1, J) + C1(2, J) + C1(3, J) + C1(4, J) + C1(5, J) + D(6, A) + (102(7, J) + D(6, G)) + C2(7, J) \\ 101 940 J = 1, 20 \\ 001 040 J = 1, 20 \\ 0$		
$\begin{array}{l} C2(1, J) = 12, *K(1, J) \times 1(1, J)/DY \\ C3(I, J) = 12, *K(1, J) \times 2(1, J)/DX \\ 151 C4(1, J) = CP(1, J) \times DFN(1, J) \times AFD(1) \times DYN/12. \\ 933 FORMAT(5E20.6) \\ 00 932 J = 1, 20 \\ 932 WR 1TE(6, 933) CP(1, J) + CP(2, J) + CP(3, J) + CP(4, J) + CP(5, J) \\ 01 934 J = 1, 20 \\ 934 WR 1TE(6, 933) DEN(1, J) + DEN(2, J) + DEN(3, J) + DEN(4, J) + DFN(5, J) + DEN(6, J) + DEN(7, J) \\ 01 935 J = 1, 20 \\ 936 WR 1TE(6, 933) A(1, J) + V(2, J) + RV(3, J) + K(5, J) + K(6, J) + K(6, J) + (7, J) \\ 01 935 J = 1, 20 \\ 936 WR 1TE(6, 933) A(1, J) + V(2, J) + RV(3, J) + K(4, J) + K(5, J) + K(6, J) + (7, J) \\ 01 937 J = 1, 20 \\ 937 WR 1TE(6, 933) A(1, J) + A1(2, J) + A1(3, J) + A1(4, J) + A1(5, J) + A1(6, J) + (14, 17, J) \\ 01 937 J = 1, 20 \\ 937 WR 1TE(6, 933) C1(1, J) + C1(2, J) + C1(3, J) + C1(4, J) + C2(5, J) + C2(6, a) + (12(7, J) + C1(7, J) + C1(7, J) \\ 01 939 J = 1, 20 \\ 938 WR 1TE(6, 933) C1(1, J) + C1(2, J) + C1(3, J) + C2(4, J) + C2(5, J) + C2(6, a) + (12(7, J) + C1(7, J) + C1(7, J) \\ 01 939 J = 1, 20 \\ 030 WR 1TE(6, 933) C2(1, J) + C2(2, J) + C2(4, J) + C2(5, J) + C2(6, a) + (12(7, J) + C1(7, J) + C1(7, J) + C1(7, J) + C1(7, J) \\ 01 949 J = 1, 20 \\ 01 940 J = 2, JF2 \\ 01 940 J = 2$		
$\begin{array}{c} C_{3}(1, J) = 12 \cdot & \times (1, J) \times 2(1, J) / DX \\ 151 C_{4}(1, J) = CP(1, J) \times DF^{1}(1, J) \times Af_{D}(1) \times DY^{1}/2 \cdot \\ 935 FORMAT(5E20.6) \\ \hline D0 932 J = 1, 20 \\ 932 MRITE(6, 933) CP(1, J) \cdot CP(2, J) \cdot CP(3, J) \cdot CP(4, J) \cdot CP(5, J) \\ \hline D0 934 J = 1, 20 \\ 934 MRITE(6, 933) DEN(1, J) \cdot DEN(2, J) \cdot DEN(3, J) \cdot DFN(4, J) \cdot DFN(5, J) \cdot DFN(6, J) \cdot \\ \hline 1DEN(7, J) \\ \hline D1 935 J = 1, 20 \\ 935 9RITE(6, 933) A(1, J) \cdot D(2, J) \cdot K/3, J) \cdot K(4, J) \cdot K(5, J) \cdot K(6, J) \cdot (7, J) \\ \hline D1 935 J = 1, 20 \\ 936 \times RITE(6, 933) A(1, J) \cdot D(2, J) \cdot A(3, J) \cdot A(4, J) \cdot A(5, J) \cdot A(6, J) \cdot (7, J) \\ \hline D1 937 J = 1, 20 \\ 937 \times RITE(6, 933) A(2(1, J) \cdot D(2, J) \cdot A(3, J) \cdot A(4, J) \cdot A(5, J) \cdot A(6, J) \cdot (7, J) \\ \hline D11 937 J = 1, 20 \\ 937 \times RITE(6, 933) A(2(1, J) \cdot D(2, J) \cdot A(3, J) \cdot A(4, J) \cdot A(2(5, J) \cdot PZ(6, J) \cdot (7, J) \\ \hline D11 937 J = 1, 20 \\ 937 \times RITE(6, 933) C2(1, J) \cdot D(2, J) \cdot C1(3, J) \cdot C1(4, J) \cdot C1(5, J) \cdot PZ(6, J) \cdot (7, J) \\ \hline D11 938 J = 1, 20 \\ 938 V \times RITE(6, 933) C2(1, J) \cdot C2(2, J) \cdot C2(3, J) \cdot C2(4, J) \cdot C2(5, J) \cdot C2(6, e) \cdot \\ 1C2(7, J) \\ \hline D11 941 J = 1, 20 \\ O(0 0 0 0 0 H RITE(6, 933) C2(1, J) \cdot C3(2, J) \cdot C3(3, J) \cdot C3(4, J) \cdot C3(5, J) \cdot C3(6, e) \cdot \\ 1C2(7, J) \\ \hline D12 942 J = 1, 20 \\ O(0 0 0 H RI TE(6, 933) C3(1, J) \cdot C3(2, J) \cdot C3(3, J) \cdot C3(4, J) \cdot C3(5, J) \cdot C3(6, e) \cdot \\ 1C2(7, J) \\ \hline D14 94 J = 1, 20 \\ O(0 0 H RI TE(6, 933) C3(1, J) \cdot C3(2, J) \cdot C3(3, J) \cdot C3(4, J) \cdot C3(5, J) \cdot C3(6, e) \cdot \\ 1C2(7, J) \\ \hline D14 94 J = 1, 20 \\ O(0 H RI TE(6, 933) C3(1, J) \cdot C3(2, J) \cdot C3(3, J) \cdot C3(4, J) \cdot C3(5, J) \cdot C3(6, e) \cdot \\ \hline D15 94 \times H RI TE(6, 933) C4(1, J) \cdot C4(2, J) \cdot C3(3, J) \cdot C3(4, J) \cdot C3(5, J) \cdot C3(6, e) \cdot \\ \hline 1C = (7, J) \\ \hline D14 94 0 = 1, 20 \\ O(0 H RI TE(6, 933) C3(1, J) \cdot C3(2, J) \cdot C3(3, J) \cdot C3(4, J) \cdot C3(5, J) \cdot C3(6, e) \cdot \\ \hline D16 96 0 D = 2, F2 \\ \hline D16 90 0 O M C [(1, 1) = DT \times (H \times AT (1) (H \times T (H - T(1, 1)) - C1(1, 2) \times (T(1, -1) - ((-1, 1))) \\ \hline H = C1(1, 2) \times (T(1, 1) - T(1, 2)) - C3(1+1, 1) \times (T(1, -1) - T(1+1, 1)) \\ \hline H M 22 = M 2 - 1 \\ \hline D10 800 2 = 2, J M 2 \\ \hline D2 \\ \hline D2 0 R D (I = 2, I F 2 \\ \hline D2 \\ \hline$		
151 C4(1, J)=CP(1, J) × DFF ([, J) × AFb(1) × AYU/12. 935 FORMAT(5F20.6) D 092 J=1,20 932 WRITE(6,933) CP(1, J), CP(2, J), CP(3, J), CP(4, J), CP(5, J) D 034 J=1,20 934 MRITE(6,933) DFN(1, J), DEN(2, J), DEN(3, J), UPFN(4, J),		
933 FORMAT(5E20.6) D0 932 J=1,20 934 WRITE(6,933)CP(1,J).CP(2,J).CP(3,J).CP(4,J).CP(5,J) 00 934 J=1,20 934 WRITE(6,933)DEN(1,J).DEN(2,J).DEN(3,J).DEN(4,J).UF*(5,J).UF*(6,J). 10E*(7,J) 109 935 J=1,20 935 WRITE(6,933)A1(1,J).V(2,J).K(3,J).K(4,J).K(5,J).K(6,J).X(7,J) 101 937 J=1,20 937 WRITE(6,933)A2(1,J). 2(2,J).A1(3,J).A1(4,J).A1(5,J).A1(6,J). 101 937 J=1,20 937 WRITE(6,933)A2(1,J). 2(2,J).A2(3,J).A2(4,J).A2(5,J).72(6,). 102(7,J) 101 938 J=1,20 939 WRITE(6,933)C2(1,J).C2(2,J).C2(4,J).C1(5,J).C1(6,). 102(7,J) 101 939 J=1,20 939 WRITE(6,933)C2(1,J).C2(2,J).C2(4,J).C2(5,J).C2(6,). 102(7,J) 101 941 J=1,20 940 URITE(6,933)C2(1,J).C3(2,J).C3(3,J).C3(4,J).C3(5,J).C3(6,A). 102(7,J) 101 941 J=1,20 940 WRITE(6,933)C4(1,J).C4(2,J).C3(3,J).C3(4,J).C3(5,J).C3(6,A). 102(7,J) 103 941 J=1,20 940 URITE(6,933)C4(1,J).C4(2,J).C3(3,J).C3(4,J).C4(5,J).C4(6,A). 103(7,J) 941 WRITE(6,933)C4(1,J).C4(2,J).C3(3,J).C3(4,J).C4(5,J).C4(6,A). 104 WRITE(6,933)C4(1,J).C4(2,J).C3(3,J).C3(4,J).C4(5,J).C4(6,A). 105(7,J) 104 00ET(1,1)=DT*(H*ATF(1)*(TAN=T(1,1))- 11(1,2).*(T(1,1)=T(1,1))- 11(1,2).*(T(1,1)=T(1,2))-C3(1+1,1)*(T(1,1)=T(1+1,1))- 11(1,2).*(T(1,1)=T(1,2))-C3(1+1,1)*(T(1,1)=T(1+1,1))- 11(1,2).*(T(1,1)=T(1,2))-C3(1+1,1)*(T(1,1))- 11(1,2).*(T(1,1)=T(1,2))-C3(1+1,1))+(1(1,1)=T(1+1,1))) 100 802 J=2,JWZ2 00 802 J=2,J		and an and an
DD 932 J=1,20 932 MRITE(6,933)CP(1,J).CP(2,J).CP(3,J).CP(4,J).CP(5,J) DO 934 J=1,20 934 WRITE(6,933)DEN(1,J).DEN(2,J).DEN(3,J).DEN(4,J).DEN(4,J).DEN(6,J). 1DEN(7,J) 1DEN(7,J) 10) 935 J=1,20 935 WRITE(6,933)A(1,J).V(2,J).K(3,J).K(4,J).K(5,J).K(6,J).N(7,J) 10) 936 J=1,20 937 WRITE(6,933)A(1,J).V(2,J).A1(3,J).A1(4,J).A1(5,J).A1(4,J). 1A1(7,J) 1A1(7,J) 1A1(7,J) 1A2(7,J) 937 WRITE(6,933)A2(1,J).Z(2,J).A2(4,J).A2(4,J).A2(5,J).V(4,J). 1A2(7,J) 0) 938 J=1,20 939 WRITE(6,933)C1(1,J).V1(2,J).C1(3,J).C1(4,J).C1(5,J).V1(4,J). 1C1(7,J) 10) 939 J=1,20 939 WRITE(6,933)C2(1,J).C2(2,J).C2(3,J).C2(4,J).C2(5,J).V2(6,A). 1C2(7,J) 0) 941 J=1,20 940 WRITE(6,933)C3(1,J).C3(2,J).C3(3,J).C3(4,J).C3(5,J).V3(6,A). 1C3(7,J) 041 WRITE(6,933)C3(1,J).C3(2,J).C3(3,J).C3(4,J).C3(5,J).V3(6,A). 1C3(7,J) 041 WRITE(6,933)C3(1,J).C3(2,J).C3(3,J).C3(4,J).C3(5,J).V3(6,A). 1C3(7,J) 041 WRITE(6,933)C3(1,J).C3(2,J).C3(3,J).C4(4,J).C4(5,J).V3(6,A). 1C3(7,J) 041 WRITE(6,933)C3(1,J).C3(2,J).C3(3,J).C3(4,J).C4(5,J).V3(6,A). 1C4(7,J) 1C4(7,J) 1C4(7,J) 1C4(7,J) 052 J=2,Z P00 GANGT(1,1)=DT*(H%ATF(1)*(TAN=T(1,1))= C1(1,2) *(T(1-1,1)-T(1+1,1)) JM22=JM22 D0 B02 J=2,JM22 D0 B02 J=2,JM22 D0 B02 J=2,JF2 P00 GANGT(J,J)=C1(T,J) *(T(T,J))		12•
932 MRITE(6,933) CP(1, J) · CP(2, J) · CP(3, J) · CP(4, J) · CP(5, J) 100 934 J=1, 20 934 WRITE(6,933) DEM(1, J) · DEM(2, J) · DEM(3, J) · DEM(4, J) · DEM(5, J) · DEM(6, J) · 102 935 J=1, 20 935 WRITE(6,933) K(1, J) · '('2, J) · K('3, J) · K('4, J) · K('5, J) · K('6, J) · N(', J) 101 936 J=1, 20 936 "RITE(6,933) A1(1, J) · A1(2, J) · A1(3, J) · A1(4, J) · A1(5, J) · A1(6, J) · 101 937 J=1, 20 937 931 J=1, 20 937 931 J=1, 20 937 931 J=1, 20 938 J=1, 20 938 J=1, 20 939 931 J=1, 20 930 941 J=1, 20 940 941 J=1, 20 941 941 941 941 941 941 941 941 941 941		
$\begin{array}{c} & 0 & 0 & 934 & j=1,20 \\ & 934 & \text{MRITF(6,933)DEN(1,J),DEN(2,J),DEN(3,J),DEN(4,J),DEN(5,J),dEN(6,J), \\ & 1 & 1 & 0 & 0 & j=1,20 \\ & 935 & \text{JEL20} \\ & 935 & \text{JEL20} \\ & 936 & \text{JEL20} \\ & 937 & MRITE(6,933)A1(1,J),A1(2,J),A1(3,J),A1(4,J),A1(5,J),A1(6,J), \\ & 1 & 1 & 1 & 0 & 0 & 0 \\ \hline & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 3 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 1 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ \hline & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 &$		
<pre>934 WRITE(6,933)DEN(1,J),DEN(2,J),DEN(3,J),DEN(4,J),DEN(5,J),DEN(7,J) 1DEN(7,J) (b) 935 J=1,20 935 WRITE(6,933)A(1,J),P((2,J),K(3,J),K(4,J),K(5,J),K(6,J),∧(7,J) 1DF 936 J=1,20 936 WRITE(6,933)A1(1,J),A1(2,J),A1(3,J),A1(4,J),A1(5,J),A1(6,J), 1A1(7,J) DEN(937 J=1,20 937 WRITE(6,933)A2(1,J),Z(2,J),A2(3,J),A2(4,J),A2(5,J),P(2(6,J), 1A2(7,J) DEN(938 J=1,20 938 WRITE(6,933)C1(1,J),P(1(2,J),C1(4,J),C1(5,J),C1(6,J), 1C1(7,J) DEN(938 J=1,20 939 WRITE(6,933)C2(1,J),C2(2,J),C2(3,J),C2(4,J),C2(5,J),C1(6,J), 1C2(7,J) DEN(941 J=1,20 940 WRITE(6,933)C3(1,J),C3(2,J),C3(3,J),C3(4,J),C3(5,J),C3(6,A), 1C2(7,J) 940 WRITE(6,933)C3(1,J),C3(2,J),C3(3,J),C3(4,J),C3(5,J),C3(6,A), 1C3(7,J) 941 WRITE(6,933)C4(1,J),C4(2,J),C3(3,J),C4(4,J),C4(5,J),C3(6,A), 1C4(7,J) 169 U×ET(1,1)=DT*(H*ATP(1)*(TAW-T(1,1)) - C1(1,2) *((((((((((((((((((((((((((((((((((((</pre>		(P(4,J), (P(5,J))
$\frac{10\text{E}N(7, \text{J})}{(\text{h}) 935 \text{ J=1}, 20}$ (h) 935 J=1, 20 936 WRITE (6,933) K(1, 4) + V(2, \text{J}), K(3, \text{J}), K(4, \text{J}), K(5, \text{J}), K(6, \text{J}), N(7, \text{J})}{(\text{h}) 936 \text{ J=1}, 20} 936 WRITE (6,933) A1 (1, J) + A1 (2, J) + A1 (3, J), A1 (4, J), A1 (5, J) + A1 (6, J), 101 937 J=1, 20 937 WRITE (6,933) A2 (1, J) + 22 (2, J), A2 (3, J), A2 (4, J), A2 (5, J), A2 (6, J), 101 938 J=1, 20 938 WRITE (6,933) C1 (1, J) + 12 (2, J), C1 (3, J), C1 (4, J), C1 (5, J), (11 (6, 1, 1))) 101 938 J=1, 20 939 WRITE (6,933) C2 (1, J) + C2 (2, J), C2 (4, J), C2 (5, J), (16, 1, 1)) 101 940 J=1, 20 940 WRITE (6,933) C2 (1, J) + C2 (2, J), C2 (4, J), C2 (5, J), C2 (6, A), 1C 2 (7, J) 101 941 J=1, 20 940 WRITE (6,933) C3 (1, J) + C3 (2, J), C3 (3, J), C3 (4, J), C3 (5, J), C3 (6, A), 1C 3 (7, J) 941 J=1, 20 940 WRITE (6,933) C3 (1, J) + C4 (2, J), C3 (3, J), C3 (4, J), C3 (5, J), C3 (6, A), 1C 3 (7, J) 1A9 UBET (1, 1)=DT*(H*ATF(1)*(TAW-T(1, 1)) - C1 (1, 2) *(1(1, +))) 1A9 UBET (1, 1)=DT*(H*ATF(1)*(TAW-T(1, 1)) + C2 (1, -1)*(T(1, -1, 1)) + ((+, +))) 1A0 1=2, 1F2 P00 UBET (1, 1)=DT*(H*ATF(1)*(TAW-T(1, 1)) + C2 (1, -1)*(T(1, -1, 1)) + ((+, +))) 1-C1 (1, 2)*(T(1, 1)-T(1, 2)) - C3 (1+1, 1)*(T(1, -1)) + ((+, +)))) JW 202 JW2-1 D0 802 J=2, JW22 D0 802 J=2, JW22	$\frac{111934 J=1, 20}{024 JETTER 022 ADENUAL ADDENUAL ADDENUAL$	1. INCALL IN AND IN ACTURED AND
(h) 935 J=1,20 (c) MRITE (6,933)K(1,1), F(2,J), K(3,J), K(4,J), K(5,J), K(6,J), $(7,J)$ (f) 936 J=1,20 (g) MRITE (6,933)A1(1,J), A1(2,J), A1(3,J), A1(4,J), A1(5,J), A1(5,J), A1(5,J), A1(5,J), A1(5,J), A1(5,J), A1(7,J) (g) MRITE (6,933)A2(1,J), A2(2,J), A2(3,J), A2(4,J), A2(5,J), F2(6,J), A2(7,J) (g) MRITE (6,933)A2(1,J), A2(2,J), A2(3,J), A2(4,J), A2(5,J), F2(6,J), A2(5,J), A2(7,J) (g) MRITE (6,933)C1(1,J), A1(2,J), A1(4,J), C1(4,J), C1(5,J), A1(5,J), A1(5,J), A2(5,J),		J/ (UFM(4, J) ((IFM(D, J) (UFM(D, J))
$\begin{array}{c} 935 \ \mbox{WRITE}(6,933)\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$		a the second
$\begin{array}{c} \text{(h)} 936 \ J=1,20 \\ 936 \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	$\frac{110 \ 757 \ J=1; 20}{C25 \ MUTTEL2 \ O22 \ VI1 \ (V \ V22 \ V12 \ V1$	$1 \times K = 1 \times K + 1 \times $
$\begin{array}{c} 936 \mbox{ wr} ITE(6,933)A1(1,J) & \mbox{ algorithm} (2,J) & \mbox{ algorithm} (4,J) & $		9019N129J19N109019N11901
$\begin{array}{c} 1A1(7,J) \\ \hline 010 937 J=1,20 \\ 937 \sqrt{3}TE(6,933)A2(1,J) + 2(2,J),A2(3,J),A2(4,J),A2(5,J),A2(6,J), \\ 1A2(7,J) \\ \hline 010 938 J=1,20 \\ 938 \sqrt{8}KTE(6,933)C1(1,J) + 1(2,J),C1(3,J),C1(4,J),C1(5,J),C1(6,J), \\ 1C1(7,J) \\ \hline 010 939 J=1,20 \\ 939 \sqrt{8}KTE(6,933)C2(1,J) + C2(2,J),C2(3,J),C2(4,J),C2(5,J),C2(6,A), \\ 1C2(7,J) \\ \hline 010 940 J=1,20 \\ \hline 010 01 L(1,1) + 1(1,1) + 1(1,1)) \\ \hline 010 10 12,1F2 \\ \hline 010 00 2 I=2,1F2 \\ \hline 010 802 I=2,1F$		A116.11.0115.11.0116.11
$\begin{array}{c} \text{hit} 937 \ \text{J=1,20} \\ 937 \ \forall \text{RITE}(6,933) \text{A2}(1,1), \forall \text{A2}(2,1), \text{A2}(3,1), \text{A2}(4,1), \text{A2}(5,1), \forall \text{A2}(6,n), \\ 1 \text{A2}(7,1) \\ \text{Dit} 938 \ \text{J=1,20} \\ 938 \ \forall \text{RITE}(6,933) \text{C1}(1,1), \forall \text{L1}(2,1), \text{C1}(3,1), \text{C1}(4,1), \text{C1}(5,1), \forall \text{L1}(6, n), \\ 1 \text{C1}(7,1) \\ \text{Dit} 939 \ \text{J=1,20} \\ 939 \ \forall \text{RITE}(6,933) \text{C2}(1,1), \text{C2}(2,1), \text{C2}(3,1), \text{C2}(4,1), \text{C2}(5,1), \text{U2}(6,n), \\ 1 \text{C2}(7,1) \\ \text{Dit} 940 \ \text{J=1,20} \\ 010 \ 941 \ \text{J=1,20} \\ 010 \ 940 \ \text{J=1,20} \\ 940 \ \forall \text{RITE}(6,933) \text{C3}(1,1), \text{C3}(2,1), \text{C3}(3,1), \text{C3}(4,1), \text{C3}(5,1), \text{C3}(6,n), \\ 1 \text{C3}(7,1) \\ 941 \ \forall \text{RITE}(6,933) \text{C3}(1,1), \text{C4}(2,1), \text{C3}(3,1), \text{C3}(4,1), \text{C3}(5,1), \text{C3}(6,n), \\ 1 \text{C3}(7,1) \\ 941 \ \forall \text{RITE}(6,933) \text{C4}(1,1), \text{C4}(2,1), \text{C3}(3,1), \text{C4}(4,1), \text{C4}(5,1), \text{C4}(6,n), \\ 1 \text{C3}(7,1) \\ 941 \ \forall \text{RITE}(6,933) \text{C4}(1,1), \text{C4}(2,1), \text{C3}(3,1), \text{C4}(4,1), \text{C4}(5,1), \text{C4}(6,n), \\ 1 \text{C3}(7,1) \\ 941 \ \forall \text{RITE}(6,933) \text{C4}(1,1), \text{C4}(2,1), \text{C3}(3,1), \text{C4}(4,1), \text{C4}(5,1), \text{C4}(6,n), \\ 1 \text{C3}(7,1) \\ 941 \ \forall \text{RITE}(6,933) \text{C4}(1,1), \text{C4}(2,1), \text{C3}(3,1), \text{C4}(4,1), \text{C4}(5,1), \text{C4}(6,n), \\ 1 \text{C3}(7,1) \\ 941 \ \forall \text{RITE}(6,933) \text{C4}(1,1), \text{C4}(2,1), \text{C3}(3,1), \text{C4}(4,1), \text{C4}(5,1), \text{C4}(6,n), \\ 1 \text{C3}(7,1) \\ 941 \ \forall \text{RITE}(6,933) \text{C4}(1,1), \text{C4}(2,1), \text{C3}(3,1), \text{C4}(4,1), \text{C4}(5,1), \text{C4}(6,n), \\ 1 \text{C3}(7,1) \\ 1 \text{B0} \text{B0} \text{C1}=2, \text{IF2} \\ \text{PO} \ \text{DM} \text{BO} \text{C1}=2, \text{IF2} \\ \text{PO} \ \text{DM} \text{BO} \text{C1}=2, \text{IF2} \\ \text{DO} \ \text{BO} \text{C1}=2, \text{IF2} \\ \text{DO} \ \text{BO} \text{C1}=2, \text{IF2} \\ \text{PO} \ \text{DM} \text{ET}(1,1)=\text{D7}(1,1) \\ \text{C1}(1,1)=\text{D7}(1,1), \text{C1}(1,1), \text{C1}(1,1), \text{C1}(1,1), \text{C1}(1,1)) \\ \text{C1}(1,1,1)=\text{D7}(1,1) \\ \text{BO} \ \text{BO} \text{C1}=2, \text{IF2} \\ \text{PO} \ \text{DM} \text{C1}(1,1)=\text{D7}(1,1) \\ \text{C1}(1,1)=\text{D7}(1,1) \\ \text{C1}(1,1)=\text{D1}(1,1) \\ \text{C1}(1,1)=\text{D1}(1,1) \\ \text{C1}(1,1)=\text{D1}(1,1) \\ \text{C1}(1,1)=\text{D1}(1,1) \\$		AL (T+0/9AL()90/9AL(090/9
$\begin{array}{c} 937 \ \forall \forall \exists TE(6,933)A2(1,d) & \forall (2(2,J),A2(3,J),A2(4,J),A2(5,J),C2(4,d), \\ 1A2(7,J) \\ 011 \ 938 \ J=1,20 \\ 938 \ \forall \forall \exists TE(6,933)C1(1,J),C1(2,J),C1(3,J),C1(4,J),C1(5,J),C1(6,), \\ 1C1(7,J) \\ 0.1 \ 939 \ \exists J=1,20 \\ 939 \ \forall \forall \exists TE(6,933)C2(1,J),C2(2,J),C2(3,J),C2(4,J),C2(5,J),C2(6,e), \\ 1C2(7,J) \\ 001 \ 941 \ J=1,20 \\ 0(1 \ 940 \ J=1,20 \\ 0(1 \ 1,1) = DT*(H*ATP(1)*(TAW-T(1,1)) - C1(1,2) \ *(1(1,1) \\ 1-(1,2) \ *(1(1,1) - T(2,1))) \\ 0(1 \ 940 \ J=1,20 \\ 0(1 \ J=2,1E2 \\ 0(1 \ 0(1 \ J=1,2) \ J=1,20 \\ 0(1 \ J=2,1E2 \\ 0(2 \ 0(1 \ J=2,1E2 \\ 0(2 \ 0(1 \ J=1,2) \ J=0T*(1,1) \ J=1,20 \\ 0(1 \ J=1,2) \ J=0T*(1,1) \ J=0T*(1,1$		
$\begin{array}{c} 1 \land 2(7, J) \\ (h) 1 938 J=1, 20 \\ (g) 4 \forall RTTE(6, 933)C1(1, J) (f)(2, J), C1(3, J), C1(4, J), C1(5, J), (f)(4, J), C1(5, J), (f)(4, J), C1(7, J)) \\ (h) 1 939 J=1, 20 \\ (g) 4 \forall RTTE(6, 933)C2(1, J) C2(2, J), C2(3, J), C2(4, J), C2(5, J), C2(6, e), c) \\ (f) 1 f(2(7, J)) \\ (f) 1 g) 1 $		A2 (4.1) . A2 (5.1) . r2(6.1) .
$\begin{array}{c} \text{i)} (1 \ 93\text{R} \ J=1,20 \\ \hline 93\text{F} \ \neg \text{KITE}(6,933)(C1(1,J),(1(2,J),C1(3,J),C1(4,J),C1(5,J),(1(6, N, N, N, N))) \\ 1 \ 1 \ \text{CI}(7,J) \\ \hline 0,1 \ 939 \ \text{J}=1,20 \\ \hline 939 \ \neg \text{KITE}(6,933)(C2(1,J),C2(2,J),C2(3,J),C2(4,J),C2(5,J),C2(6,n), \\ 1 \ 1 \ 1 \ 1 \ 1 \ 1 \ 2 \ 1 \ 2 \ 1 \ 2 \ 1 \ 2 \ 1 \ 2 \ 2$		ME 1- FU F FACI 270 / J. Clift 4: F
$\begin{array}{c} 93F \rightarrow RITE(6,933)C1(1,J) \cdot C1(2,J), C1(3,J), C1(4,J), C1(5,J), C1(6,J), \\ 1C1(7,J) \\ 0,0 939 J=1,20 \\ 939 \rightarrow RITE(6,933)C2(1,J) \cdot C2(2,J), C2(3,J), C2(4,J), C2(5,J), C2(6,a), \\ 1C2(7,J) \\ 0,0 940 J=1,20 \\ 0,0 940 J=1,20 \\ 940 \rightarrow RITE(6,933)C3(1,J) \cdot C3(2,J), C3(3,J), C3(4,J), C3(5,J), C3(6,a), \\ 1C3(7,J) \\ 941 \rightarrow RITE(6,933)C4(1,J), C4(2,J), C3(3,J), C4(4,J), C4(5,J), C3(6,a), \\ 1C3(7,J) \\ 941 \rightarrow RITE(6,933)C4(1,J), C4(2,J), C3(3,J), C4(4,J), C4(5,J), C4(a,a), \\ 1C4(7,J) \\ 169 \rightarrow RITE(1,1) = DT*(H*ATF(1)*(TAW-T(1,1)) - C1(1,2) = (1(1,1)) \\ 1-C1(1,2) - C3(2,1)*(1(1,1) - T(2,1))) \\ 101 B00 I=2, IF2 \\ PD0 \ CaveT(I,1) = DT*(H*ATF(I)*(TAW-T(I,1)) + C2(I, 1)*(T(I-1,1) - 1((1,1))) \\ 1-C1(I,2)*(T(I,1) - T(I,2)) - C3(I+1,1)*(T(I,1) - T(I+1,1))) \\ JW22 = JW2 - 1 \\ DD B02 J=2, JW22 \\ DD B02 I=2, IF2 \\ PO2 \ QMET(I,J) = DT*((C1(1,J) + C1(1,J) + C1(I,J)) \\ POB = POT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = PT = PT = (C1(1,J) + C1(I,J) + C1(I,J)) \\ POB = PT = P$		
$ \begin{array}{c} 1C1(7, J) \\ 1), 1 & 939 \ J=1, 20 \\ 939 \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$		$(1 (4.1) \cdot (1 (5.1) \cdot (1 (5.1)))$
$\begin{array}{c} \text{(b)} \ 939 \ \text{J=1,20} \\ \hline 939 \ \text{IRTE(6,933)C2(1,J),C2(2,J),C2(3,J),C2(4,J),C2(5,J),C2(6,*),} \\ \hline 1C2(7,J) \\ \hline \text{(b)} \ 941 \ \text{J=1,20} \\ \hline \text{(c)} \ 940 \ \text{J=1,20} \\ \hline \text{(c)} \ 1C3(7,J) \\ \hline \text{(c)} \ 1C3(2,1) \times (1,J) \ C4(2,J), C3(3,J), C4(4,J), C4(5,J), C4(6,*) \\ \hline \text{(c)} \ 1C3(7,J) \\ \hline \text{(c)} \ 1C3(2,1) \times (1,J) \ C4(2,J), C3(3,J), C4(4,J), C4(5,J), C4(6,*) \\ \hline \text{(c)} \ 1C3(7,J) \\ \hline \text{(c)} \ 1C3(2,1) \times (1,1) \ C4(2,J), C3(3,J), C4(4,J), C4(5,J), C4(6,*) \\ \hline \text{(c)} \ 1C3(7,J) \\ \hline \text{(c)} \ 1C3(2,1) \times (1,1) \ C4(2,J), C3(3,J), C4(4,J), C4(5,J), C4(6,*) \\ \hline \text{(c)} \ 1C3(2,1) \times (1,1) \ C4(2,J), C3(2,1) \times (1,1) \ C4(2,J) \\ \hline \text{(c)} \ 1C3(2,1) \times (1,1) \ C4(2,J), C3(2,1) \times (1,1) \ C1(1,2) \ C1(1,2) \ C1(1,2) \ C1(1,2) \ C1(1,2) \ C1(1,1) $		~~ · · · · · · · · · · · · · · · · · ·
$\begin{array}{c} 939 \forall R ITE(6, 933) C2(1, J) , C2(2, J) , C2(4, J) , C2(5, J) , C2(6, n) , \\ 1 C2(7, J) \\ 0 IIC 941 J = 1 , 20 \\ 0 IIC 940 J = 1 , 20 \\ 940 IR ITE(6, 933) C3(1, J) , C3(2, J) , C3(3, J) , C3(4, J) , C3(5, J) , C3(6, \wedge) , \\ 1 C G(7, J) \\ 941 \forall R ITE(6, 933) C4(1, J) , C4(2, J) , C3(3, J) , C4(4, J) , C4(5, J) , C4(6, \wedge) , \\ 1 C G(7, J) \\ 941 \forall R ITE(6, 933) C4(1, J) , C4(2, J) , C3(3, J) , C4(4, J) , C4(5, J) , C4(6, \wedge) , \\ 1 C4(7, J) \\ 1 C4(7, J) \\ 1 C4(7, J) \\ 1 C9 GN C1(I, I) = DT K (H^{\times} \wedge TP(1) K (IAW - T(I, I)) - \\ 1 C1(I, 2) C3(2, 1) K (T(I, I) - T(I, 2)) \\ 1 C1(I, 2) C3(2, 1) K (T(I, I) - C1(I, 2)) \\ C1(I, 2) C3(I, I) I C1(I, I) C1(I, I) C1(I, I) \\ I C1(I, I) C3(I, I) C3(I, I) C3(I, I) C4(I, I) \\ I C1(I, I) C1(I, I) C1(I, I) C1(I, I) C2(I, I) C4(I, I, I) C4(I, I, I) C3(I, I) C4(I, I) C4(I, I, I) C4(I, I) C4(I$		
$ \frac{1(2(7, J))}{0(1.941 J=1, 20)} \\ \frac{1}{0(1.940 J=1, 20)} \\ \frac{1}{0(1.940 J=1, 20)} \\ \frac{1}{0(2.000 WR1TE(6, 933)C3(1, J) \cdot C3(2, J), C3(3, J), C3(4, J), C3(5, J), C3(6, h), f(2, G), f(3, J))}{1(2.000 WR1TE(6, 933)C4(1, J), C4(2, J), C3(3, J), C4(4, J), C4(5, J), C4(h, h), f(2, H),$		(2(4, J), (2(5, J), (2(6, n)),
$\begin{array}{c} \text{(b)} 941 \ \text{J}=1,20 \\ \text{(c)} 940 \ \text{J}=1,20 \\ 940 \ \text{(HR1TE(6,933)C3(1,J)+C3(2,J),C3(3,J),C3(4,J),C3(5,J),C3(5,A),} \\ 1C3(7,J) \\ \hline 041 \ \text{(HR1TE(6,933)C4(1,J),C4(2,J),C3(3,J),C4(4,J),C4(5,J),C4(6,A),} \\ 1C4(7,J) \\ \hline 169 \ \text{U}+\text{ET}(1,1)=\text{DT}+(\text{H}+\text{A}+\text{T}+(1)+(TAW-T(1,1))-(C1(1,2)) \\ \hline 1-T(1,2))-C3(2,1)+(T(1,1)-T(2,1)) \\ \hline 101 \ \text{B}00 \ \text{I}=2,\text{IF2} \\ \hline \text{POD} \ \text{G}\times\text{ET}(1,1)=\text{DT}+(\text{H}+\text{A}+\text{T}+(1)+(TAW-T(1,1))+C2(1,1)+(T(1-1,1)-1)((,1)) \\ \hline 1+C1(1,2)+(T(1,1)-T(1,2))-C3(1+1,1)+(T(1,1)-T(1+1,1))) \\ \hline \text{J}H22=\text{J}H2-1 \\ \hline \text{DO} \ \text{B}02 \ \text{J}=2,\text{J}H22 \\ \hline \text{DO} \ \text{B}02 \ \text{J}=2,\text{J}H22 \\ \hline \text{DO} \ \text{B}02 \ \text{J}=2,\text{J}H2 \\ \hline \text{CO2} \ \text{O}\text{H}\text{ET}(1,\text{J})=\text{DT}+(())+(-())) \\ \hline \text{H}(1,1,1)=\text{DT}+(())+(-())) \\ \hline \text{H}(1,1,1)=\text{DT}+(())+(-())+(-())) \\ \hline \text{H}(1,1,1)=\text{DT}+(())+(-())+(-())) \\ \hline \text{H}(1,1,1)=\text{DT}+(())+(-())+(-())) \\ \hline \text{H}(1,1,1)=\text{DT}+(())+(-())+(-())+(-())) \\ \hline \text{H}(1,1,1)=\text{DT}+(())+(-())+(-())+(-())) \\ \hline \text{H}(1,1,1)=\text{DT}+(())+(-())+(-())+(-())+(-())) \\ \hline \text{H}(1,1,1)=\text{DT}+(())+(-())+(-())+(-())+(-())+(-())+(-())+(-())) \\ \hline \text{H}(1,1,1)=())+(-())+($		
$ \frac{1}{10000000000000000000000000000000000$		<u></u>
940 $\forall R TE(6,933) C3(1,J) \cdot C3(2,J), C3(3,J), C3(4,J), C3(5,J), C3(6,A),$ 1C3(7,J) 941 $\forall R TE(6,933) C4(1,J), C4(2,J), C3(3,J), C4(4,J), C4(5,J), C4(A,A),$ 1C4(7,J) 169 $\Box AET(1,1) = DT*(H*ATP(1)*(TAW-T(1,1)) - C1(1,2) *(T(1-1,1)))$ 169 $\Box AET(1,1) = DT*(H*ATP(1)*(TAW-T(1,1)) + C2(1,1))$ 101 $BOO I=2, IF2$ 800 $\Box AET(1,1) = DT*(H*ATP(1)*(TAW-T(I,1)) + C2(1,1)) *(T(1-1,1)-T(1,1)))$ 1-C1(1,2)*(T(1,1)-T(1,2)) - C3(I+1,1)*(T(1,1)-T(1+1,1))) 1-C1(1,2)*(T(1,1)-T(1,2)) - C3(I+1,1)*(T(1,1)-T(1+1,1))) JW22=JW2-1 DO $BO2 I=2, IF2$ BOD $BO2 I=2, IF2$ C1(T,J) $*(T(T,J)-T(1,J))$		
$ \begin{array}{c} 1C 3(7, J) \\ \hline 041 & \exists \exists \exists E(6, 933) C4(1, J), C4(2, J), C3(3, J), C4(4, J), C4(5, J), C4(J, J), C4(J, J), C4(J, J), C4(J, J), C4(J, J), C4(J, J), C$		(3(4.J),(3(5.J),(3(6.4)))
$\begin{array}{c} 941 & \exists x TE(6,933) C4(1,J), C4(2,J), C3(3,J), C4(4,J), C4(5,J), C4(6,A), \\ 1C4(7,J) \\ 169 & GSET(1,1) = DT*(H*ATP(1)*(TAW-T(1,1)) - C1(1,2) & \approx (+(+,+)) \\ 1-T(1,2)) - C3(2,1)*(+(+,1)) - T(2,1)) \\ D1 & B00 & I = 2, IF2 \\ \hline 800 & GSET(I,1) = DT*(H*ATP(I)*(TAW-T(I,1)) + C2(I,1)*(T(1-1,1)-+((+,1))) \\ 1-C1(I,2)*(T(I,1)-T(1,2)) - C3(I+1,1)*(T(I,1)-T(I+1,1))) \\ JW22 = JW2 - 1 \\ DD & B02 & J = 2, JW22 \\ DU & B02 & I = 2, IF2 \\ \hline 802 & GNET(I,J) = DT*((-C1(T,J)) & \approx (T(T,J) - T(I,J)) \\ \hline \end{array}$		
$\frac{1(4(7, J))}{169 \text{ GAET}(1, 1) = \text{DT}*(\text{H}*(\text{TP}(1)*(\text{TAW}-\text{T}(1, 1))) - C1(1, 2) \approx (1(1, 1))}{1-\Gamma(1, 2)) - C3(2, 1)*(1(1, 1) - T(2, 1)))}$ $\frac{1-\Gamma(1, 2) - C3(2, 1)*(1(1, 1) - T(2, 1)))}{100 \text{ BOO} I = 2, IF2}$ $\frac{800 \text{ GAET}(I, 1) = \text{DT}*(\text{H}*(\text{TT}(I))*(\text{TAW}-\text{T}(I, 1)) + C2(I - 1)*(1(1-1, 1)) - 1((+, 1)))}{1-C1(I, 2)*(\text{T}(I, 1)) - T(I, 2)) - C3(I+1, 1)*(\text{T}(I, 1)) - T(I+1, 1))}$ $\frac{1+C1(I, 2)*(T(I, 1)) - T(I, 2)) - C3(I+1, 1)*(T(I, 1)) - T(I+1, 1)))}{1+C2(I - 1, 2) + C2(I - 1, 2)}$ $\frac{1+C1(I, 2)*(T(I, 1)) - T(I, 2)) - C3(I+1, 1)*(T(I, 1)) - T(I+1, 1))}{1+C2(I - 1, 2) + C2(I - 1, 2)}$ $\frac{1+C1(I, 2) + C2(I - 1, 2)}{1+C2(I - 1, 2) + C2(I - 1, 2)}$		(4(4, J), (4(5, J), (4(k, t)),
$\begin{array}{cccccccccccccccccccccccccccccccccccc$		
$\frac{1-T(1,2)-C3(2,1)*(T(1,1)-T(2,1))}{D(1,2)-C3(2,1)*(T(1,1)-T(2,1))}$ $\frac{1-T(1,2)+T(1,1)+T(1,1)+T(1,1)+C2(1,1)*(T(1-1,1)-T(1,1))}{1-C1(1,2)*(T(1,1)-T(1,2))-C3(1+1,1)*(T(1,1)-T(1+1,1)))}$ $\frac{1-C1(1,2)*(T(1,1)-T(1,2))-C3(1+1,1)*(T(1,1)-T(1+1,1)))}{JW22=JW2-1}$ $\frac{1-C1(1,2)*(T(1,1)-T(1,2))-C3(1+1,1)*(T(1,1)-T(1+1,1)))}{D(1,2)+2}$ $\frac{1-C1(1,2)*(T(1,1)-T(1,2))-C3(1+1,1)*(T(1,1)-T(1+1,1)))}{D(1,2)+2}$ $\frac{1-C1(1,2)*(T(1,1)-T(1,2))-C3(1+1,1)*(T(1,1)-T(1+1,1)))}{D(1,2)+2}$		$(1(1,2)) \approx (1(1,1))$
$\begin{array}{c} \text{III} & \text{BOO} I=2, IF2 \\ \text{POO} \Omega \sim \mathbb{E} I(I,1) = \text{UT} * (\text{H} * A \text{T} (I) * (\text{TAW} - \text{T} (I,1)) + C2 (I , 1) * (\text{T} (1 - 1, 1) - 1 ((, 1))) \\ 1 - \text{U1} (I,2) * (\text{T} (I,1) - \text{T} (I,2)) - C3 (I + 1, 1) * (\text{T} (I,1) - \text{T} (I + 1, 1))) \\ \text{JW22= JW2-1} \\ \text{DO} 802 J=2, JW22 \\ \text{DO} 802 I=2, IF2 \\ \text{OO} 802 I=2, IF2 \\ \text{OO} \text{ONET} (I,J) = \text{DT} * (C1 (T,J) * (\text{T} (I,J - 1) - \text{T} (I,J)) \\ \end{array}$		
$\begin{array}{c} 800 0.8 \leq \overline{I(1,1)} = UT * (H * AT : (I) * (TAW - T(I,1)) + C2 (I , 1) * (T(1-1,1)-i((,1))) \\ 1 - U1(I,2) * (T(I,1) - T(I,2)) - C3(I+1,1) * (T(I,1) - T(I+1,1))) \\ JW22 = JW2 - 1 \\ DD 802 J = 2, JW22 \\ DD 802 J = 2, JW22 \\ DU 802 I = 2, IF2 \\ W02 QNET(I,J) = DT * (C1(T,J) & *(T(I,J-1) - T(I,J)) \end{array}$		<u></u>
$\frac{1-(1(I,2)*(T(I,1)-T(I,2))-C3(I+1,1)*(T(I,1)-T(I+1,1)))}{JW22=JW2-1}$ DD 802 J=2,JW22 DU 802 I=2,IF2 $\frac{1-(1(I,1)-T(I,1))}{W02} = 0T*((I,J) + (T(I,J)))$		C2(1, 1)*(1(1-1, 1)-1(1, 1))
JW22=JW2-1 DD 802 J=2,JW22 DU 802 I=2,IF2 202 QNET(I,J)=DT*((1(T,J) *(T(T,J-1)-T(I,J))	$\frac{1}{1-(1+1)} = \frac{1}{1-(1+1)} = \frac{1}{1-(1+1)$	
DD 802 J=2, JW22 DD 802 I=2, IF2 202 DNET(I, J)=DT*((.1(T, J) *(T(T, J-1)-T(I, J))		I Y & T B F J X Z Y L F F T
DU 802 I=2, IF2 BOZ DNET(I, J)=DT*((1(T, J) *(T(T, J-1)-T(I, J))		
202 ONET(I, J) = DT*((1(T, J)) *(T(T, J-1) - T(I, J))		
		*(]([.]-])-]([.])
,我们们就是你们的,你们们就是你们的,我们就是你们的你们,你们就是你们的你们。""你们,你们们就是你们的你们,你们们不是你们的你们,你们们不是你们的你们,你们们不	T-OTITAO. Start 119401 HILLARD (14)	

- (1) No surface joints
- (2) Good surface detail reproduction
- (4) Accurate instrument location
- (6) Sufficient strength
- (8) Instrument placement anywhere
- (9) Effective in areas of high thermal gradients

The plated slab possesses a very hard surface that is resistant to particle damage and therefore meets in principal the model objective number (5). However, particle damage did occur in the pebble-bed heater facility used in this evaluation. Figure 19 shows post-test magnified views of the flat face of ECAN Model CC compared to the heat treated (190,000 psi) flat face of the master Model A. Both models were subjected to all eight runs in the hypersonic tunnel and both were still providing data without any loss of instrumentation. Figure 19 and Table IX indicate particle damage resistance of the ECAN models is comparable to a heat treated stainless steel model. The softer copper coating of the ATZC process had more severe particle damage as noted in Table IX.

The customization of sensor sensitivity, objective (7), was restricted to materials that provided good plate-to-substrate bond strength. The best materials for bond strength fortunately also provided good data sensitivity. Areas of low heating impose less demand on the plate bond and therefore less restriction on the choice of materials for increased sensitivity (if required).

Data accuracy (not listed as a specific objective) obviously must be adequate if the plated slab concept is to be practiced. The tunnel results of this preliminary test proved that this model method will provide accurate data. Further improvements in accuracy can be expected as material, process and data reduction improvements are made. Discovery of the Niculoy/ constantan thermocouple greatly enhances the data accuracy and overall attractiveness of this modeling approach.

<u>Problem Areas.</u> - A smooth surface finish (objective (3)) could be provided, however, for marginal operating temperatures. The principal problem area was finding an acceptable compromise between surface smoothness, plate hardness and maximum operating temperature of the model.

Figure 20 is a photograph comparing the surface smoothness of master, ATZN and ECAN models. The smoothness of ATZN models are considered adequate for applications involving natural hypersonic boundary layer transition. Figure 21 shows magnified views of the ATZN surfaces compared to the master and the aluminum transfer film. Note that polishing marks of the master are reproduced in the plated plastic models which attests to the faithful reproduction of surface detail of this process. The thicker plate of Model M shows some pores caused by hydrogen bubbles forming on the surface during plating. This problem can be reduced by better control of the nitrogen agitation in the plating solution.

Enclosure 2 (Conit.)

	EIRIUSUIT & LOOMI.
$152 \text{ ATO}(I) = 3.1416 \times 1000 \times 1000 \times 10000 \times 100000 \times 100000000$	12.1144. Page 2 of 3
$\frac{1}{1} \frac{1}{1} \frac{1}$	
$(11) \frac{1}{15} (1 = 1 + 1 + 2)$	
$h_1(I,J) = 3.1416*01/*07F*(I-1)/$	<u>1</u> 4 6 4 .
r2(1,J)=3.1416*DX*DYF*I/144.	
$C1(I,J) = 12.80 \times (I,J) \times TB(1)/DY$	
$C_{Z}(J,J) = 12(I,J) = 1(I,J)/U$	
C3(I,J)=12.*X(I,J)**X(I,J)/D	
150 C4(I,J)=CP(I,J)*C= (I,J)*ATO	(J)*5YF/12.
UU 151 J=2,20	
DU 151 I=1,JF2	
IF(J-2)157,155,156	
155 DYH=.05	
GU TU 157	ORIGINAL PAGE IS
156 DYM=.05	OF POOR QUALITY
157 A1(I,J)=3.1416*DX*D(W*(I-1)/	
A2(1, J) = 3.1416*11/*10Y*1/144.	
C1(I,J)=12.*K(I,J)*ATB(I)/DY	
$\frac{C2(I,J)=12.*K(I,J)*/1(I,J)/U}{C2(I,J)=12.*K(I,J)*/1(I,J)/U}$	
$C3(I,J) = 12 \cdot K(I,J) \times A2(I,J)/D$	
151 C4(I,J)=CP(I,J)*DFb([,J)*ATD	(1)*DY9/12•
933 FORMAT(5E20.6)	
00 932 J=1,20	
932 WRITE(6,933)CP(1,J),CP(2,J),	<u>CP(3, J), CP(4, J), CP(5, J)</u>
DD 934 J=1,20	
934 WRITE(6,933)DEN(1,J), DEN(2,J), DEN(3, J), DEN(4, J), DEN(5, J), DEN(6, J),
1DEM(7,J)	
()) 935 J=1,20	
935 NRITE (6,933) K(1, 1) + 1(2, J) + K(3, J), K(4, J), K(5, J), K(6, J), K(7, J)
DH 936 J=1,20	
936 WRITE(6,933)A1(1,J), 1(2,J),	A1(3, J), A1(4, J), A1(5, J), A1(6, J),
1A1(7,J)	
DD 937 J=1,20	
937 WRITE(6,933) A2(1,J), 2(2,J),	#2(3, J) • A2(4, J) • A2(5, J) • #2(6, J) •
1A2(7,J)	
1)11 938 J=1,20	
938 WRITE(6,933)C1(1,J)+C1(2,J),	(1(3, J), (1(4, J), (1(5, J), (1(6, J), (1(6
1C1(7,J)	······································
00 939 J=1,20	
$\frac{100 \ 439 \ 5-1,20}{939 \ 9KITE(6,933)C2(1,J),C2(2,J)}$	(212.1).(214.1).(215.1).(214.4)
	02139019021-9019021390190210911
1C2(7,J)	
()() 941 J=1,20	·
$\sqrt{10940}$ J=1,20	
	C3(3,J),C3(4,J),C3(5,J),C3(6,a),
1C 5(7, J)	
	C3(3, J), C4(4, J), C4(5, J), C4(6, 4),
104(7,J)	
169 $A = ET(1, 1) = DT * (H * ATE(1) * (TAW - 16))$	
1-T(1,2)-C3(2,1)*(1(1,1)-T(2))	,1)))
UI) 800 I=2,IF2	
800 QMET(I,1)=UT*(H*ATE(I)*(TAW-	T(1,1) + C2(1,1) * (T(1-1,1) - ((,1)))
1-C1(I,2)*(T(I,1)-T(I,2))-C3(I+1,1)*(T(I,1)-T(I+1,1)))
JW22= JW2-1	
DD 802 J=2, JW22	
DO 802 I=2, IF2	
	τ, J) *(T(T, J-1)-T(I, J))
$\frac{1-C1(1, J+1)*(1(1, J)-1(1, J+1))}{1-C1(1, J+1)*(1(1, J)-1(1, J+1))}$	
1 TO 1 (1 9 QT 1 7 7 1 1 (1 9 0 7 - 1 (1 9 0 4) 7)	
· · · · · · · · · · · · · · · · · · ·	

	·				Enclosure 2 (G
	-T(I.J))-C		T(I,J) - T(I+1,	J))) .	Dave 3 of 3
	(11) + T(1, J) = 2		C1(1,J)	*(T(1,J-1)-	10:00 Set 2
	-C1(1,J+1)			C3(2,J)	*(1(1,J)-1(2,J)))
	DU 806 I=1		1		
			,JH2)*(T(I,	JW2-1)-T(I, JW2))
· Contraction of the local division of	+	C2(1+1.J	W2) *(T(I,	JH2)-T(I+1,JH2	())
2.	-	C3(I+1,J	1W2) *(T(I,	JW2)-T(1+1, JW2)))
	111 813 J=2				
	DOFT(11,J)		+C1(11,		$-1) - i \cdot (11, 1))$
1	+C2(11,J)*	(T(10, J) - T)	(11, J)) - C1(11)	,J+1) ×(T(11,J)	
			(11)*(TAU-T(1 (11,1)*(T(10,		C1(11,2) *
	HU 803 J=1		(11,1)~(1(10)	1/-/(11,1//	
	DO 803 I=1				
			,J)/C4(1,J)	·····	
	IF(T(1, J-2				
832	J '2= J''2+1				
	CONTINE				0
	I=(J=12)	833,833,83	34		
	J-2=12				
833	CONTINUE				
	$TI \cdots F = TI \cdots F +$	01			
	ICT=ICT+L				
	ICT=0 10RITE(6,49) The F			
	FURMAT(///			al na mila na milalan da ara da mana ana ana an	
	1).) 45 J=1,				
			2, J), T(3, J),	(4,J), 1(5,J), 1	(6, J), (7, J)
	FUREAT(5X,		and the second	and the second	
	+)+) 2000 I=	1, IF2			
2000	$T \wedge M G (I) = (T)$	(I,1) + T(I,	2))/2.		
		()1)TAVG(1)	, TAVG(2), TAVO	(3), (AVG(4),);	W(4(5), 1 - W(4(5)),
	1 AMG(7)				
	FURNAT(/,5				
	$\underline{I} \mapsto \cup CH = \underline{I} \mapsto \cup C$				
	1+(1PUCH=2 1-20 CH=0	(1) 2499, 250	12,2502		
	101() TF(5,24	0.01 1.02			
and the second se	FORMAT(15)	961542			
	111 2500 J=	1. 142			
2000	HRITE (5.26	()])TIME,1((1, J), T(2, J),	(3, J), i(4, J), i	(5, J), ((, J), ((, .)
24(1)		.4)			
24.99	CHATINDE			and the second state of th	
-	second second size and the strength second	())169,169,	970		
070	STOP				and the second
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				ORIGINAL PAGE	18
	1			OF POOR QUALIT	Y
1991	5				
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OUTPUT FORMAT

ALL VALUES EXCEPT TIME ARE TEMPERATURES (⁰F) OF THE ELEMENTS

TĘ	
TF	
	0.2496625758E 01
V FILM	0.5388E 03 0.6051E 03 0.6241E 03 0.6318E 03 0.6354E 03 0.6370E 03 0.6377E 03
1 1st SUB-LAYER	0.5355E 03 0.5996E 03 0.4163E 03 0.6260E 03 0.6295E 03 0.6311E 03 0.6317E 05
	0.3378E 03 0.3369E 03 0.3367E 03 0.3367E 03 0.3367E 03 0.3367E 03 0.3368E 03 0.3368E 03
4	0.1201E 03 0.1771E 03 0.1761E 03 0.1756E 03 0.1754E 03 0.1753E 03 0.1752E 03
	0.1110E 03 0.1094E 03 0.1089E 03 0.1087E 05 0.1085E 03 0.1085E 03 0.1084E 03
	0.8791E 02 0.8734E 02 0.8715E 02 0.8706E 02 0.8701E 02 0.8699E 02 0.6698E 02
.050" (TYP. OF	0.8166E 02 0.8149E 02 0.0144E 02 0.81415 02 0.0146E 02 0.8139E 02 0.8139E 02
REMAINING	0.8025E 02 0.8015E 02
LAYERS)	0.5372E 03 0.6024E 03 0.6212E 03 0.6289E 03 0.6324E 03 0.6341E 03 0.6347E 03
LATERSI	
	WIRE \rightarrow SUBSTRATE \rightarrow DW/2 \rightarrow DW/2 \rightarrow DW/2 \rightarrow (TYP.)
95	AVERAGE TEMP. OF FILM & IST SUBLAYER